

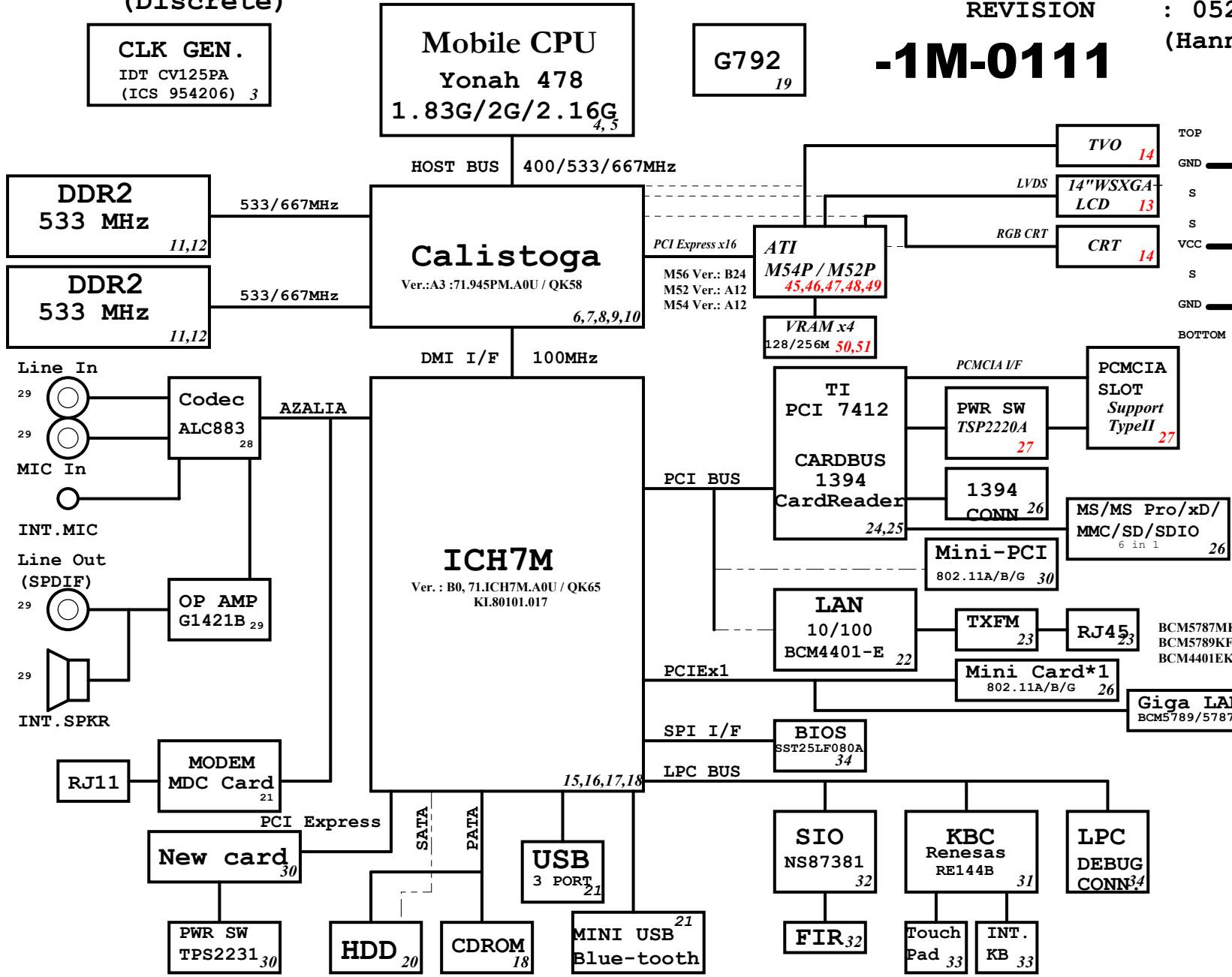
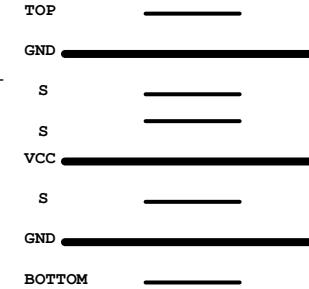
Garda-D Block Diagram

(Discrete)

Project code: 91.4A901.001
 PCB P/N : 55.4A901.XXX
 REVISION : 05217-1
 (Hannstar, ACCL)

-1M-0111

PCB STACKUP



SYSTEM DC/DC TPS51120 40	
INPUTS	OUTPUTS
DCBATOUT	5V_S5 3D3V_S5
SYSTEM DC/DC TPS51124 41	
INPUTS	OUTPUTS
DCBATOUT	1D05V_S0 1D8V_S3
TPS51100 43	
1D8V_S3	DDR_VREF_S0
APL5332KAC 43	
3D3V_S0	2D5V_S0
APL5912-U 43	
1D8V_S3	1D5V_S0

MAXIM CHARGER MAX8725 42	
INPUTS	OUTPUTS
DCBATOUT	CHG_PWR 18V 4.0A UP+5V 5V 100mA

CPU DC/DC ISL6262 38,39	
INPUTS	OUTPUTS
DCBATOUT	VCC_CORE_S0 0~1.3V 44A

ATI M54 DC/DC FAN5234 52	
INPUTS	OUTPUTS
DCBATOUT	VGA_CORE_S0
APL5331KAC 43	
1D8V_S0	1D2V_S0

<Variant Name>

緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **BLOCK DIAGRAM**

Size A3 Document Number **AG1** Rev **-1M**

Date: Wednesday, January 11, 2006 Sheet 1 of 53

ICH7M Integrated Pull-up and Pull-down Resistors

ICH7-M EDS 17837 1.5V1

EE_DIN, EE_DOUT, GNT[3:0], GPIO[25], GNT[4]#/GPIO48, GNT[5]#/GPO17, PME#, LAD[3:0]#/FWH[3:0]#, LAN_RXD[2:0]	ICH7 internal 20K pull-ups
LDRQ[0], LDRQ[1]/GPIO[41], PWRBTN#, TP[3]	
DD[7], DDREQ	ICH7 internal 11.5K pull-downs
ACZ_BIT_CLK, ACZ_RST#, ACZ_SDIN[2:0], ACZ_SDOUT, ACZ_SYNC, DPRSLPVR/GPIO16, EE_CS, SPI_ARB, SPI_CLK, SPKR,	
USB[7:0][P,N]	ICH7 internal 15K pull-downs
SATALED#	ICH7 internal 15K pull-up
LAN_CLK	ICH7 internal 100K pull-down

ICH7M IDE Integrated Series Termination Resistors

DD[15:0], DIOW#, DIOR#, DREQ, DDACK#, IORDY, DA[2:0], DCS1#, DCS3#, IDEIRQ	approximately 33 ohm
--	----------------------

ICH7M Functional Strap Definitions

page 16

Signal	Usage/When Sampled	Comment
ACZ_SDOUT	XOR Chain Entrance/PCIE Port Config bit1, Rising Edge of PWROK	Allows entrance to XOR Chain testing when TP3 pulled low. When TP3 not pulled low at rising edge of PWROK, sets bit1 of RPC.PC(Config Registers: offset 224h)
ACZ_SYNC	PCIE bit0, Rising Edge of PWROK.	Sets bit0 of RPC.PC(Config Registers:Offset 224h)
EE_CS	Reserved	This signal should not be pull high.
EE_DOUT	Reserved	This signal should not be pull low.
GNT2#	Reserved	This signal should not be pull low.
GNT3#	Top-Block Swap Override. Rising Edge of PWROK.	Sampled low:Top-Block Swap mode(inverts A16 for all cycles targeting FWH BIOS space). Note: Software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
GNT5#/GPIO17#, GNT4#/GPIO48	Boot BIOS Destination Selection. Rising Edge of PWROK.	Controllable via Boot BIOS Destination bit (Config Registers:Offset 3410h:bit 11:10). GNT5# is MSB, 01-SPI, 10-PCI, 11-LPC.
DPRSLPVR	Reserved	This signal should not be pull high.
GPIO25	Reserved. Rising Edge of RSMRST#.	This signal should not be pull low.
INTVRMEN	Integrated VccSus1_05 VRM Enable/Disable. Always sampled.	Enables integrated VccSus1_05 VRM when sampled high
LINKALERT#	Reserved	Requires an external pull-up resistor.
REQ[4:1]#	XOR Chain Selection. Rising Edge of PWROK.	TBD, Chapter 8.
SATALED#	Reserved	This signal should not be pull low.
SPKR	No Reboot. Rising Edge of PWROK.	If sampled high, the system is strapped to the "No Reboot" mode(ICH7 will disable the TCO Timer system reboot feature). The status is readable via the NO REBOOT bit.
TP3	XOR Chain Entrance. Rising Edge of PWROK.	This signal should not be pull low unless using XOR Chain testing.

954305D 27Mhz/LCDCLK Spread and Frequency Selection Table

SS3 Byte9 bit 7	SS2 bit6	SS1 bit5	SS0 bit4	Spread Amount%
0	0	0	0	-0.50 Down
0	0	0	1	-1.00 Down
0	0	1	0	-1.50 Down
0	0	1	1	-2.00 Down
0	1	0	0	-0.75 Down
0	1	0	1	-1.25 Down
0	1	1	0	-1.75 Down
0	1	1	1	-2.25 Down
1	0	0	0	+0.25 Center
1	0	0	1	+0.5 Center
1	0	1	0	+0.75 Center
1	0	1	1	+1.0 Center
1	1	0	0	+0.25 Center
1	1	0	1	+0.5 Center
1	1	1	0	+0.75 Center
1	1	1	1	+1.0 Center

page 3

PCI Routing

page 16

	IDSEL	INT -> PIRQ	REQ/GNT
7412	22	A->G, B->B', C->F, D->G'	0
MiniPCI	21	A/C B/D -> E	1
LAN	23	A -> H	2

History

Calistoga Strapping Signals and Configuration

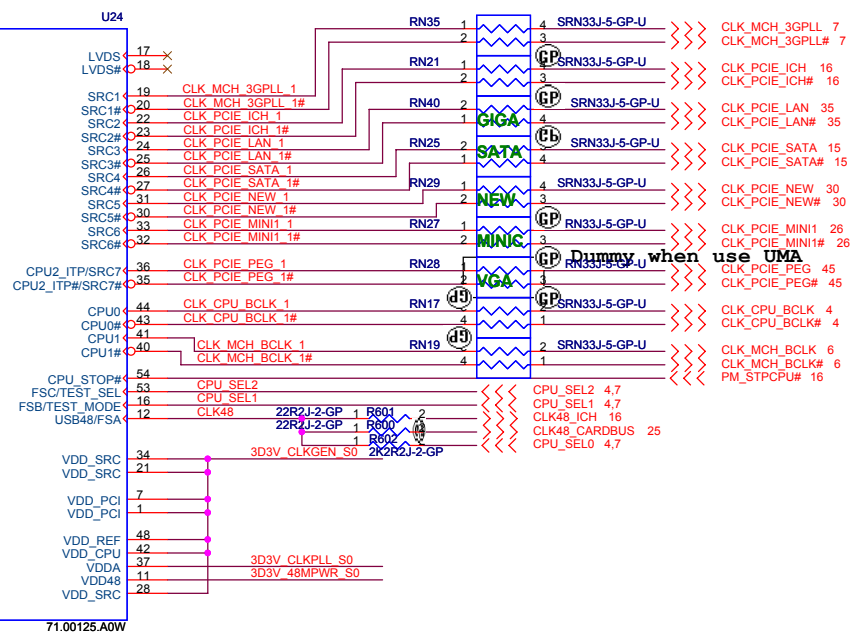
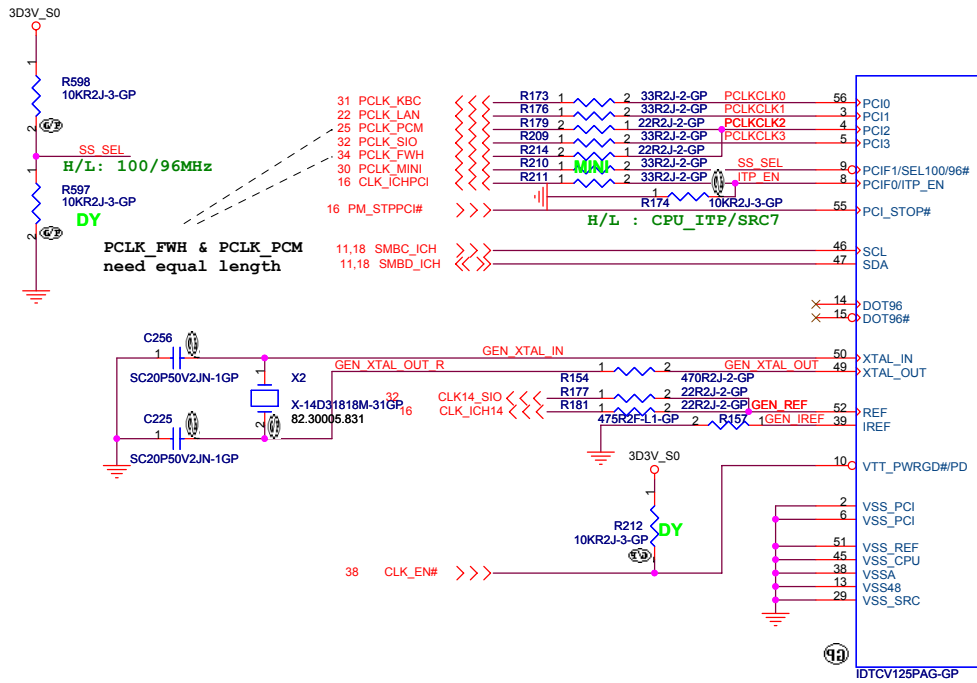
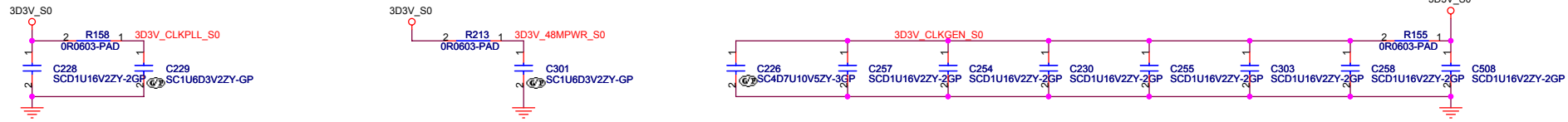
EDS 17050 0.71 page 7

Pin Name	Strap Description	Configuration
CFG[2:0]	FSB Frequency Select	001 = FSB533 011 = FSB667 others = Reserved
CFG[4:3]	Reserved	
CFG5	DMI x2 Select	0 = DMI x2 1 = DMI x4 (Default)
CFG6	Reserved	
CFG7	CPU Strap	0 = Reserved 1 = Mobile CPU(Default)
CFG8	Reserved	
CFG9	PCI Express Graphics Lane Reversal	0 = Reverse Lanes, 15->0, 14->1 ect.. 1 = Normal operation(Default): Lane Numbered in order
CFG[11:10]	Reserved	
CFG[13:12]	XOR/ALL Z test straps	00 = Reserved 01 = XOR mode enabled 10 = All Z mode enabled 11 = Normal Operation (Default)
CFG[15:14]	Reserved	Reserved
CFG16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
CFG17	Global R-comp Disable (All R-comps)	0 = All R-comp Disable 1 = Normal Operation (Default)
CFG18	VCC Select	0 = 1.05V (Default) 1 = 1.5V
CFG19	DMI Lane Reversal	0 = Normal operation (Default): lane Numbered in order 1 = Reverse Lane, 4->0, 3->1 ect...
CFG20	SDVO/PCIE Concurrent	0 = Only SDVO or PCIE x1 is operational (Default) 1 = SDVO and PCIE x1 are operating simultaneously via the PEG port
SDVOCTRL_DATA	SDVO Present	0 = No SDVO Card present (Default) 1 = SDVO Card present

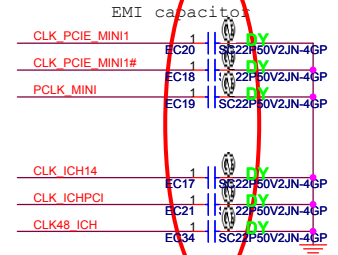
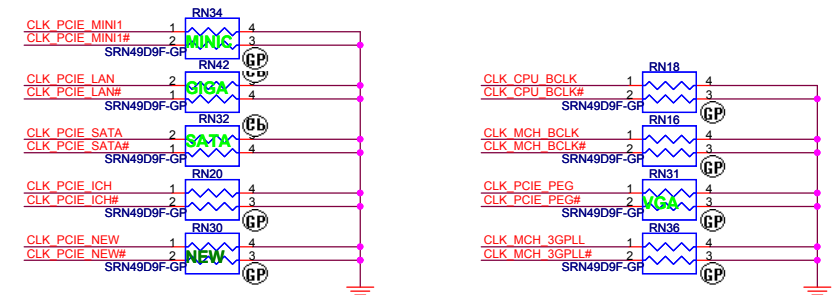
NOTE: All strap signals are sampled with respect to the leading edge of the Calistoga GMCH PWROK in signal.

<Variant Name>

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Reference			
Size A3	Document Number	Rev	SD
AG1			
Date: Tuesday, January 10, 2006		Sheet 2	of 53



SEL2	SEL1	SEL0	CPU	FSB
0	0	0	266M	X
0	0	1	133M	533M
0	1	0	200M	X
0	1	1	166M	667M
1	0	0	333M	X
1	0	1	100M	X
1	1	0	400M	X
1	1	1	Reserved	X

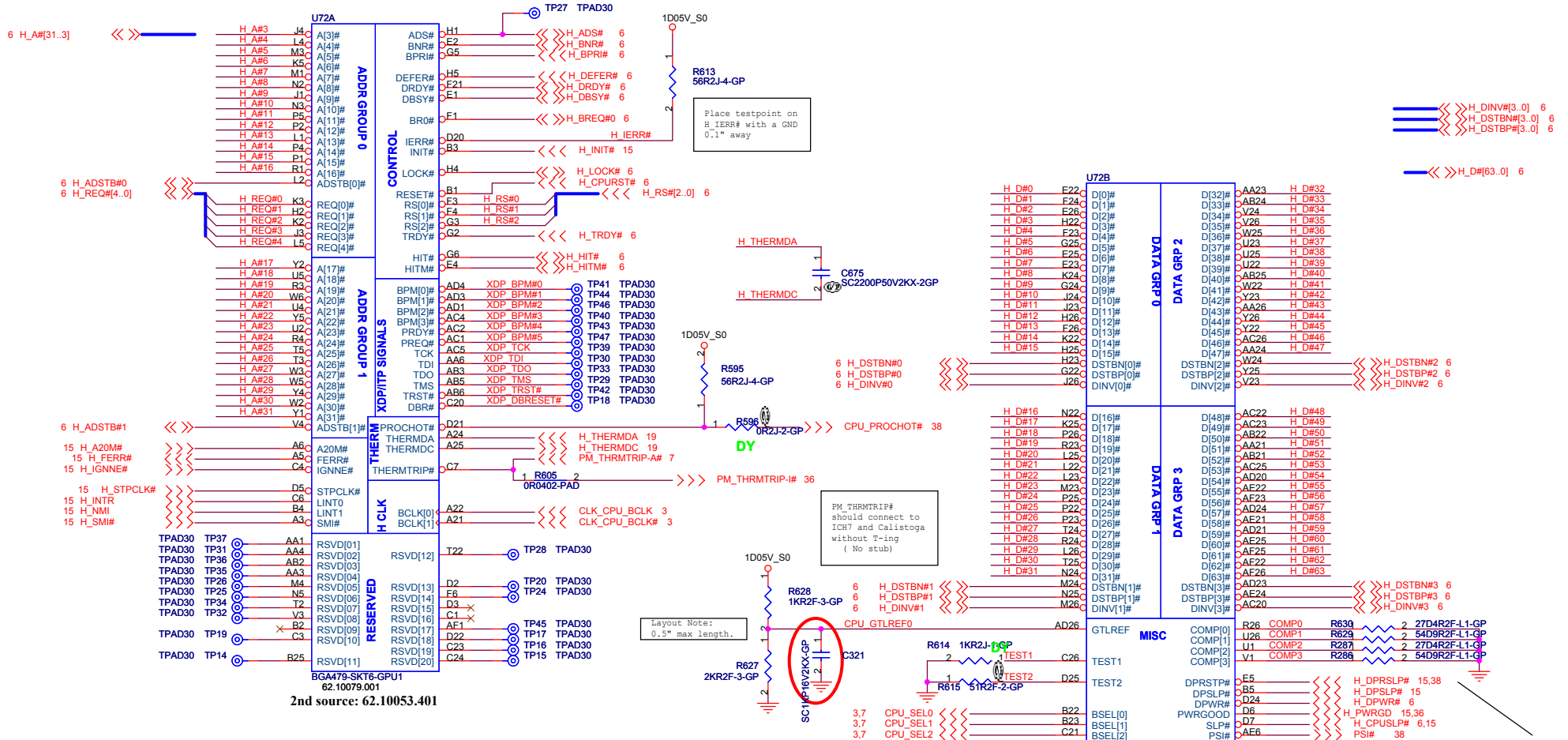


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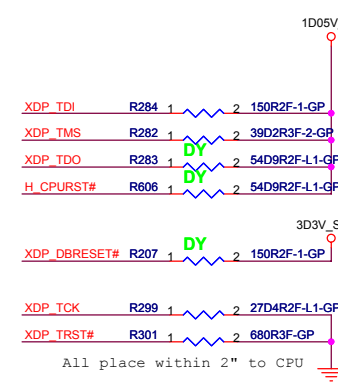
緯創資通 Wistron Corporation
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Clock Generator IDT CVT125PAG

Title	Document Number	Rev
A3	AG1	-1
Date: Tuesday, January 10, 2006	Sheet 3 of 53	



2nd source: 62.10053.001



Layout Note:
Comp0, 2 connect with Zo=27.4 ohm, make trace length shorter than 0.5\"/>

<Variant Name>

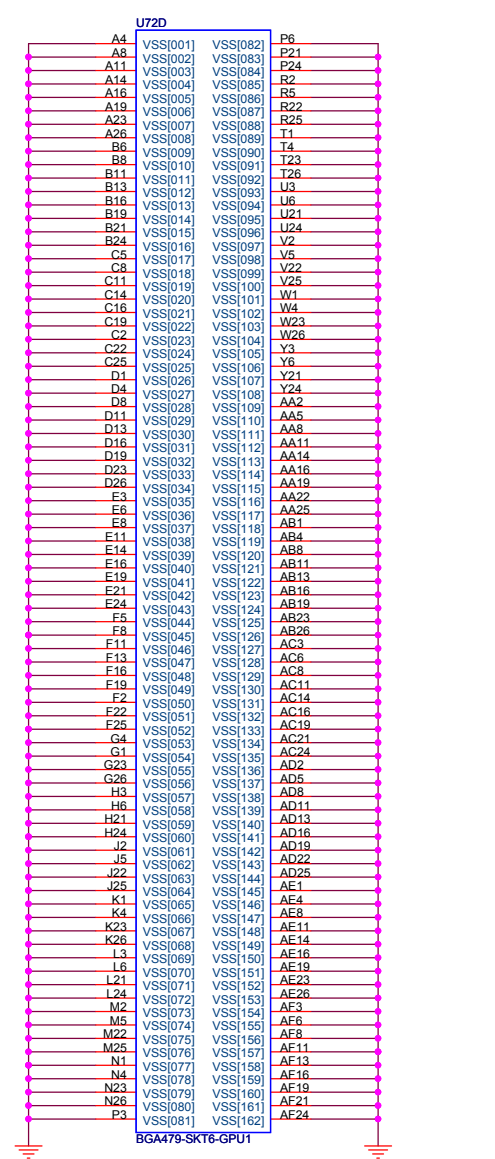
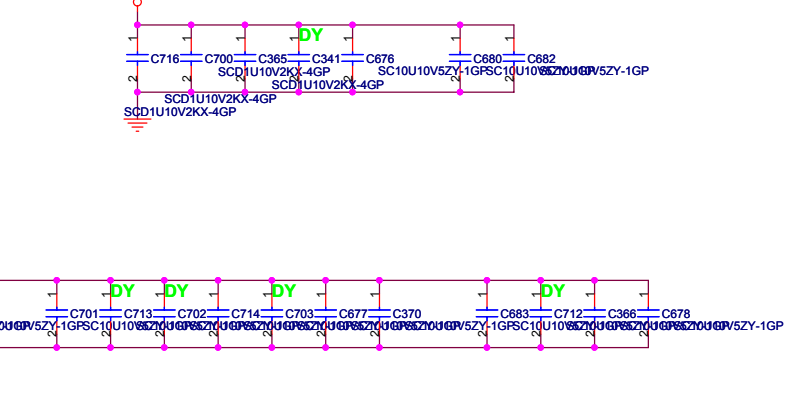
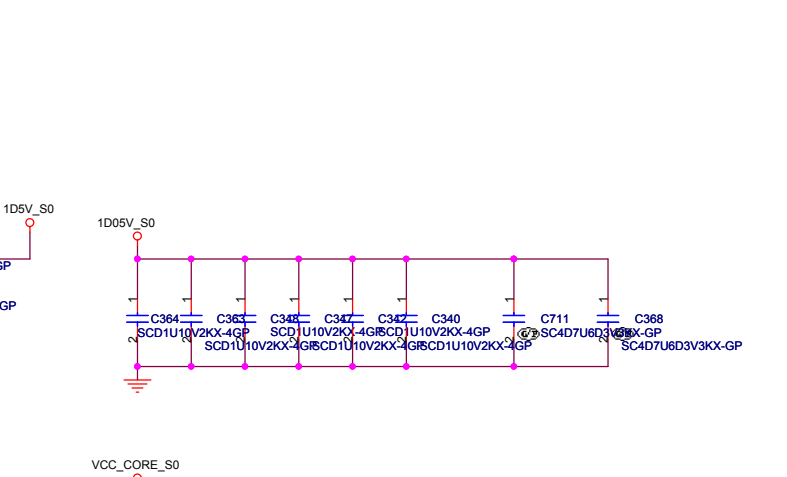
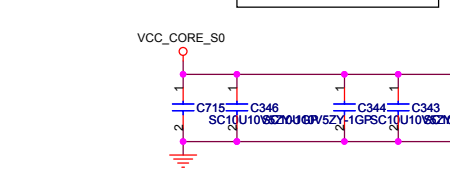
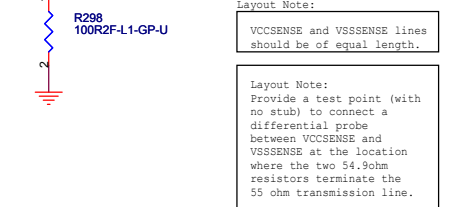
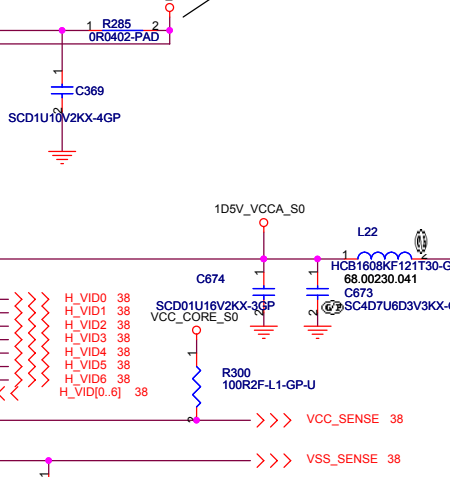
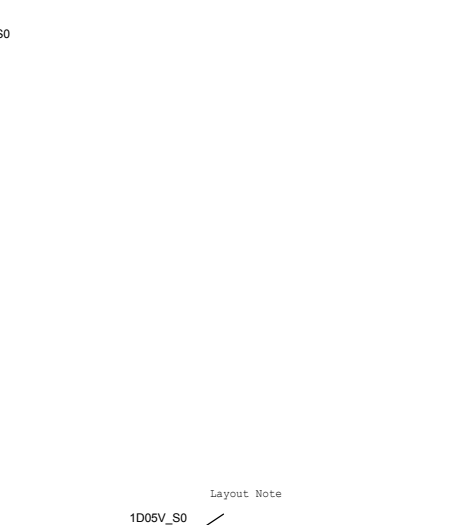
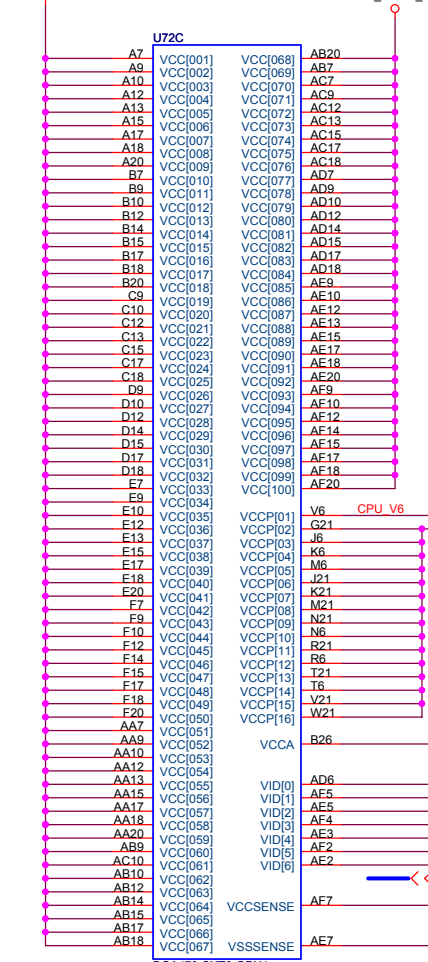
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **CPU (1 of 2)**

Size: A3 Document Number: **AG1** Rev: **SC**

Date: Tuesday, January 10, 2006 Sheet: 4 of 53

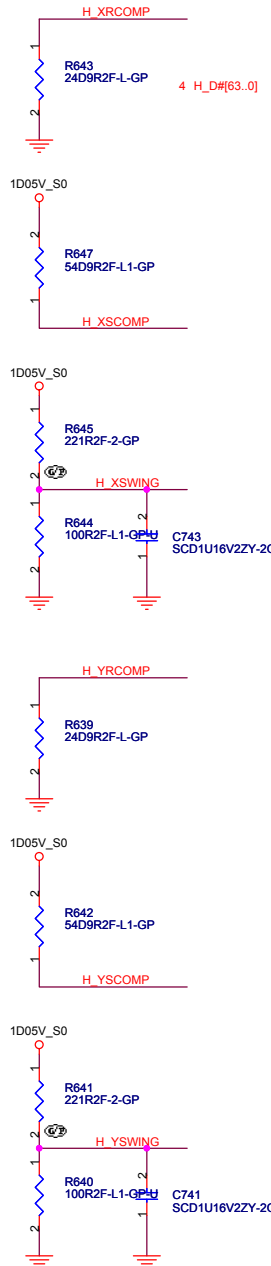
VCC_CORE_S0



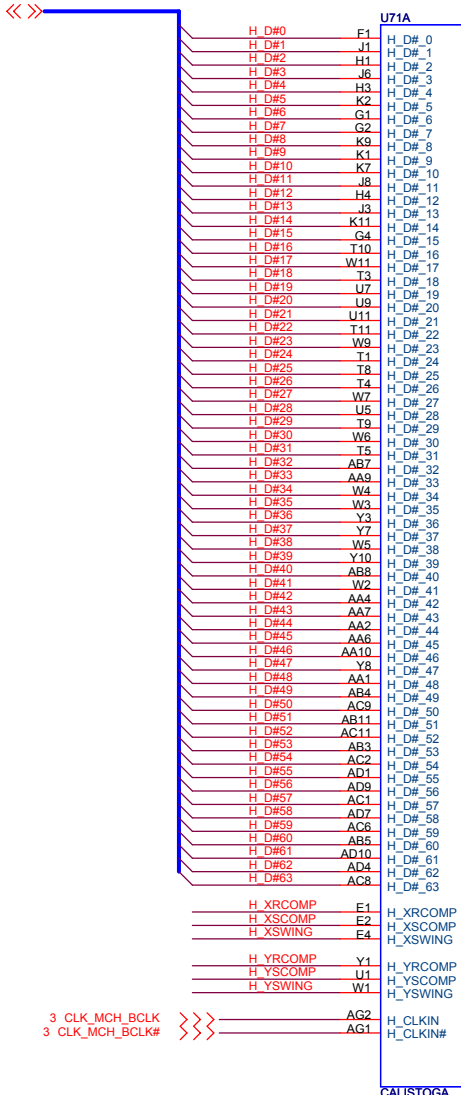
Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Size A3 Document Number **AG1** Rev SA

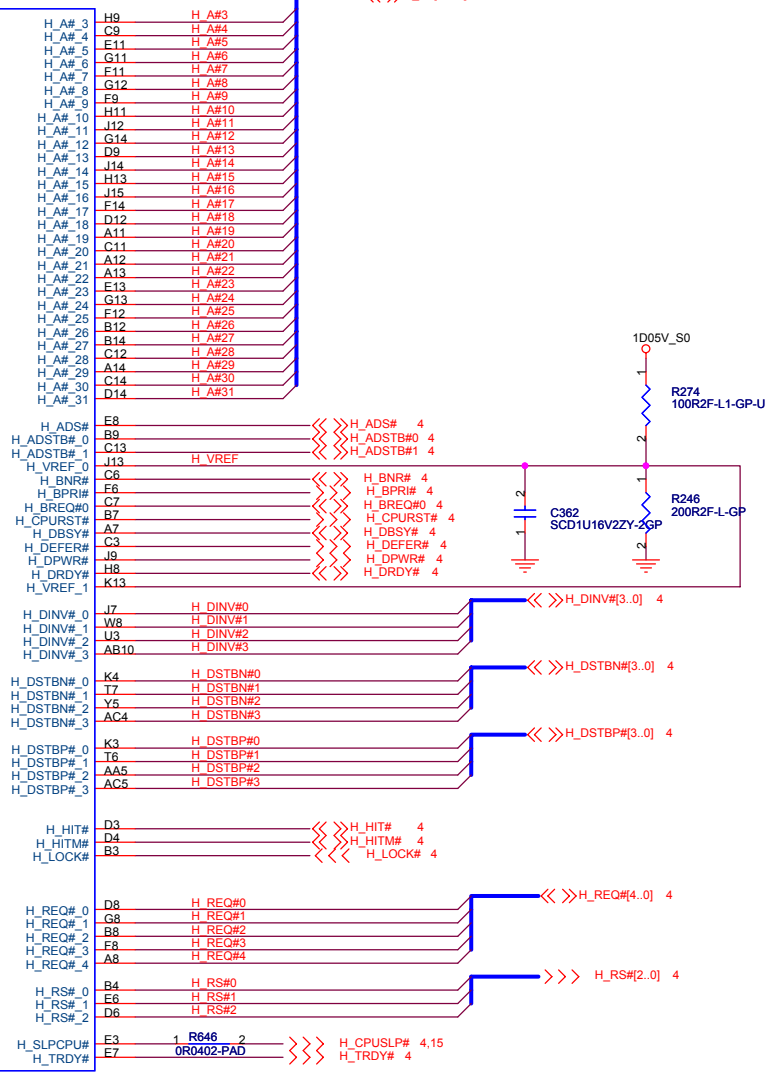
Date: Tuesday, January 10, 2006 Sheet 5 of 53



Place them near to the chip (< 0.5")



HOST



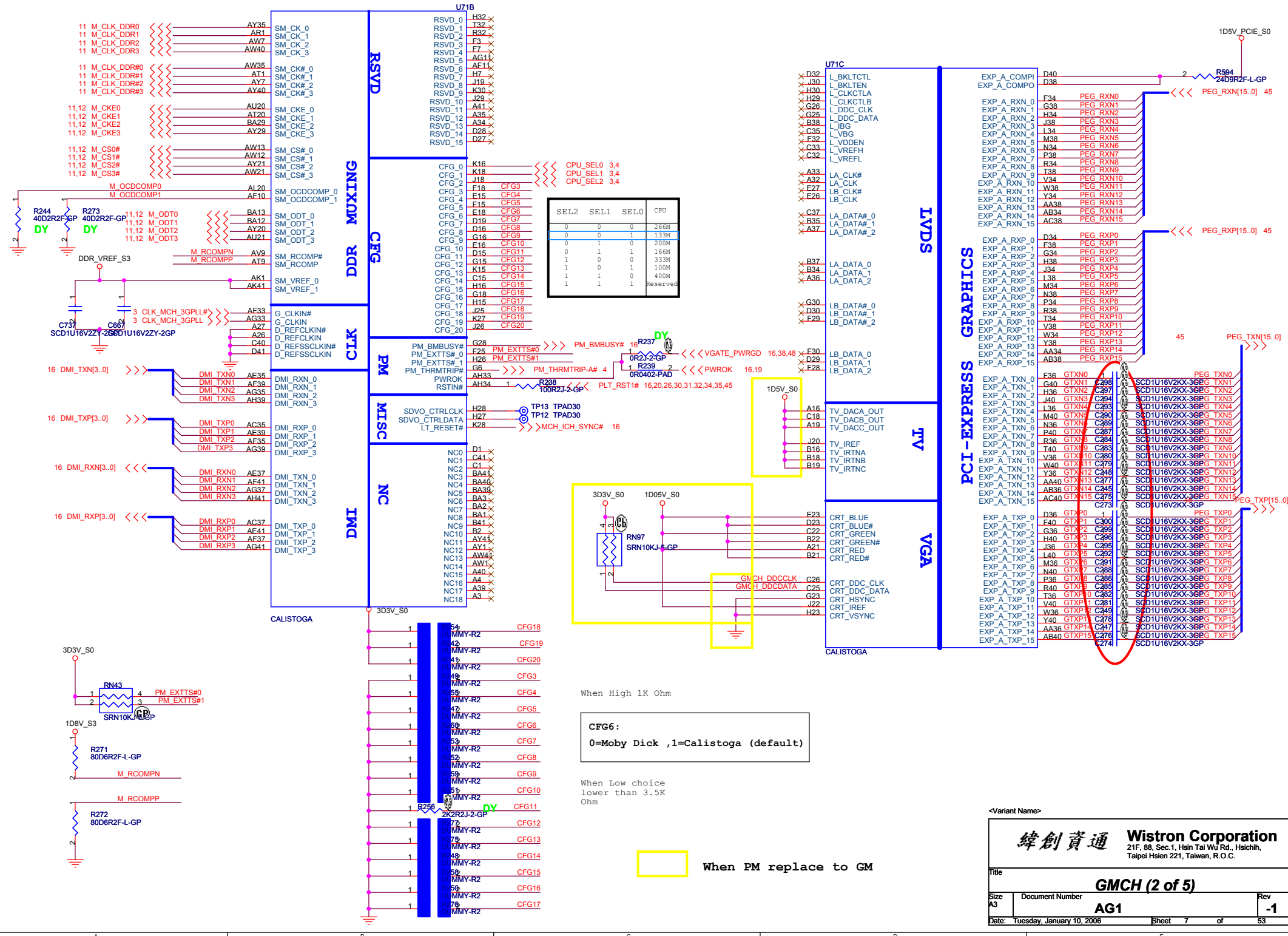
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緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **GMCH (1 of 5)**

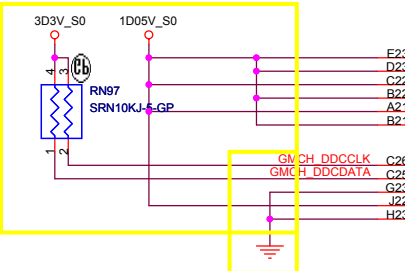
Size: A3 Document Number: **AG1** Rev: **SA**

Date: Tuesday, January 10, 2006 Sheet: 6 of 53



SEL2	SEL1	SEL0	CPU
0	0	0	266M
0	0	1	133M
0	1	0	200M
0	1	1	166M
1	0	0	333M
1	0	1	100M
1	1	0	400M
1	1	1	Reserved

CPU_SEL0 3,4
 CPU_SEL1 3,4
 CPU_SEL2 3,4



When High 1K Ohm

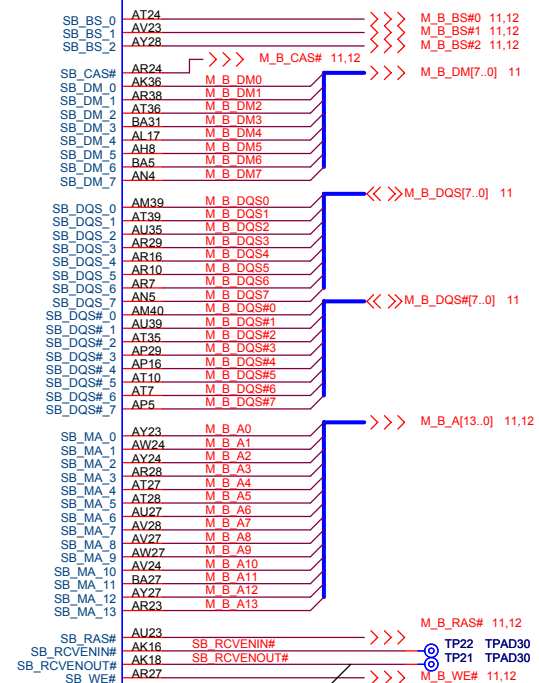
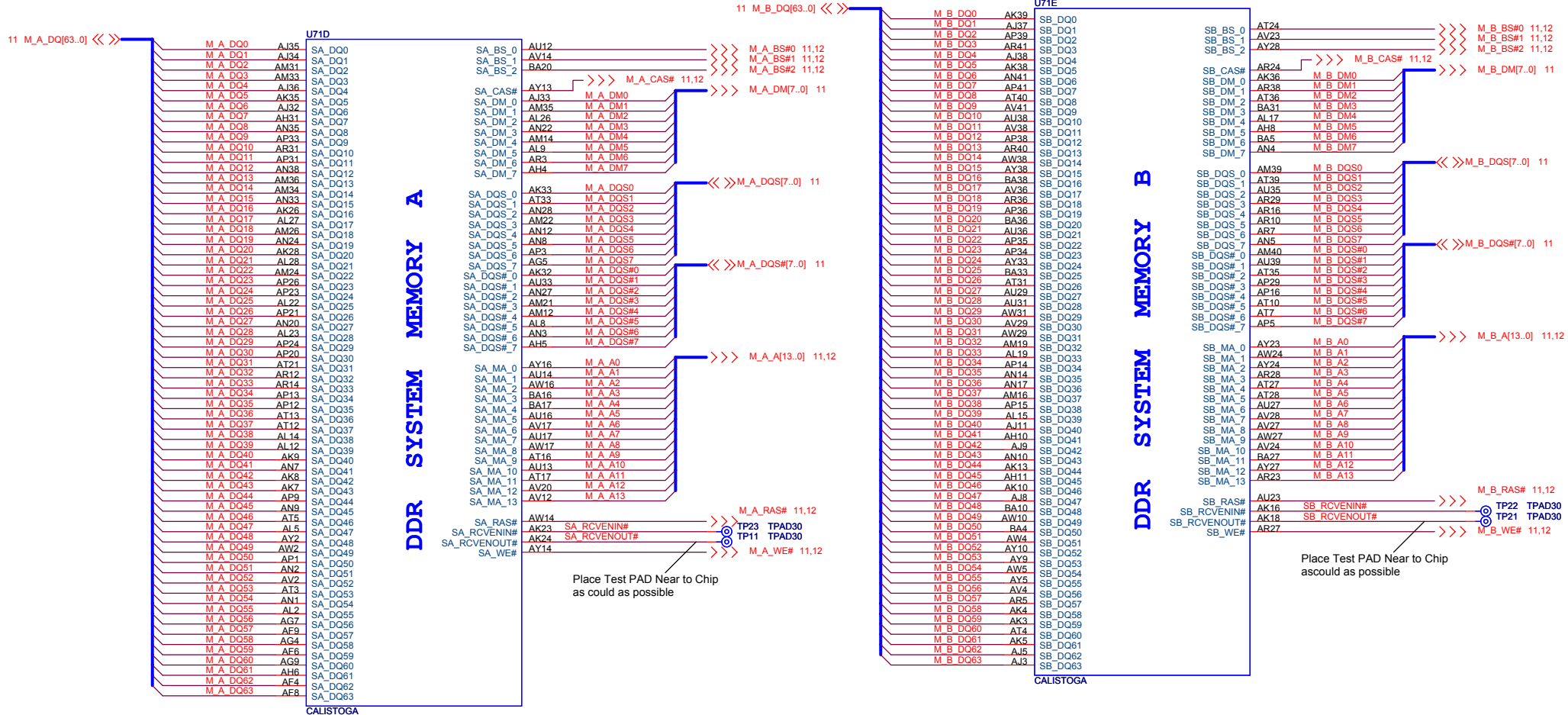
CFG6:
 0=Moby Dick ,1=Calistoga (default)

When Low choice lower than 3.5K Ohm

When PM replace to GM

<Variant Name>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
GMCH (2 of 5)			
Title	Document Number		Rev
	AG1		-1
Date:	Tuesday, January 10, 2006	Sheet	7 of 53



Place Test PAD Near to Chip
as could as possible

Place Test PAD Near to Chip
as could as possible

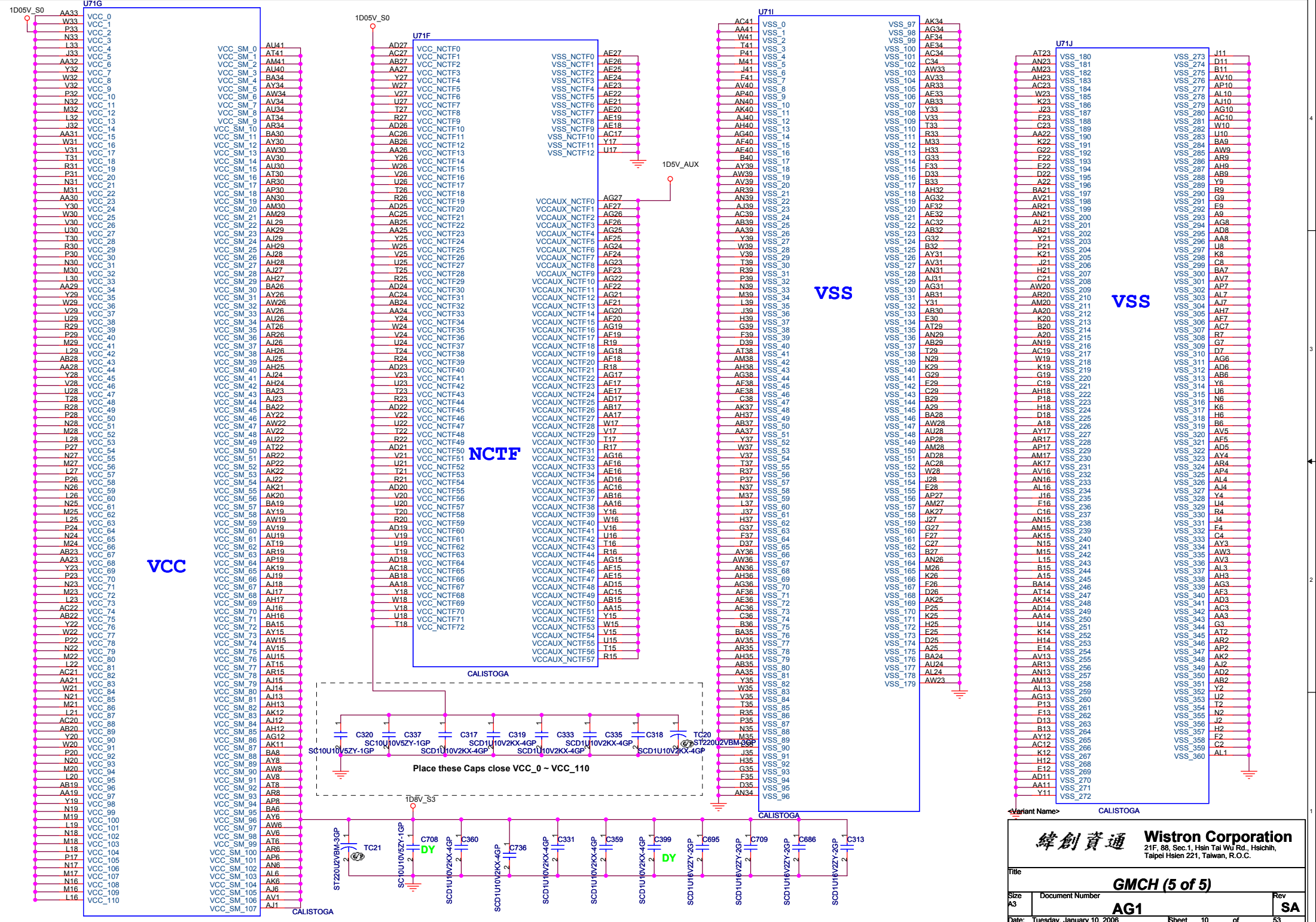
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緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **GMCH (3 of 5)**

Size: A3 Document Number: **AG1** Rev: **SA**

Date: Tuesday, January 10, 2006 Sheet: 8 of 53



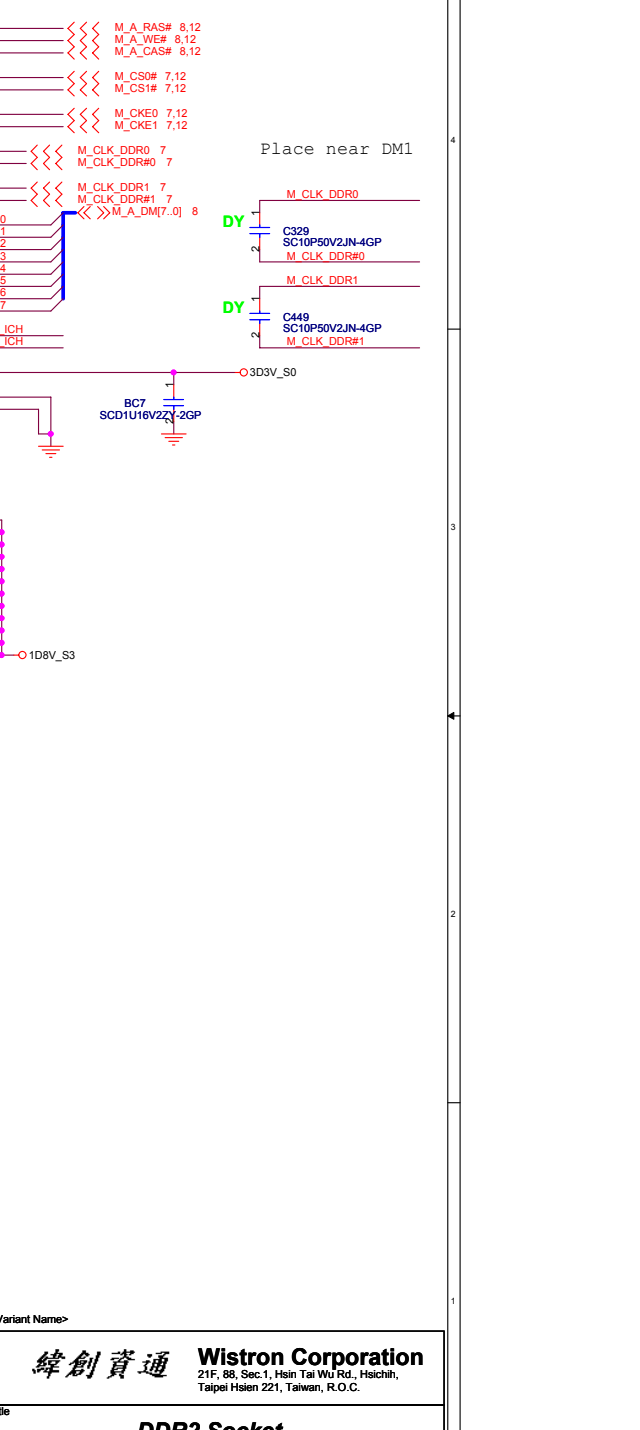
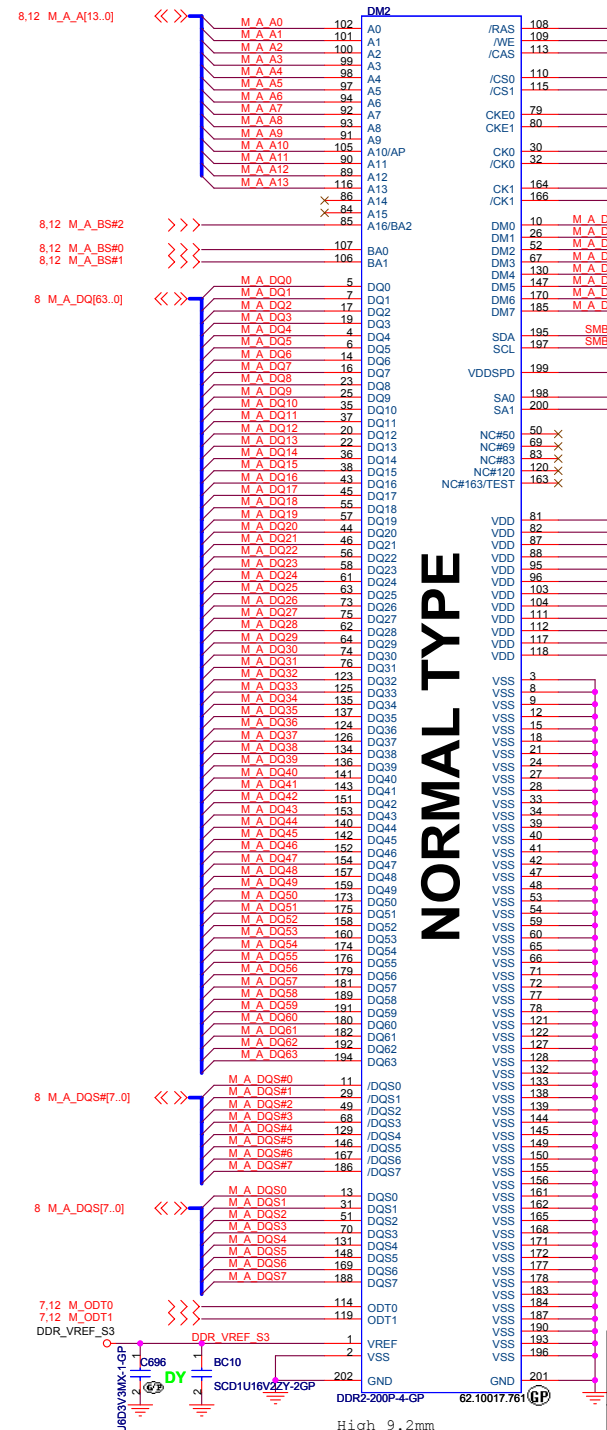
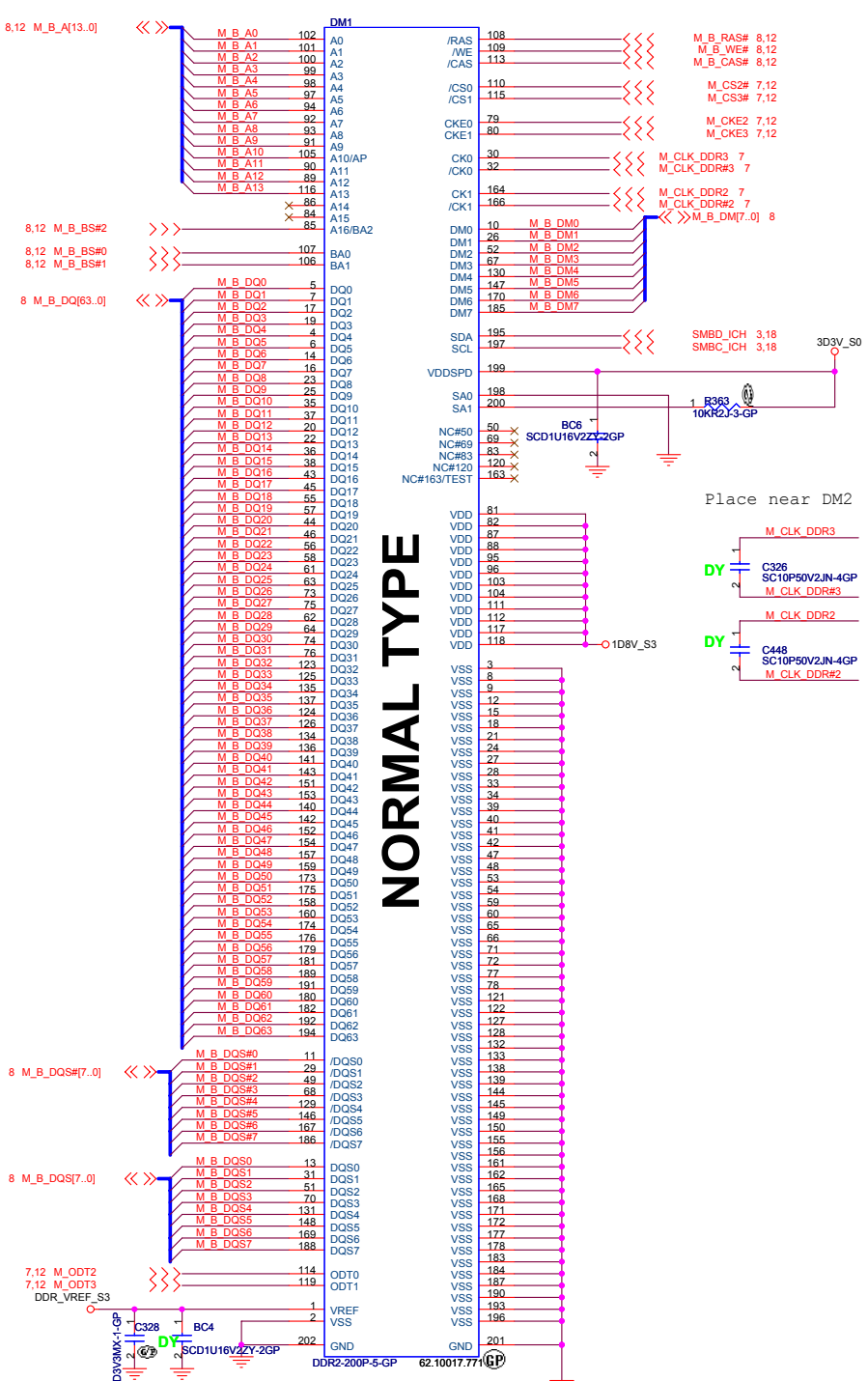
Variant Name> CALISTOGA

緯創資通 Wistron Corporation
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 Taipei Hsien 221, Taiwan, R.O.C.

Title _____

Size A3 Document Number **GMCH (5 of 5)** Rev SA

Date: Tuesday, January 10, 2006 Sheet 10 of 53



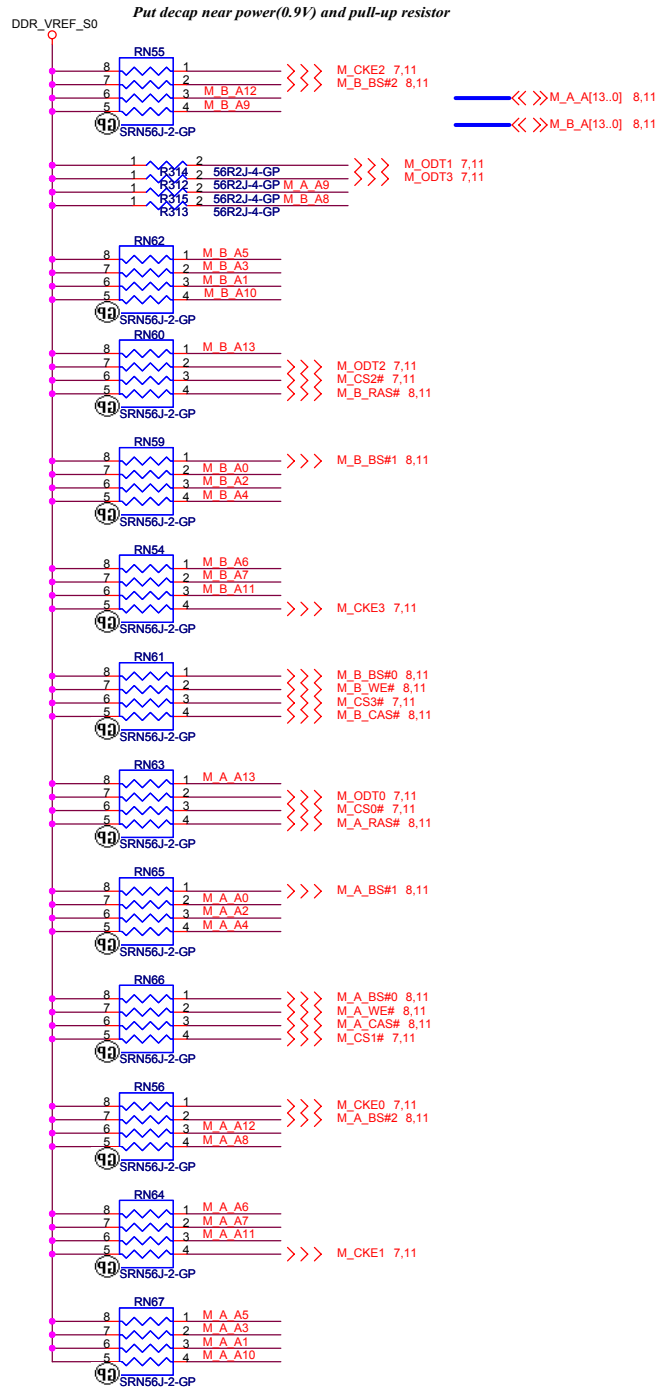
緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

Title: **DDR2 Socket**

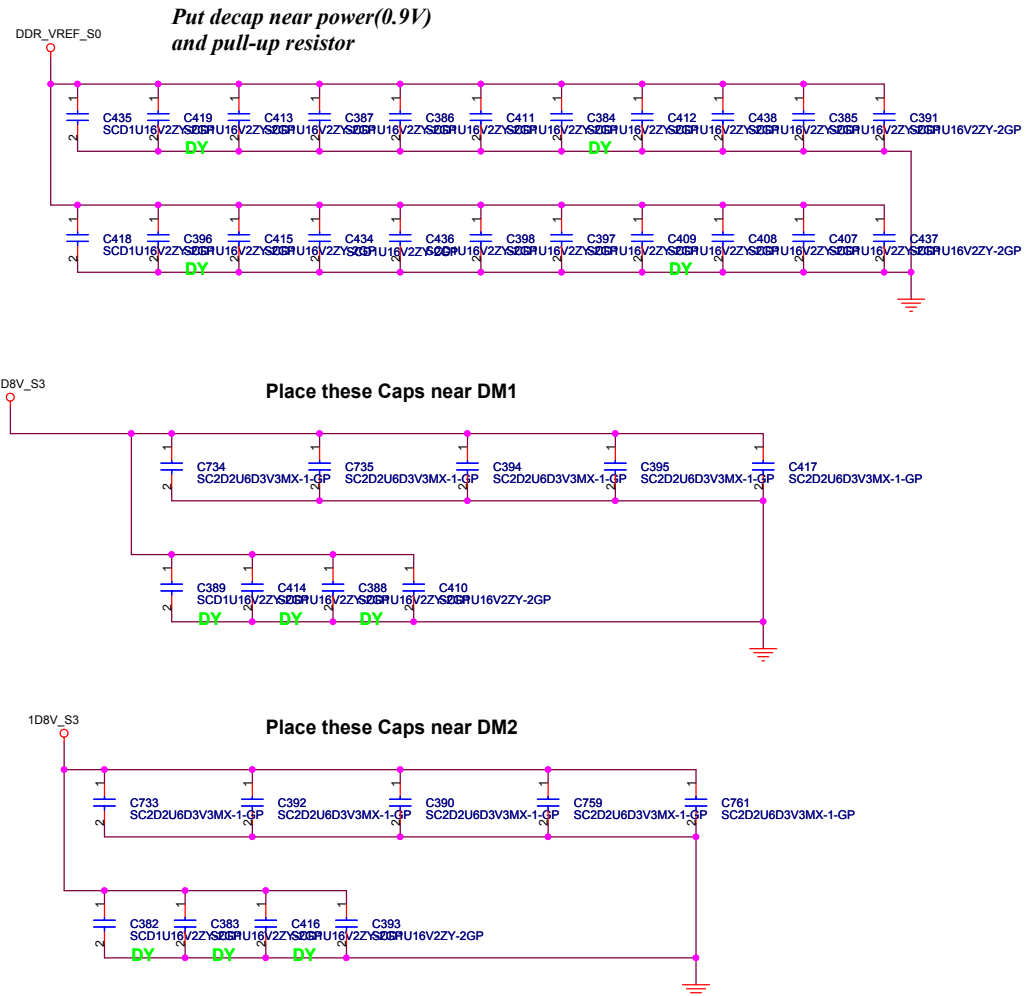
Size: Custom Document Number: **AG1** Rev: **SB**

Date: Tuesday, January 10, 2006 Sheet 11 of 53

PARALLEL TERMINATION



Decoupling Capacitor



<Variant Name>

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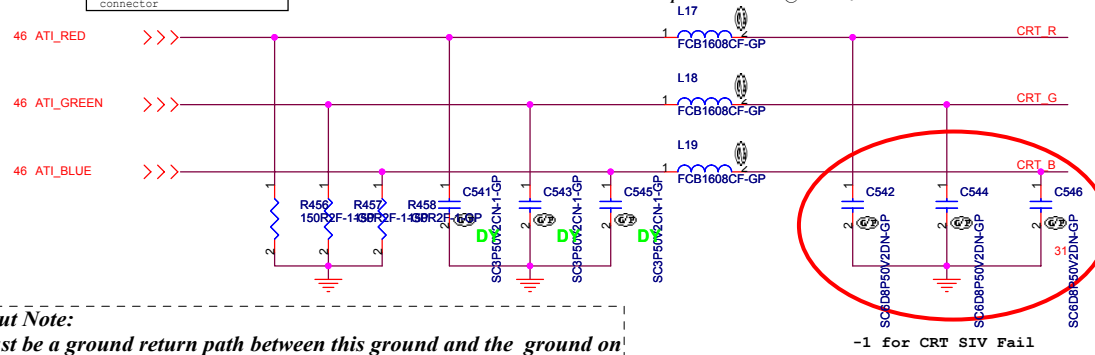
Title: **DDR2 Termination Resistor**

Size: A3	Document Number: AG1	Rev: SA
Date: Tuesday, January 10, 2006	Sheet: 12 of 53	

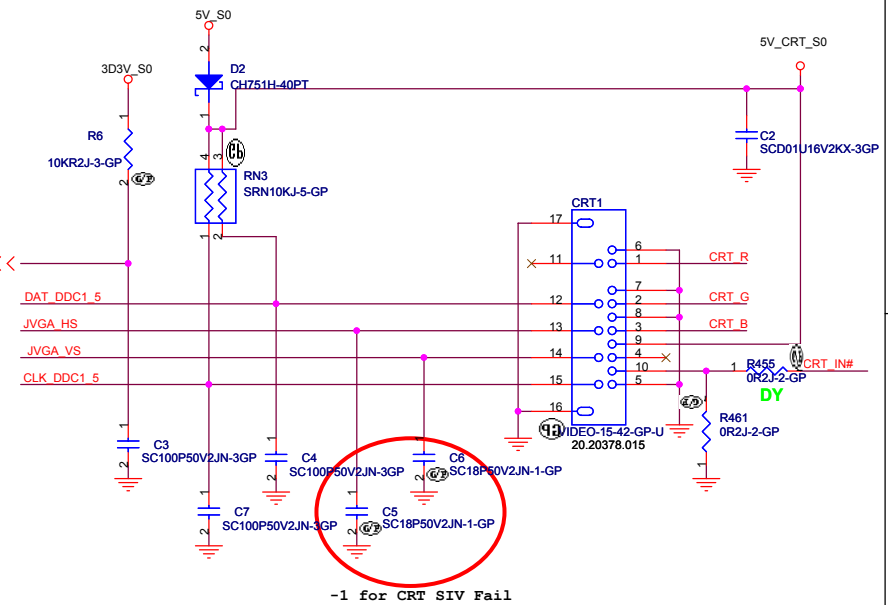
CRT I/F & CONNECTOR

Layout Note:
Place these resistors
close to the CRT-out
connector

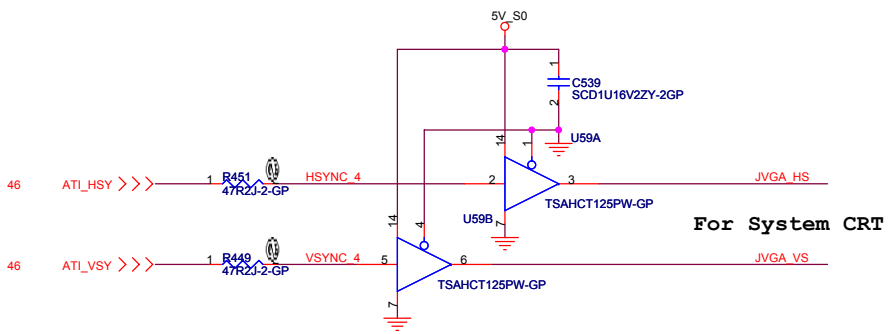
Ferrite bead impedance: 10 ohm@100MHz



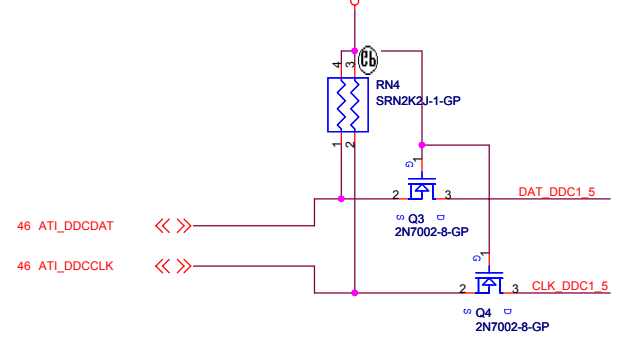
Layout Note:
* Must be a ground return path between this ground and the ground on the VGA connector.
Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN. RGB will hit 75 Ohm first, pi-filter, then CRT CONN.



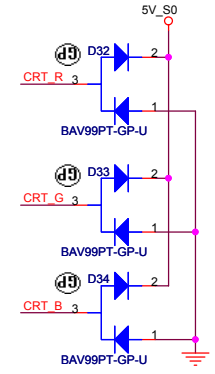
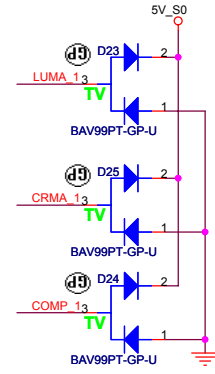
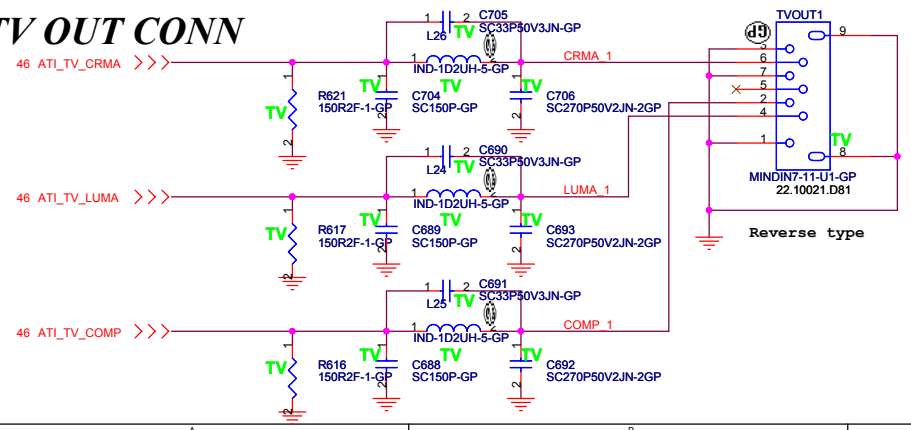
Hsync & Vsync level shift



DDC_CLK & DATA level shift



TV OUT CONN

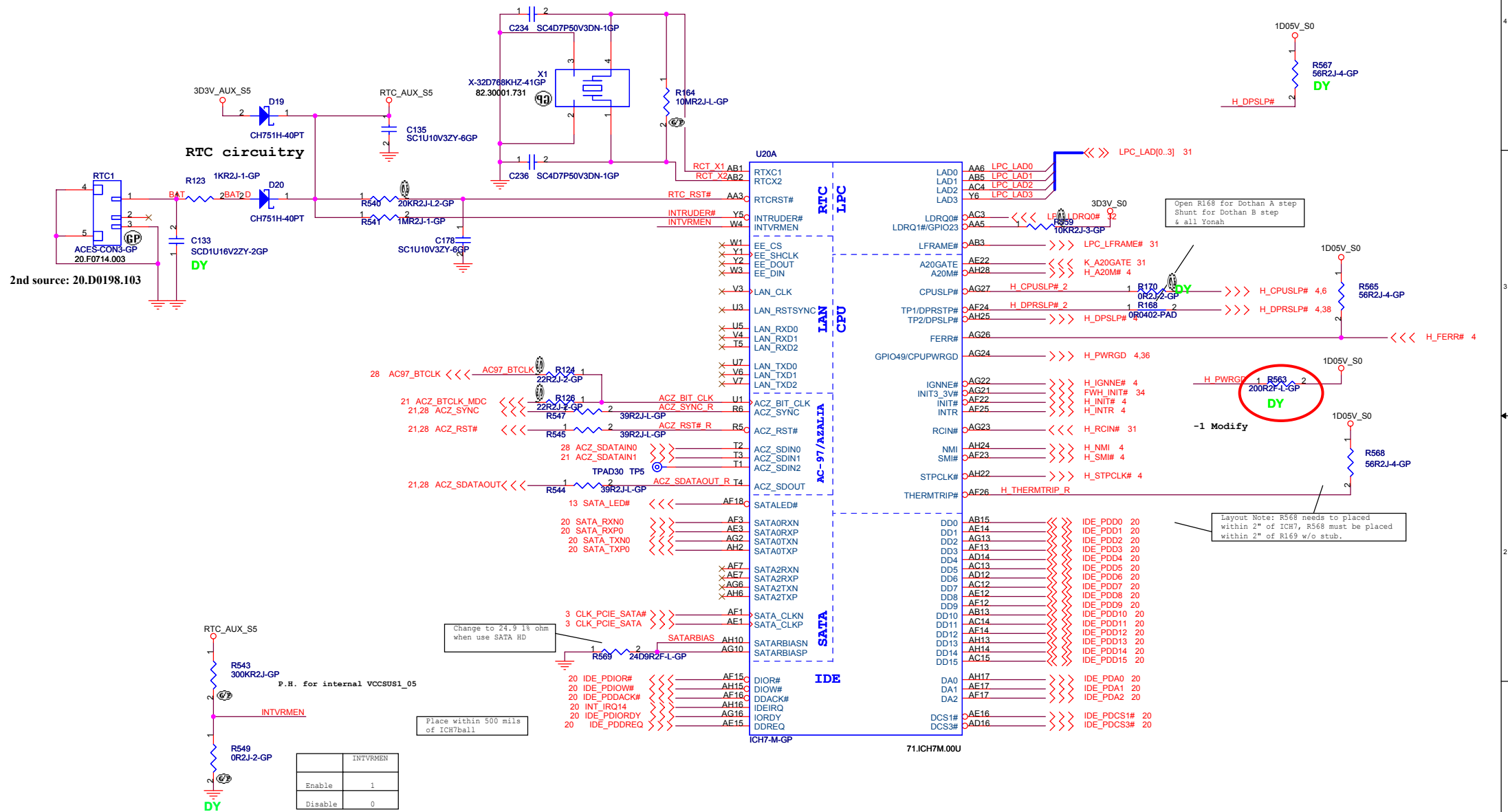


<Variant Name>

緯創資通 Wistron Corporation
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Title: CRT/TV Connector

Size A3	Document Number AG1	Rev -1
Date: Tuesday, January 10, 2006	Sheet 14 of 53	



2nd source: 20.D0198.103

RTC circuitry

RTC_AUX_S5

R543 300KR2J-GP

P.H. for internal VCCSUS1_05

INTVRMEN

R549 0R2J-2-GP

Place within 500 mils of ICH7ball

	INTVRMEN
Enable	1
Disable	0

Placement Note:
Distance between the ICH-7 M and cap on the "P" signal should be identical distance between the ICH-7 M and cap on the "M" signal for same pair.

Open R168 for Dothan A step
Shunt for Dothan B step
& all Yonah

Modify

Layout Note: R568 needs to be placed within 2" of ICH7, R568 must be placed within 2" of R169 w/o stub.

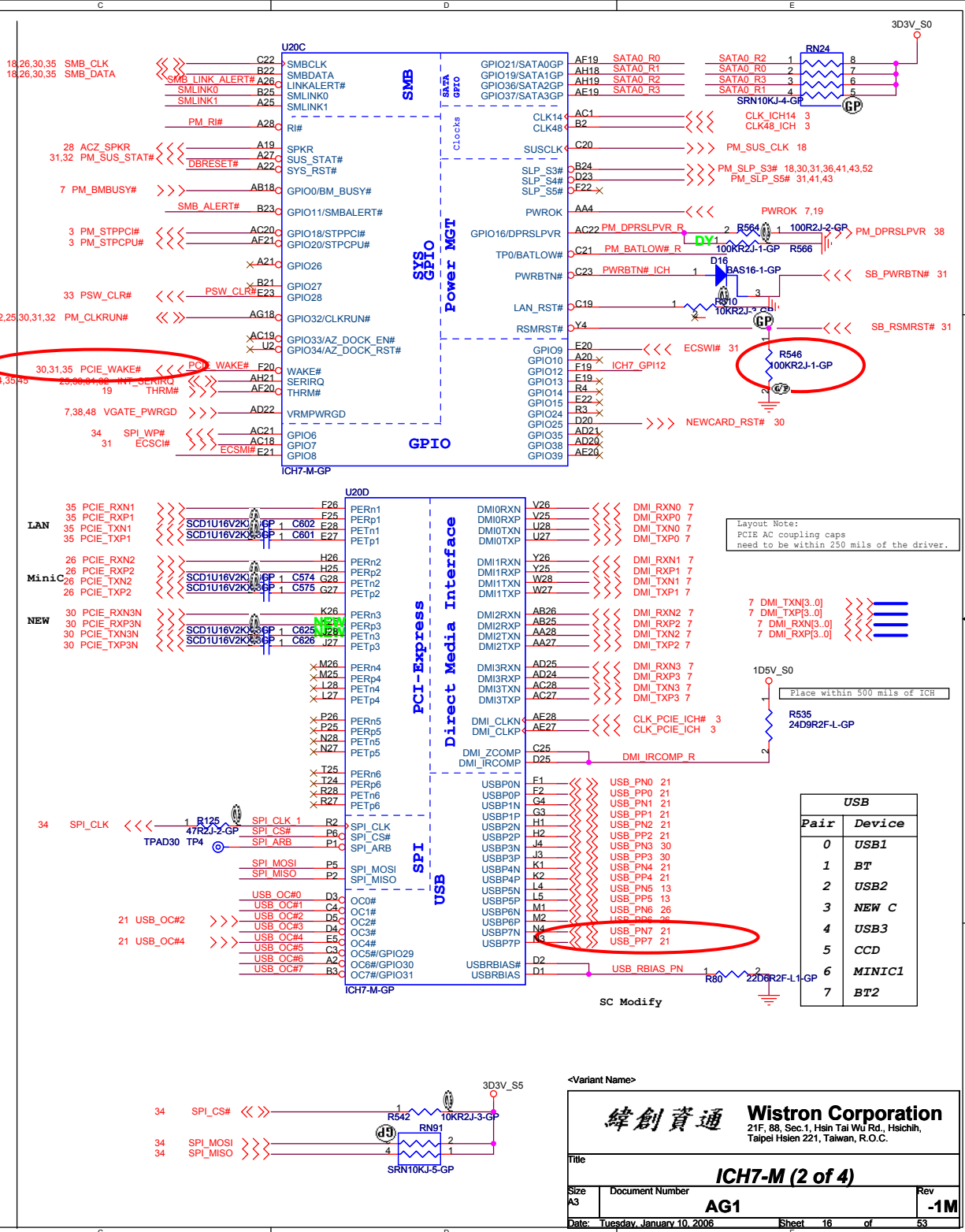
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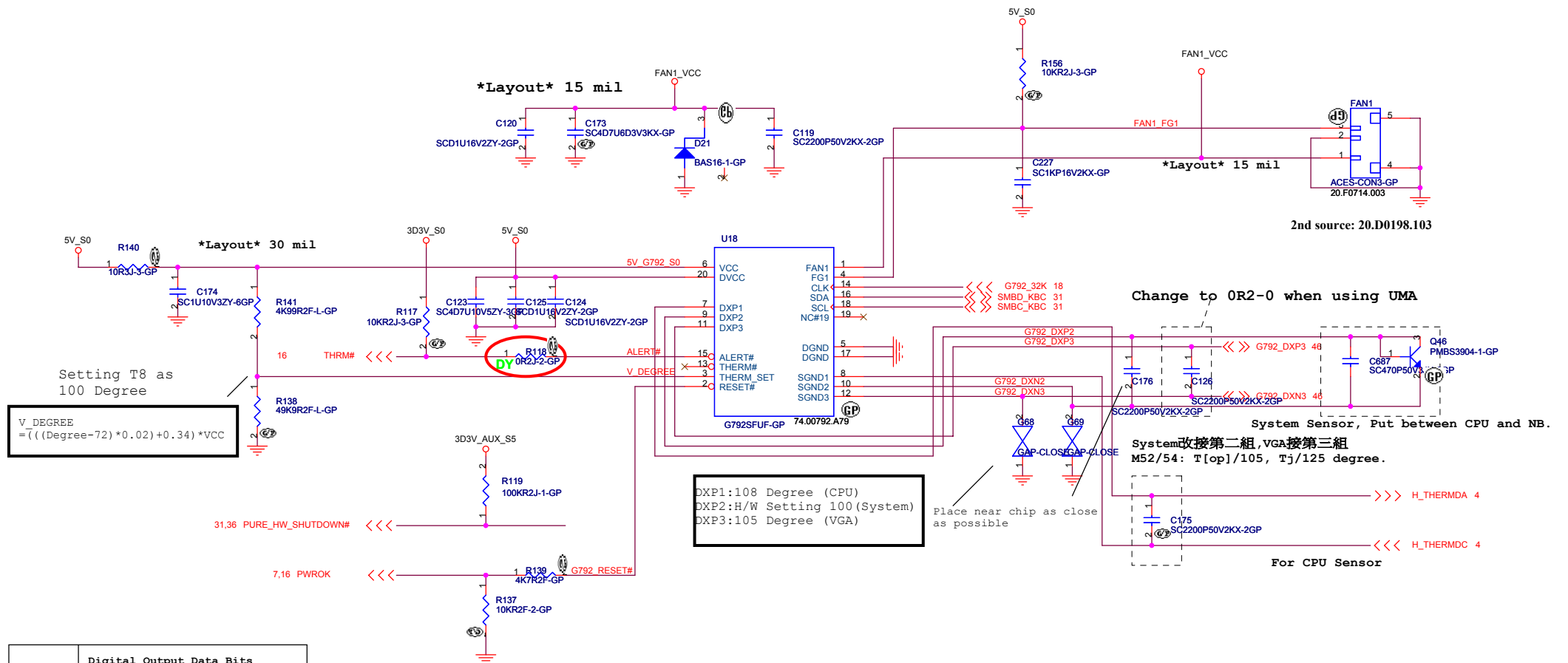
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **ICH7-M (1 of 4)**

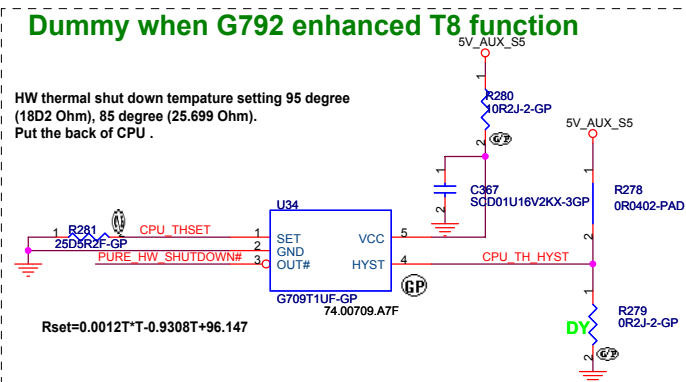
Size: A3 Document Number: **AG1** Rev: **-1**

Date: Tuesday, January 10, 2006 Sheet 15 of 53





TEMP.	Digital Output Data Bits			
	Sign	MSB	LSB	EXT
+127.875	0	111	1111	111
+126.375	0	111	1110	011
+25.5	0	001	1001	100
+1.75	0	000	0001	110
+0.5	0	000	0000	100
+0.125	0	000	0000	001
-0.125	1	111	1111	111
-1.125	1	111	1110	111
-25.5	1	110	0110	100
-55.25	1	100	1000	110
-65.000	1	011	1111	000



Thermal Get Setting

Sensor	Setting	T6	T7
Sensor 0	CPU DTS	98	100
Sensor 1	G792-1 CPU	98	100
Sensor 2	G792-2 System	78	83
Sensor 3	G792-3 VGA	110	115

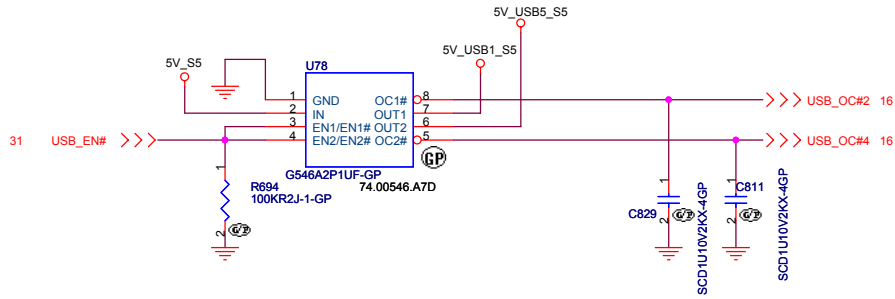
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緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

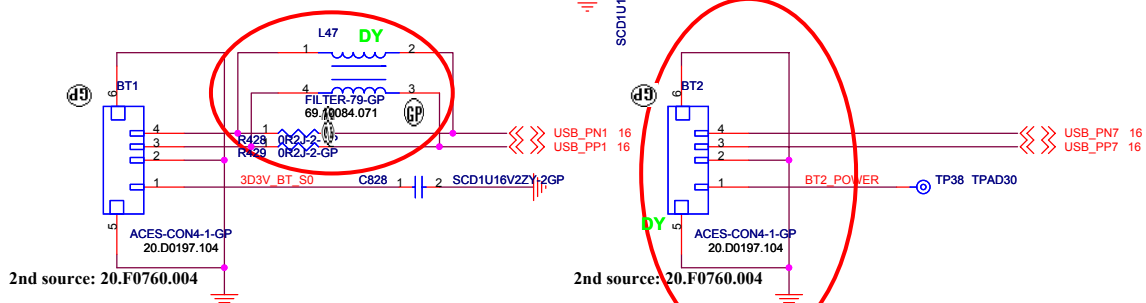
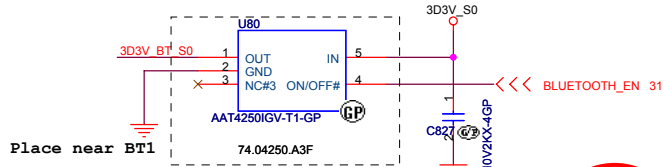
Title: **Thermal/Fan Controller G792**

Size	Document Number	Rev
Custom	AG1	SC

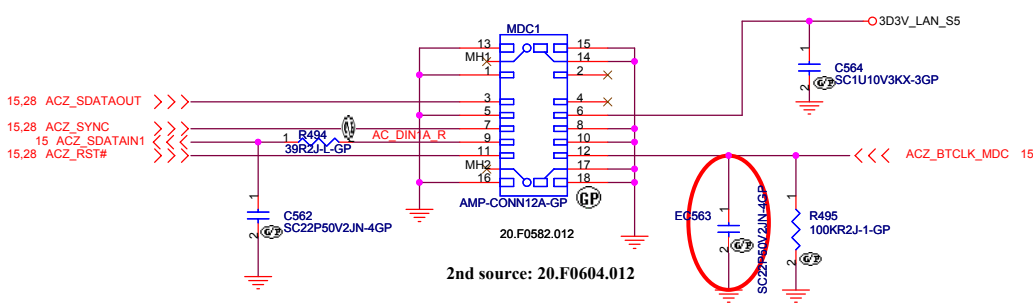
Date: Tuesday, January 10, 2006 Sheet 19 of 53



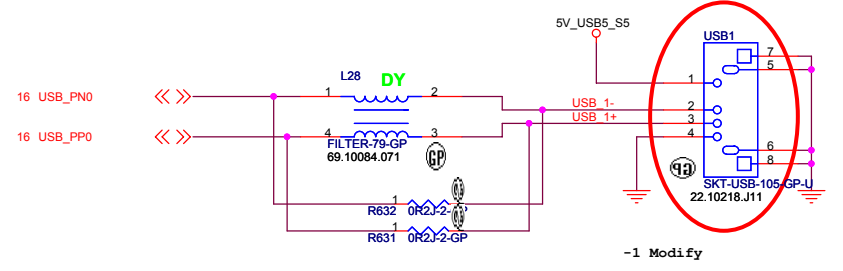
BLUETOOTH MODULE CONNECTOR



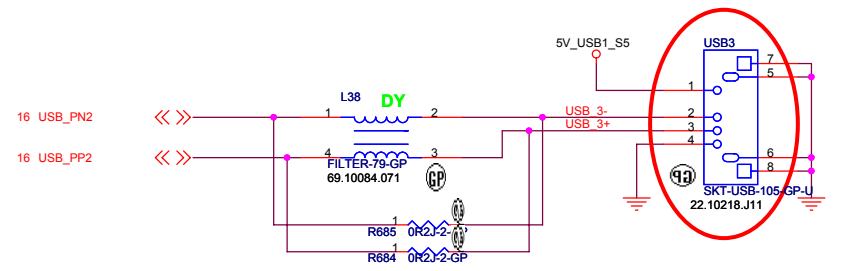
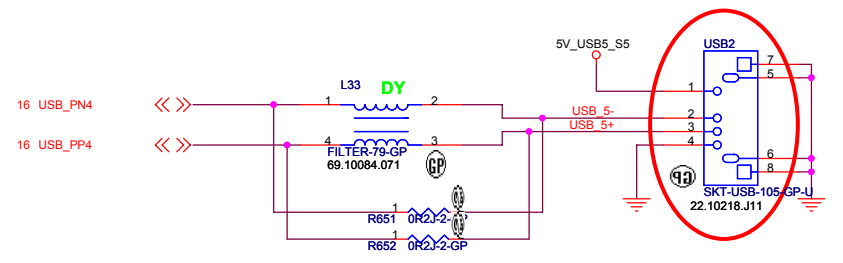
MDC 1.5 CONN



USB PORT

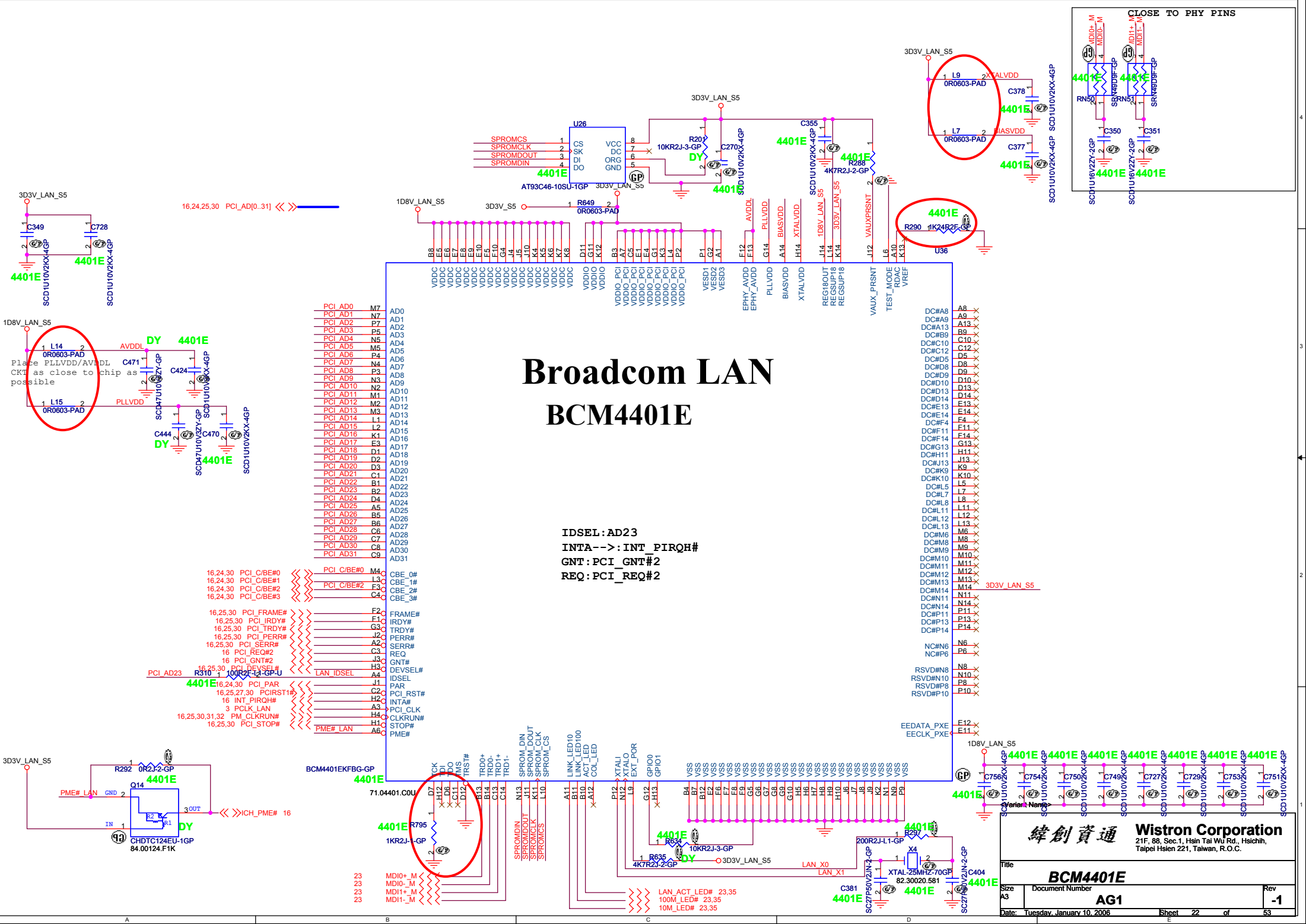


-1 Modify



<Variant Name>

緯創資通		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
USB and MDC I/F			
File	Document Number		Rev
Size	AG1		-1
A3	Date: Tuesday, January 10, 2006	Sheet 21	of 53



Broadcom LAN BCM4401E

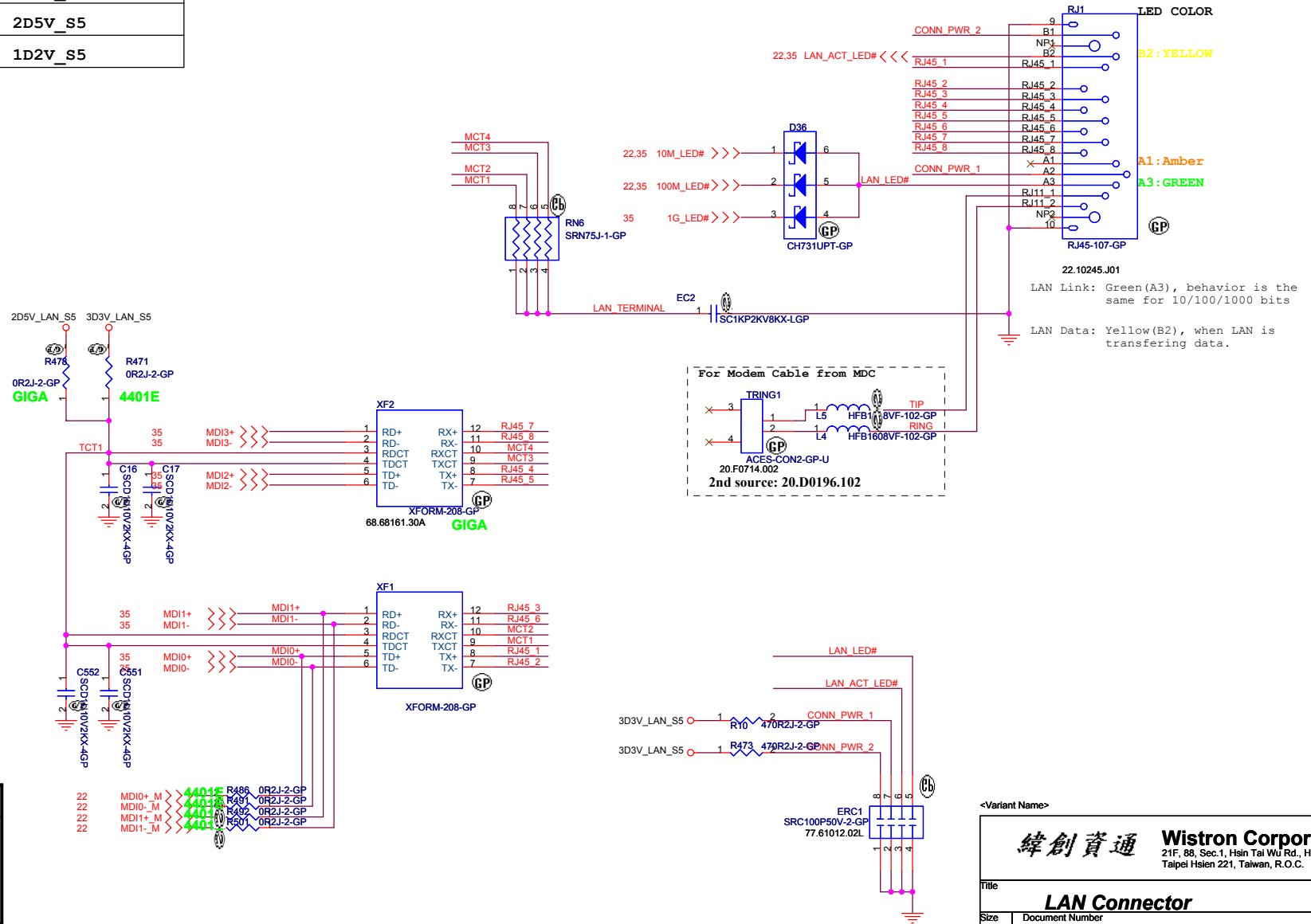
IDSEL: AD23
 INTA-->: INT_PIRQH#
 GNT: PCI_GNT#2
 REQ: PCI_REQ#2

緯創資通 Wistron Corporation
 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

BCM4401E
 AG1
 Date: Tuesday, January 10, 2006 Sheet 22 of 53

Voltage Rail	4401E	5789	5787
VDDIO_PCI	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDC	1D8V_LAN_S5	1D2V_LAN_S5	
VDDIO	3D3V_LAN_S5	3D3V_LAN_S5	
VESD	3D3V_LAN_S5	3D3V_S0	Don't Care
VDDP	Don't Care	2D5V_S5	
3D3V_2D5V_S5	3D3V_S5	2D5V_S5	
1D8V_1D2V_S5	1D8V_LAN_S5	1D2V_S5	

LAN Connector



1. route on bottom as differential pairs.
2. Tx+/Tx- are pairs. Rx+/Rx- are pairs.
3. No vias, No 90 degree bends.
4. pairs must be equal lengths.
5. 6mil trace width, 12mil separation.
6. 36mil between pairs and any other trace.
7. Must not cross ground moat, except RJ-45 moat.

RJ11 signal must leave the other signal or power plane 100mil.

DOC_TIP, DOC_RING, TIP, RING:
W/S : 10/100 @ Surface layers
10/20 @ Inner layers

10/100 LAN Transformer	RJ45 PIN
TD+ --> TX+	RJ45-1
TD- --> TX-	RJ45-2
RD+ --> RX+	RJ45-3
RD- --> RX-	RJ45-6

<Variant Name>

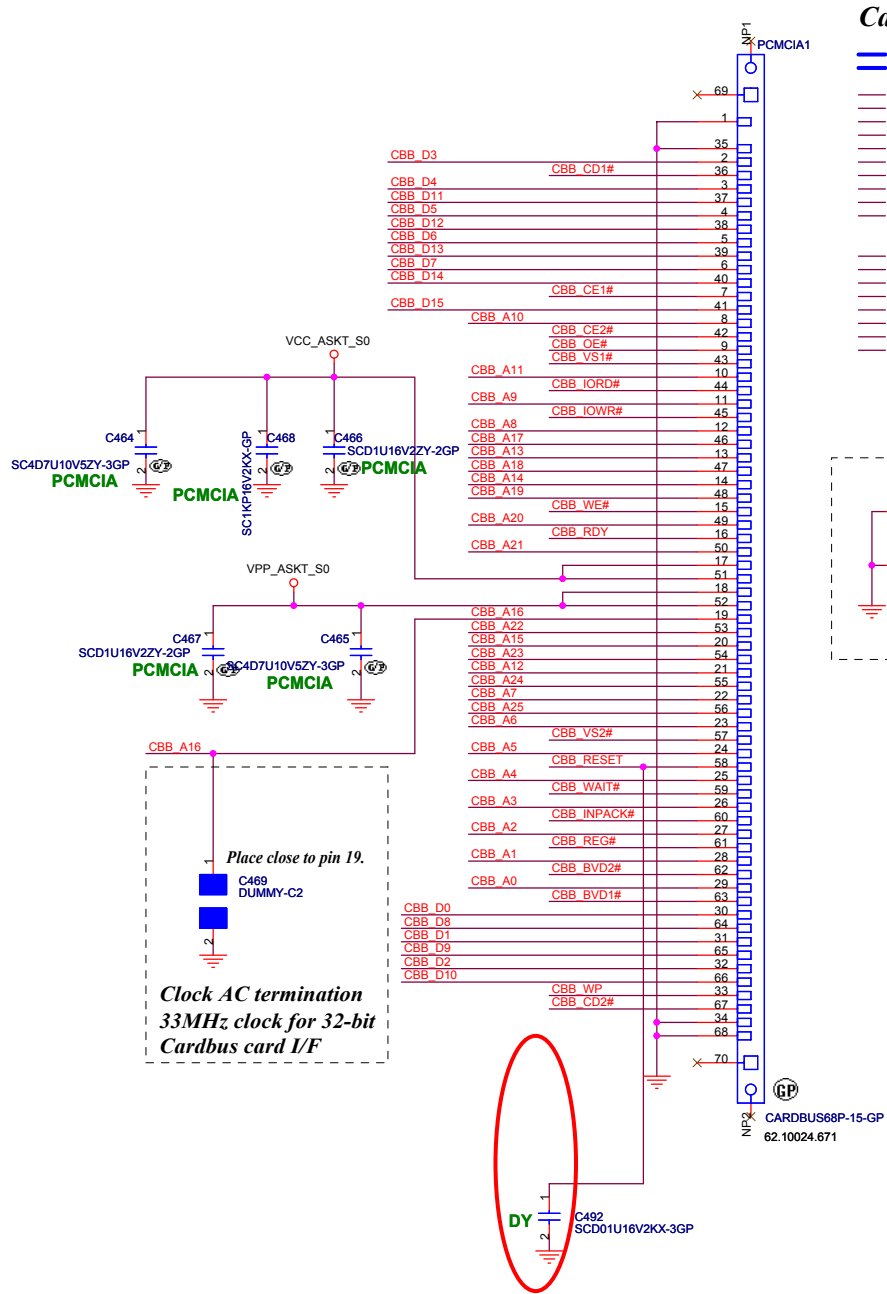
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **LAN Connector**

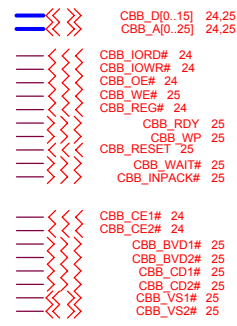
Size A3 Document Number **AG1** Rev **SD**

Date: Tuesday, January 10, 2006 Sheet 23 of 53

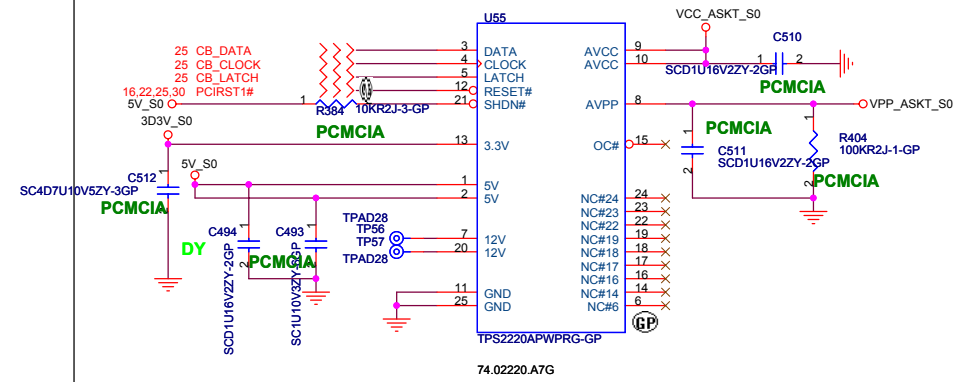
PCMCIA Socket



Cardbus I/F



Power switch



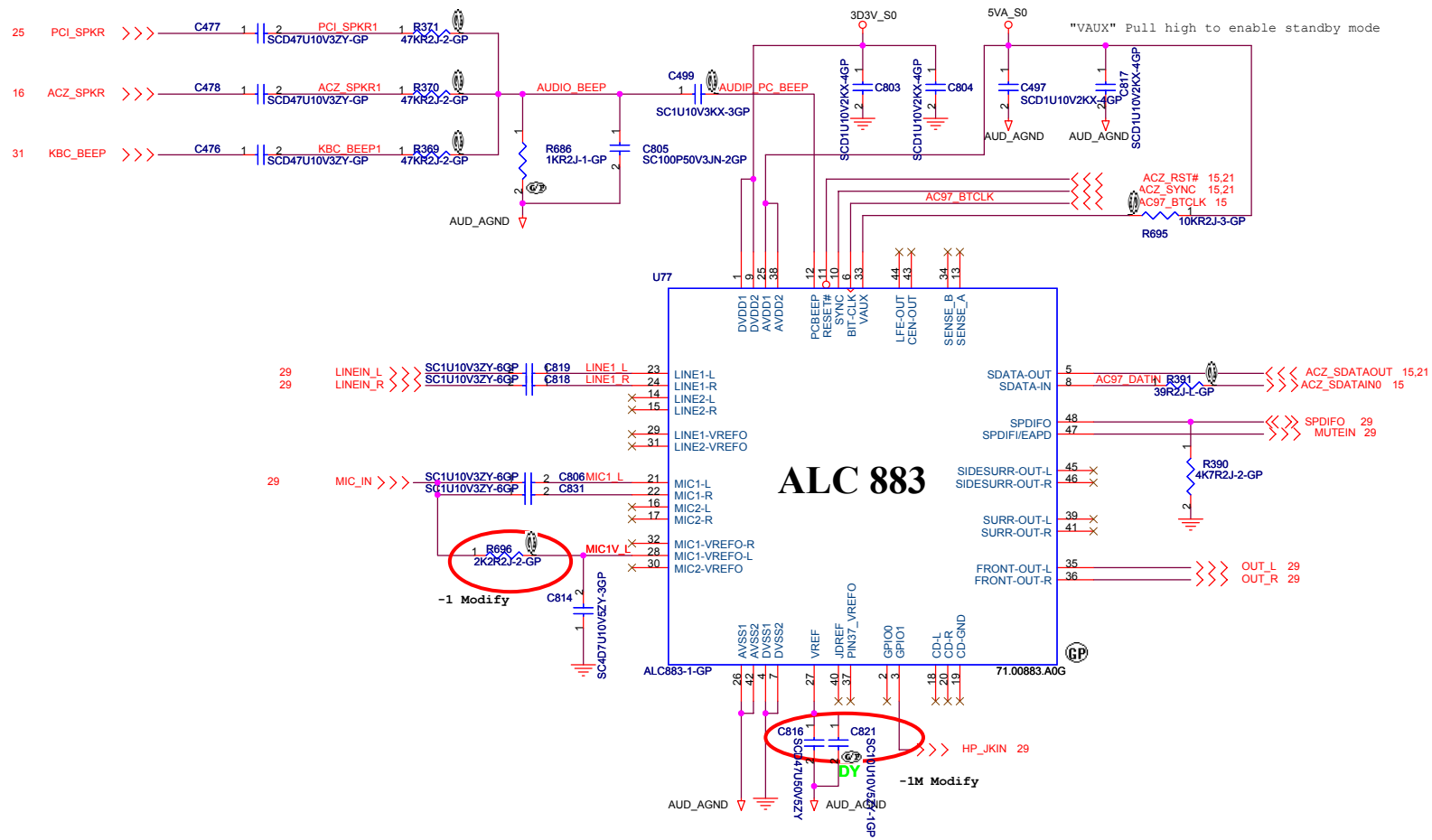
<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCMCIA**

Size A3	Document Number AG1	Rev SC
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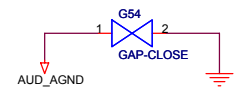
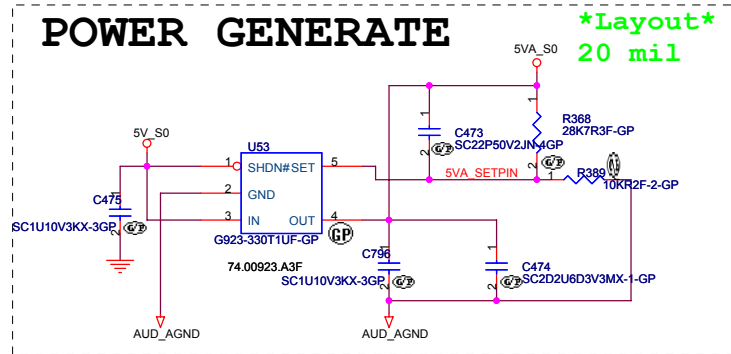
Date: Tuesday, January 10, 2006 Sheet 27 of 53



- 1) When GPIO0 is asserted, AMP should be muted.
- 2) SPDIFO should be turned off when not used.

Configuration:
 (3 External Jacks, 1 internal Mic, 1 stereo output Speaker Amp.

Pin	Symbol	Location	Re-tasking
35/36	FRONT	AMP, Jack1	AMP output, line input
39/41	SURR	X	X
43/44	CEN/LEFT	X	SURR-VREFO-L/R
45/46	SIDESURR	X	SIDESURR-L is MIC2-VREFO-R, SIDESURR-R is LINE2-VREFO-R
23/24	LINE1	Jack 2	Line input, line output
21/22	MIC1	Jack 3	Mic input, line output
14/15	LINE2	X	X
16/17	MIC2	Int. Mic	Mic input



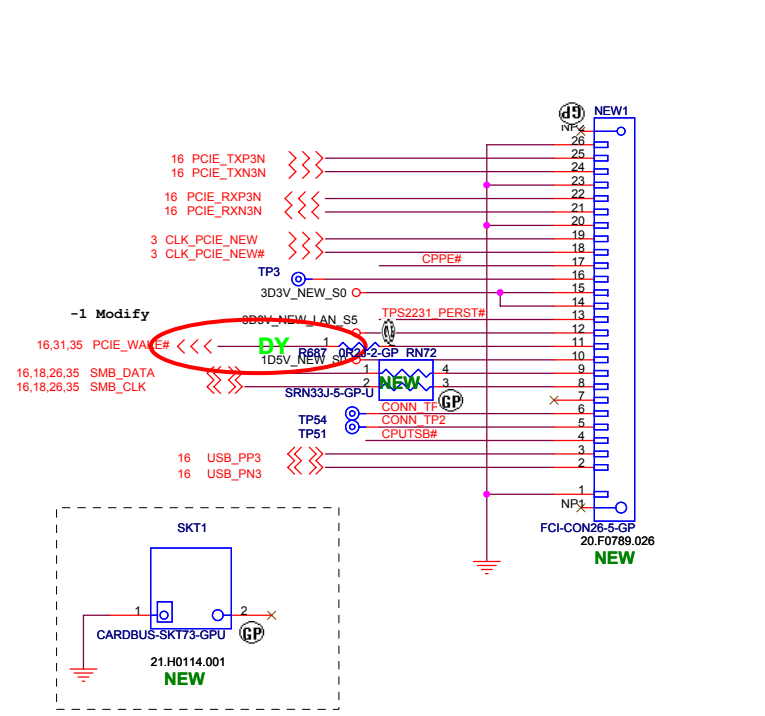
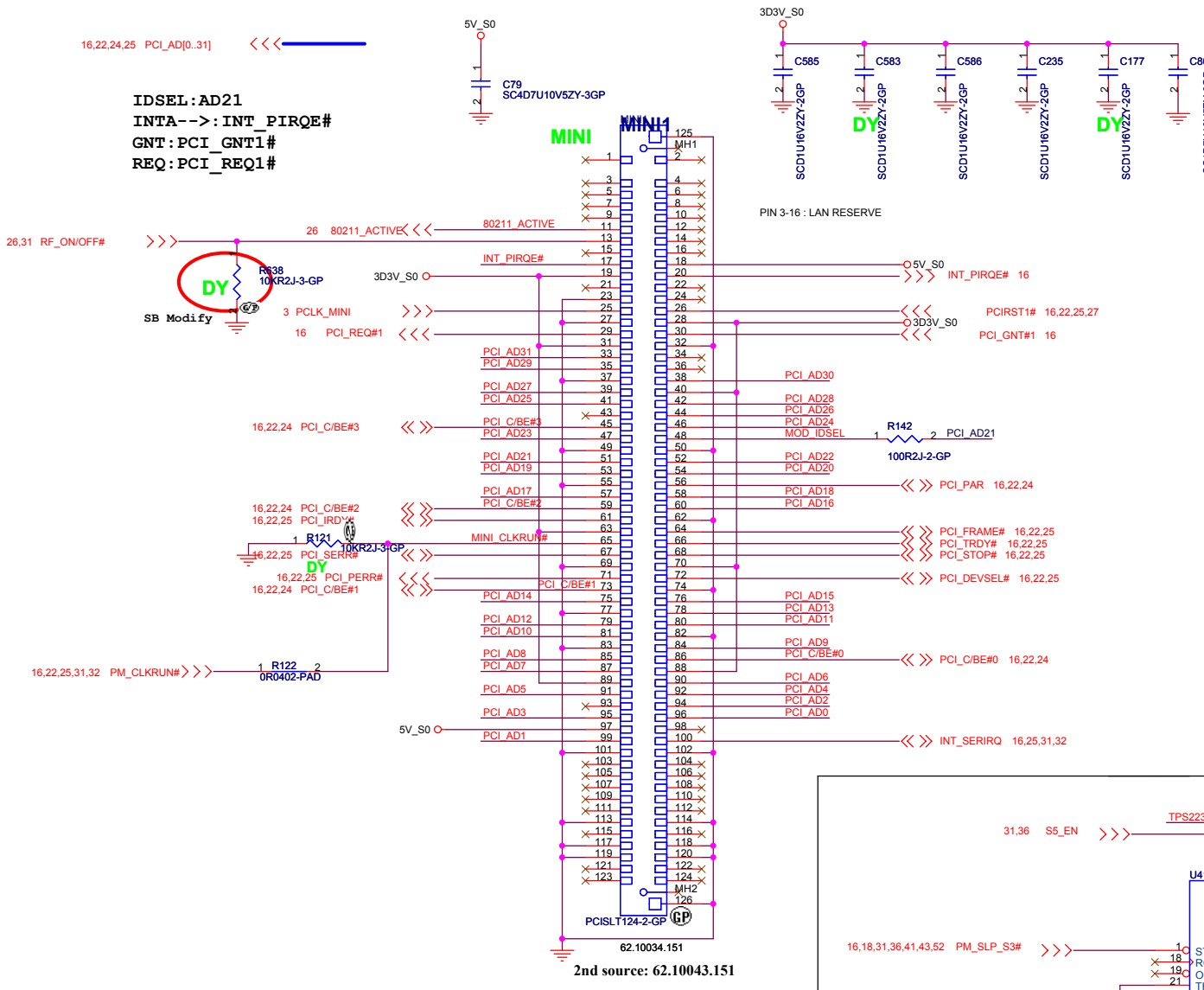
<Variant Name>

緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **Azalia codec ALC883**

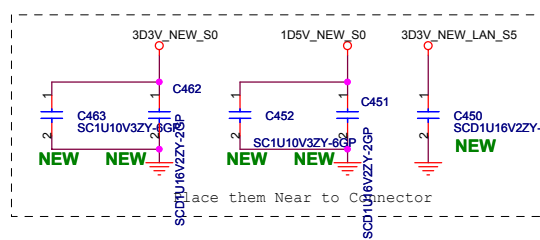
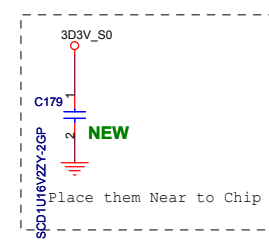
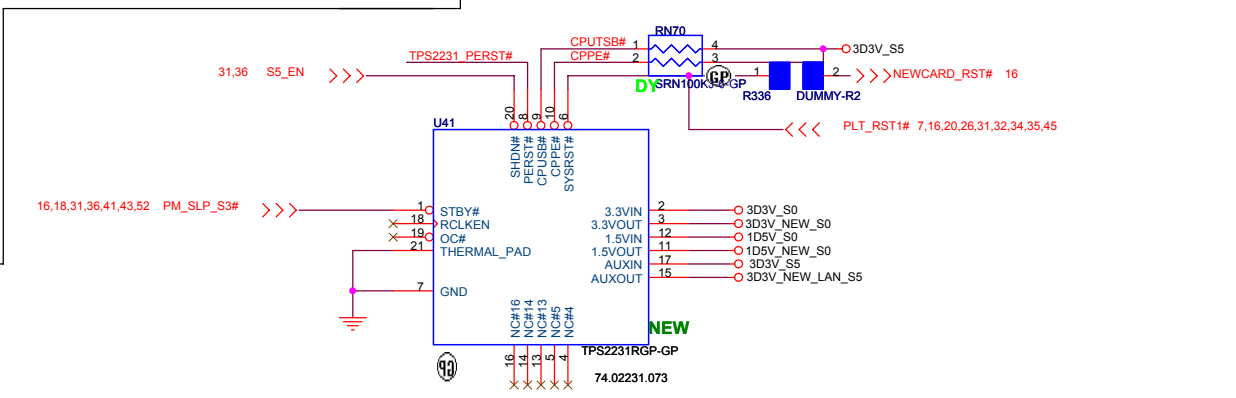
Size: A3 Document Number: **AG1** Rev: **-1M**

Date: Tuesday, January 10, 2006 Sheet 28 of 53



NEWCARD Connector

Reserve the symbol for bottom side connector



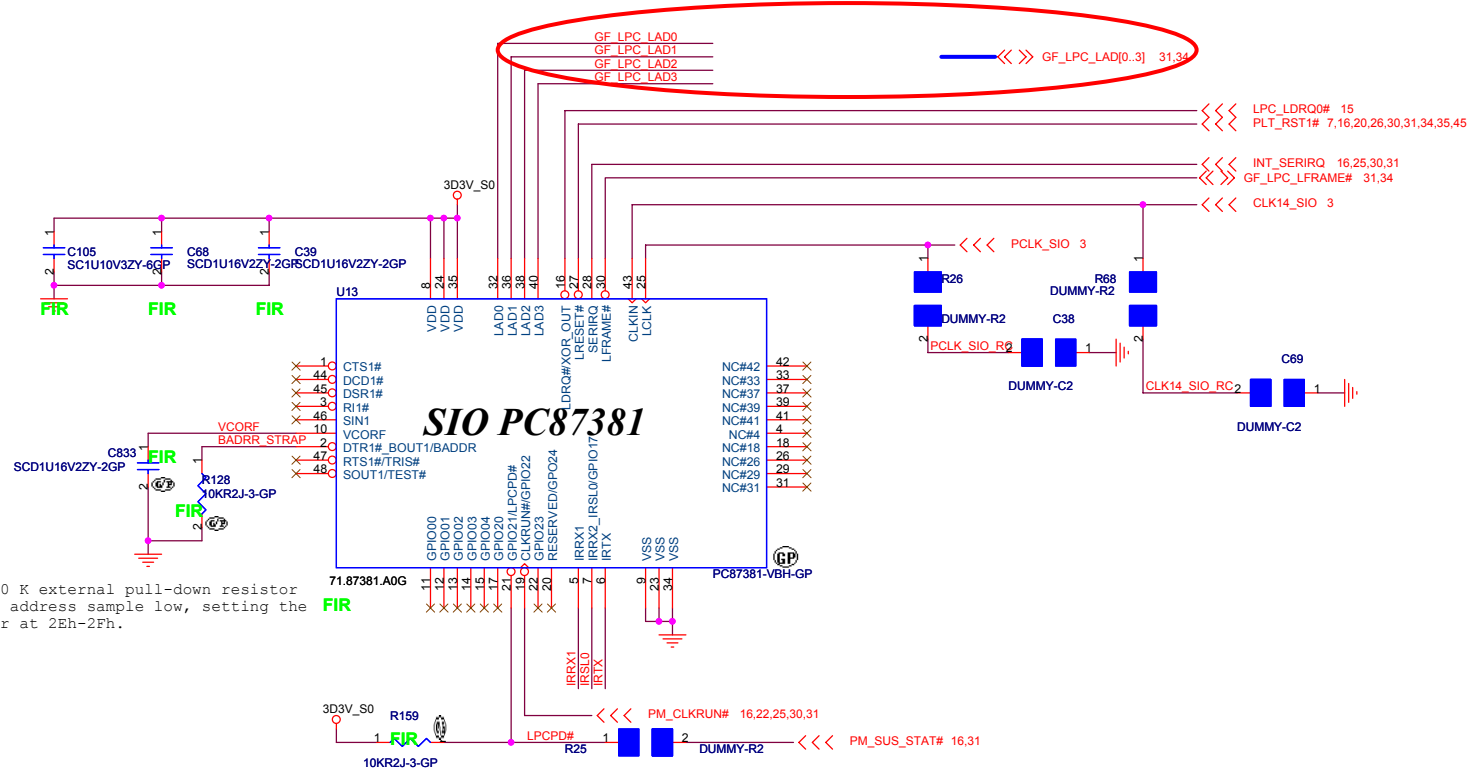
<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **MINI-PCI/NEW Card**

Size A3	Document Number	Rev
	AG1	-1

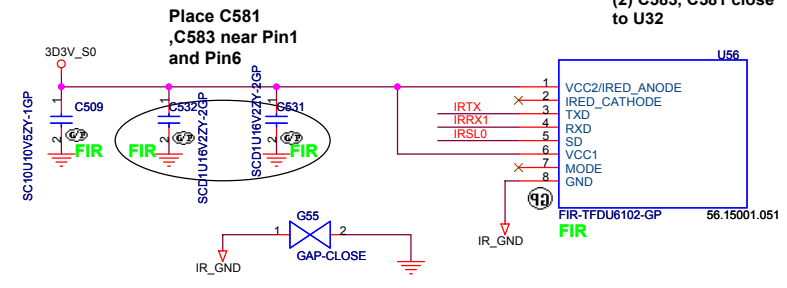
Date: Tuesday, January 10, 2006 Sheet 30 of 53



Connecting a 10 K external pull-down resistor makes the base address sample low, setting the Index-Data pair at 2Eh-2Fh.

VISHAY FIR/CIR Module

- Layout Guide:
 (1) FIR_3D3V : 30 mils,
 (2) C583, C581 close to U32



<Variant Name>

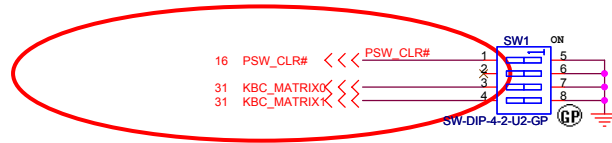
緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **SIO 87381 / FIR**

Size A3	Document Number AG1	Rev -1
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Date: Tuesday, January 10, 2006 Sheet 32 of 53

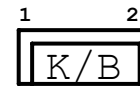
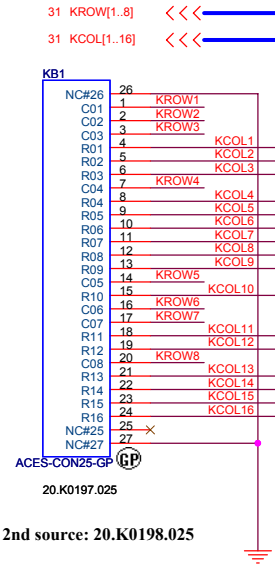
Internal Keyboard Connector



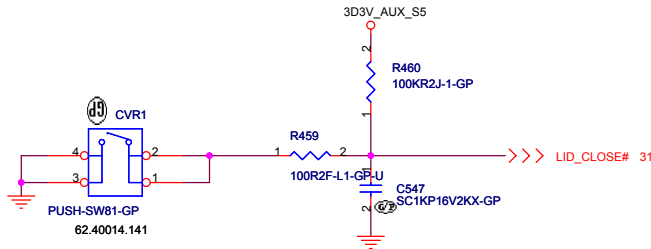
Keyboard matrix (from vendor)

	US	Eur	Jap	Ohter
MATRIXID0#	1	0	1	0
MATRIXID1#	1	1	0	0

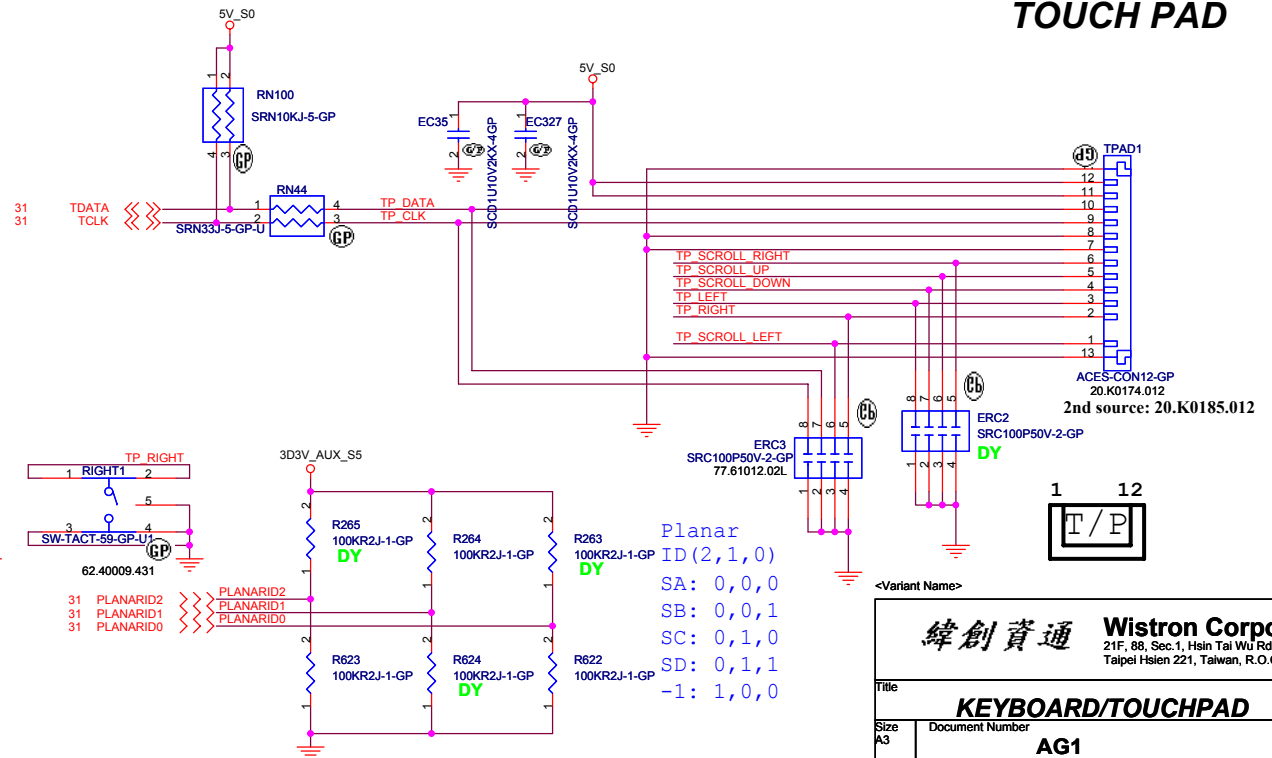
	Low Active
PSW_CLR#	1 - 5 ON
NC	2 - 6 ON
KBC_MATRIX1	3 - 7 ON
KBC_MATRIX2	4 - 8 ON



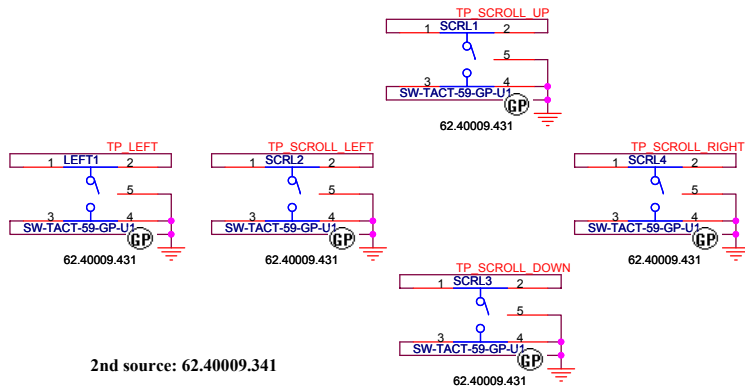
COVER SWITCH



TOUCH PAD



SCROLL KEY



2nd source: 62.40009.341

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **KEYBOARD/TOUCHPAD**

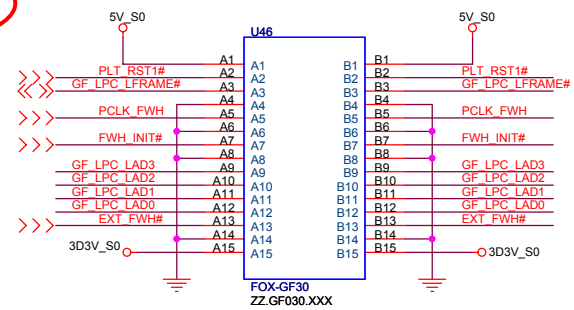
Size A3 Document Number **AG1** Rev **SC**

Date: Tuesday, January 10, 2006 Sheet 33 of 53



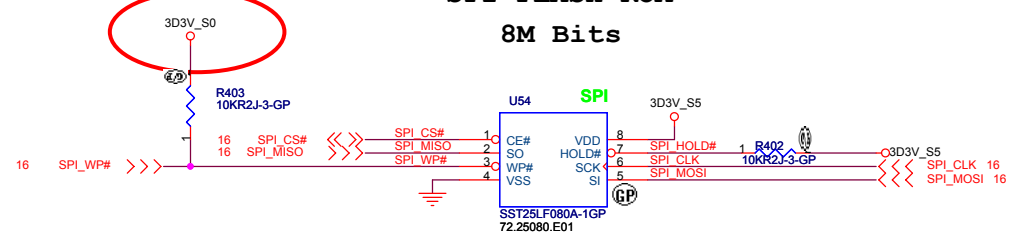
7,16,20,26,30,31,32,35,45 PLT_RST1#
 31,32 GF_LPC_LFRAME#
 3 PCLK_FWH
 15 FWH_INIT#
 16 EXT_FWH#

GOLDEN FINGER FOR DEBUG BOARD



Boot Device must have ID[3:0] = 0000
 Has internal pull-down resistors
 All may be left floated
 FPET7 Elec. P3-46

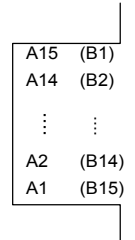
-1 Modify



**SPI FLASH ROM
8M Bits**

SOIC 200 Socket P/N:
Wieson: 62.10076.001
SPI ROM:
SST25LF080A: 72.25080.E01
SST25VF080B : 72.25080.G01
ST M25P80: 72.25P80.001

TOP VIEW



(BOTTOM VIEW)

<Variant Name>

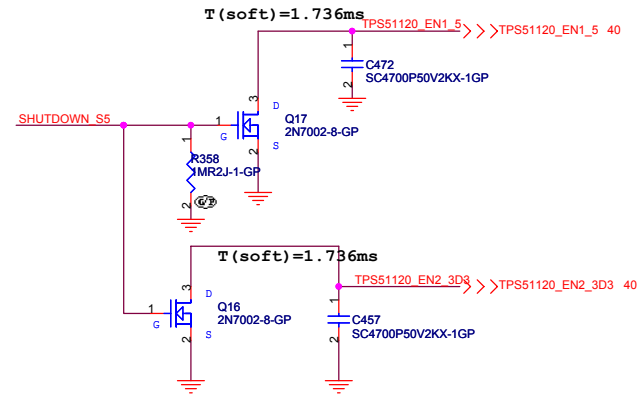
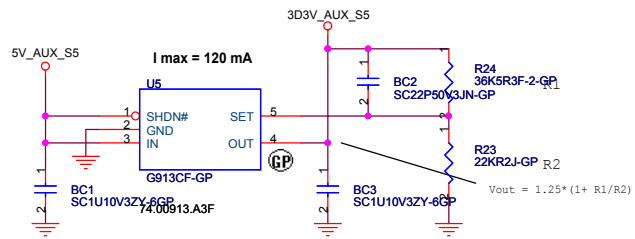
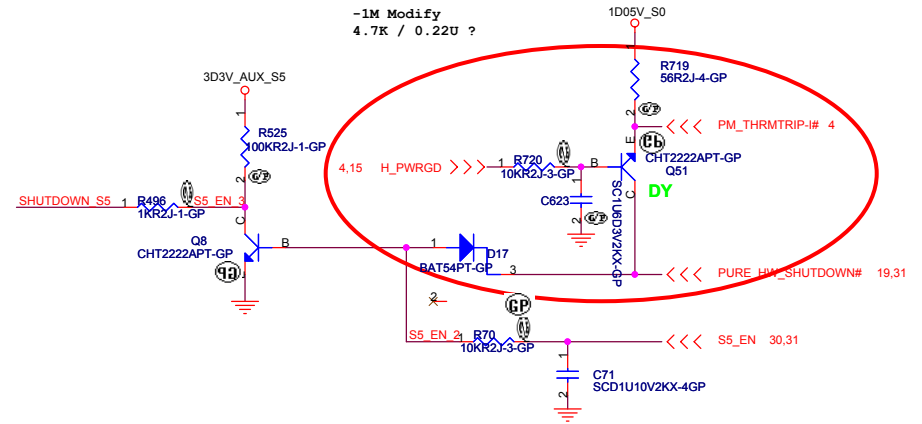
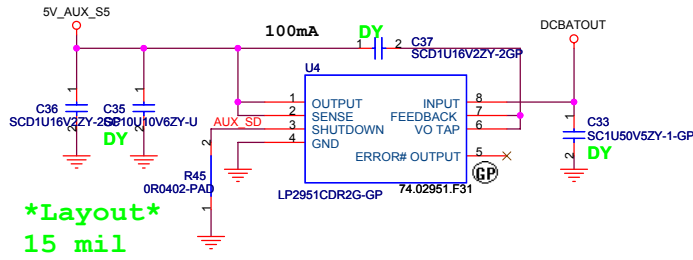
緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **BIOS : SPI**

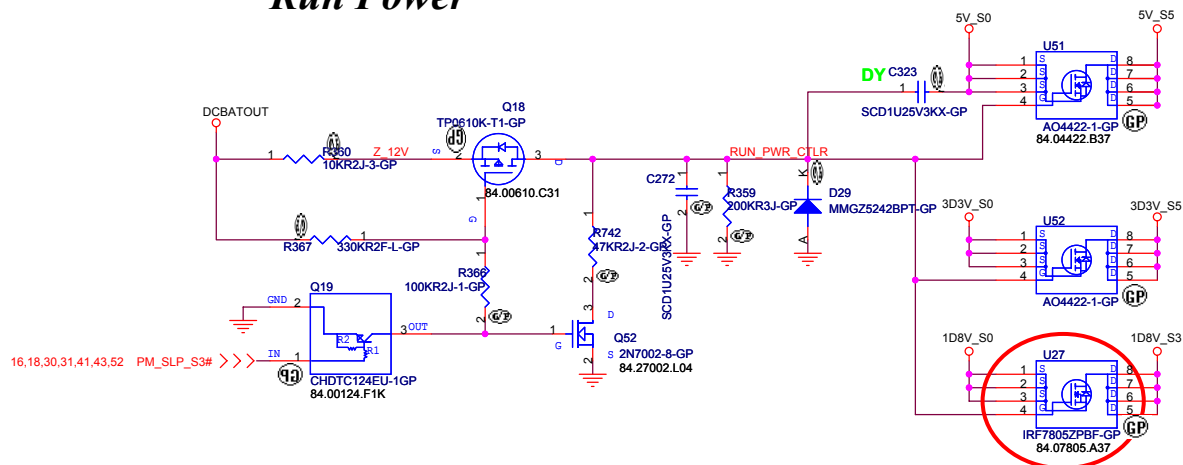
Size: A3 Document Number: **AG1** Rev: **-1**

Date: Tuesday, January 10, 2006 Sheet 34 of 53

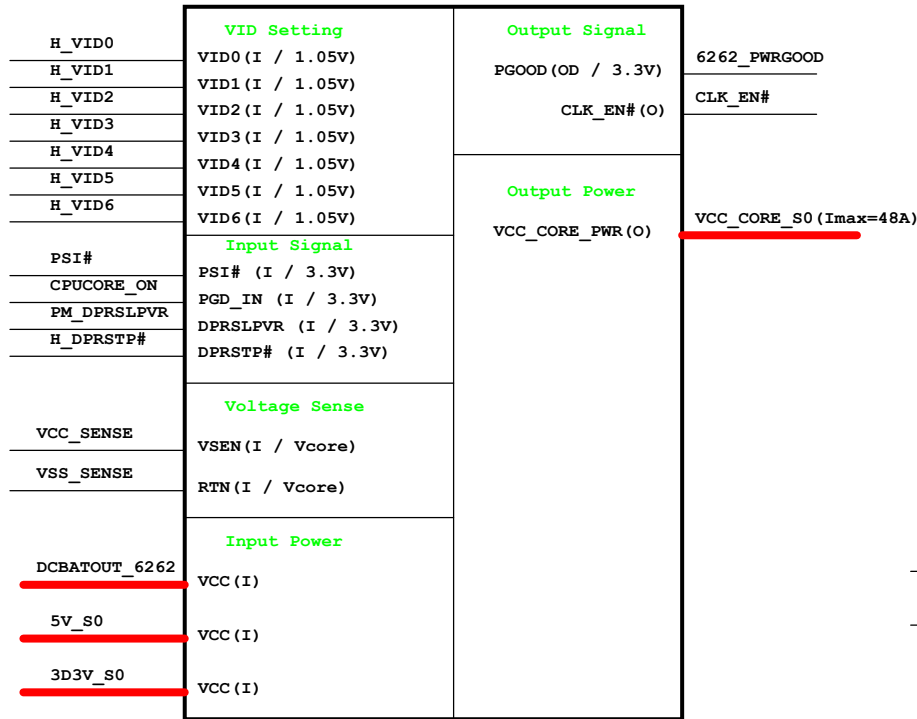
Aux Power



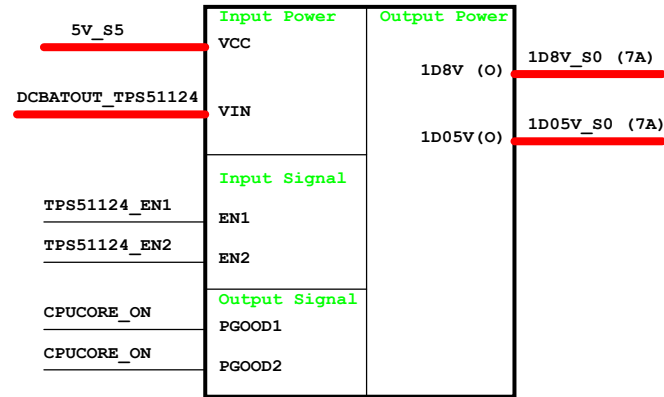
Run Power



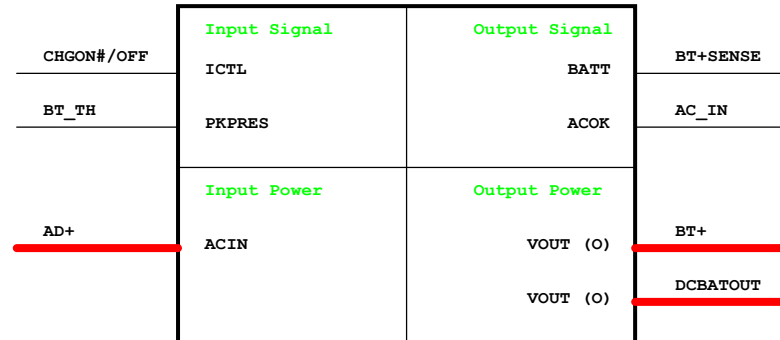
CPU_CORE
Intersil ISL6262



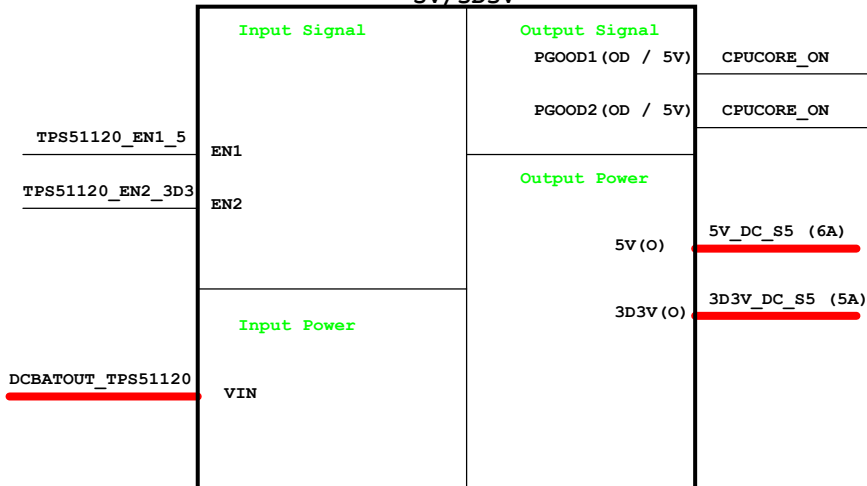
TPS51124
1D8V/1D05V



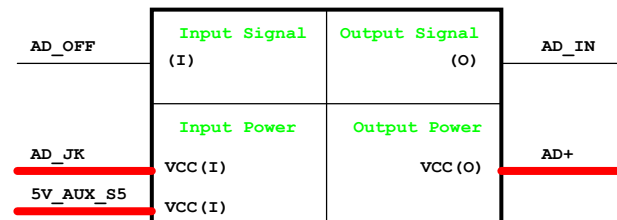
Charger Max8725



TPS51120
5V/3D3V



Adapter

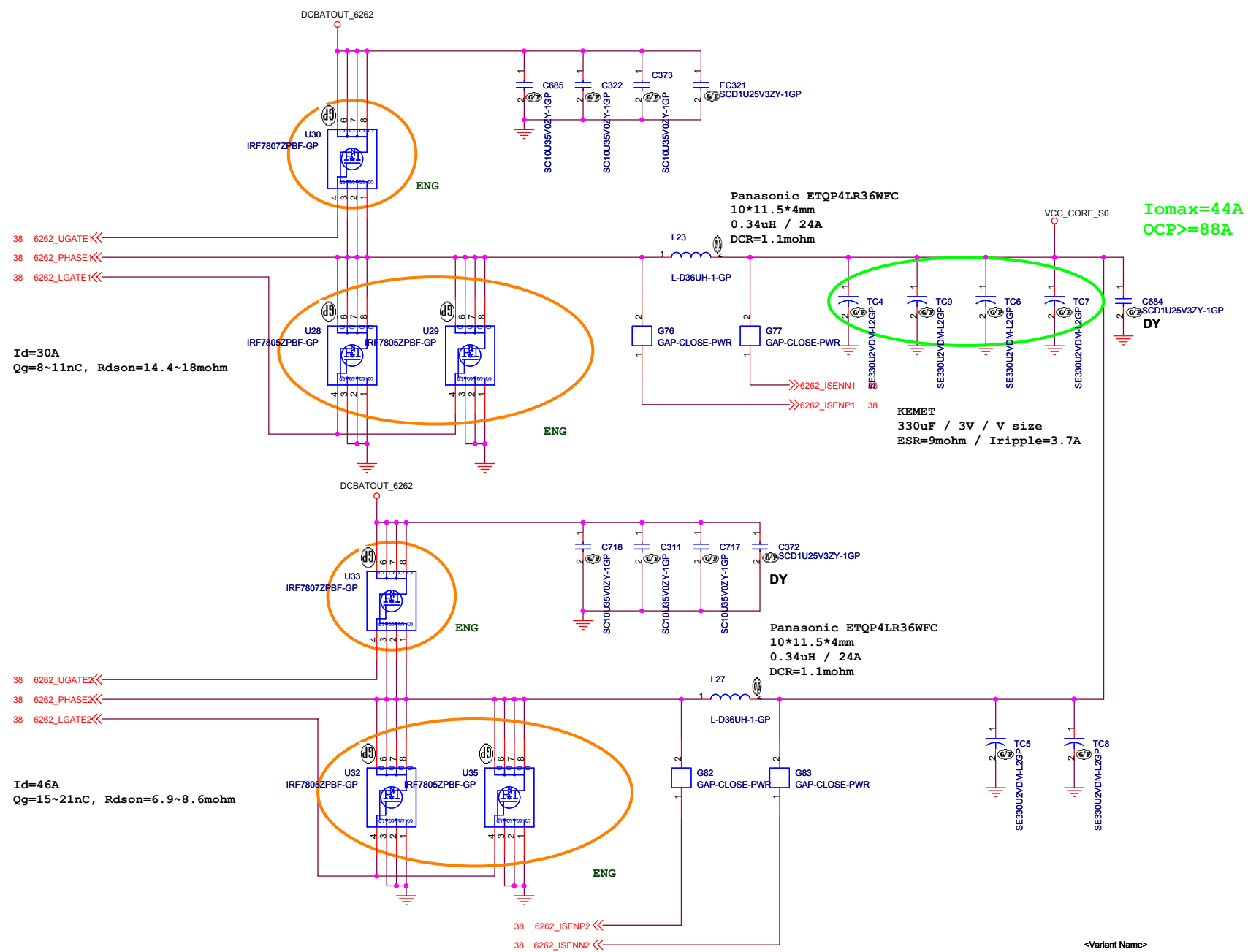


<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **Power Block Diagram**

Size: A3	Document Number: AG1	Rev: SA
Date: Tuesday, January 10, 2006 Sheet 37 of 53		



I_{max}=44A
OCP>=88A

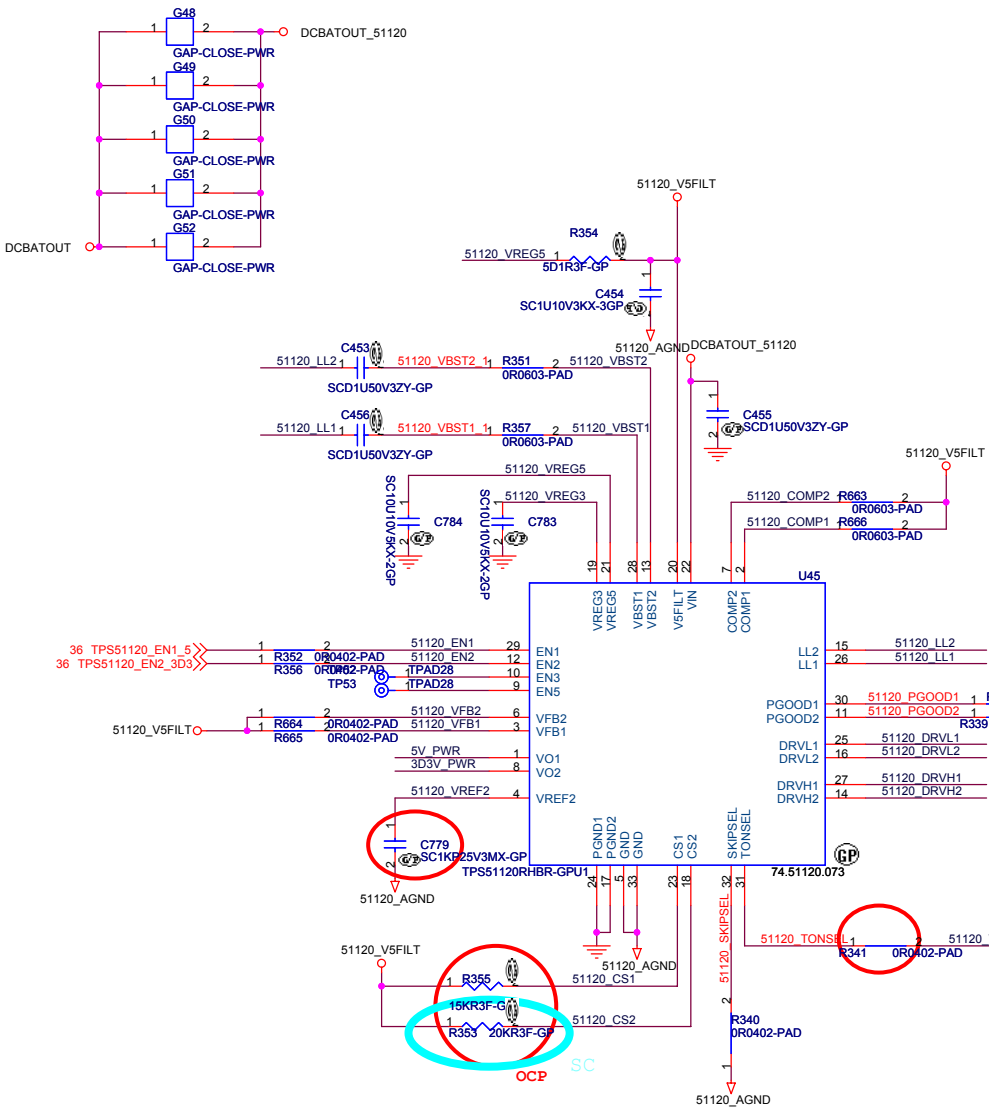
<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title
CPU Vcore Power_2

Size A3	Document Number AG1	Rev SD
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Date: Tuesday, January 10, 2006 Sheet 39 of 53

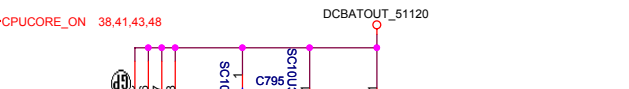
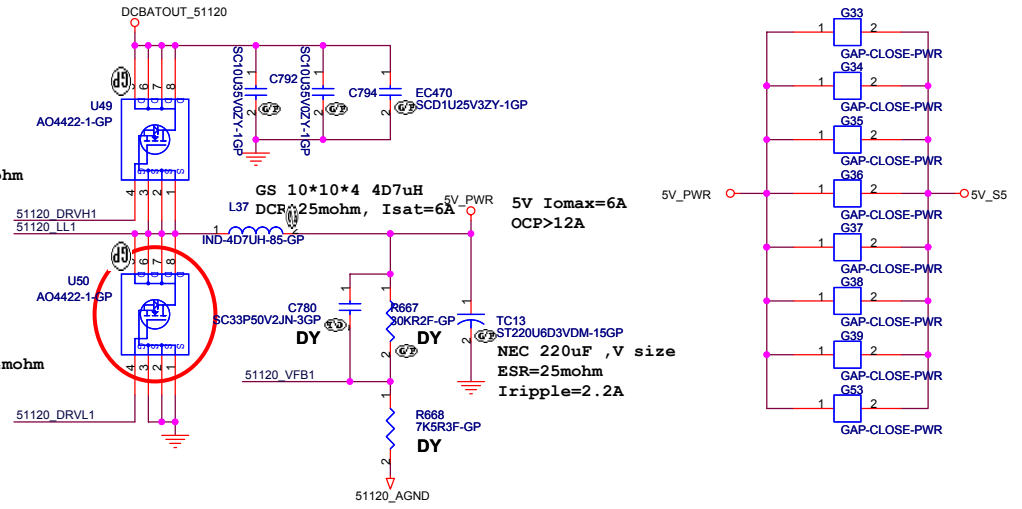


I_{omax}=11A
Q_g=9.8nC,
R_{ds(on)}=20~25mohm

I_{omax}=11A
Q_g=9.8nC,
R_{ds(on)}=19.6~24mohm

I_{omax}=11A
Q_g=9.8nC,
R_{ds(on)}=20~25mohm

I_{omax}=11A
Q_g=9.8nC,
R_{ds(on)}=19.6~24mohm



$$V_{out} = 1V * (R1 + R2) / R2$$

For TPS51120,
V_{out}=5V

- If you use a 6.8uH inductor, the minimum ESR is 70m ohm.
- If you use a 4.7uH inductor, the minimum ESR is 48m ohm.
- If you use a 3.3uH inductor, the minimum ESR is 34m ohm.

V_{out}=3.3V

- If you use a 4.7uH inductor, the minimum ESR is 51m ohm.
- If you use a 3.3uH inductor, the minimum ESR is 36m ohm.
- If you use a 2.5uH inductor, the minimum ESR is 27m ohm.

	GND	VREF2	FLOAT	V5FILT
SKIPSEL	AUTOSKIP	AUTOSKIP / FAULTS OFF	PWM	PWM
COMP	N/A	N/A	CURRENT MODE	D-Cap MODE
TONSEL	380k/CH1 590k/CH2	290k/CH1 440k/CH2	220k/CH1 330k/CH2	180k/CH1 280k/CH2
VFB1	N/A	not use	ADJ.	5V Fixed Output
VFB2	N/A	not use	ADJ.	3.3V Fixed Output
EN1, EN2	switcher OFF	not use	Switchchr ON	Switcher ON
EN3, EN5	LDO OFF	not use	LDO ON	VREG3 on

<Variant Name>

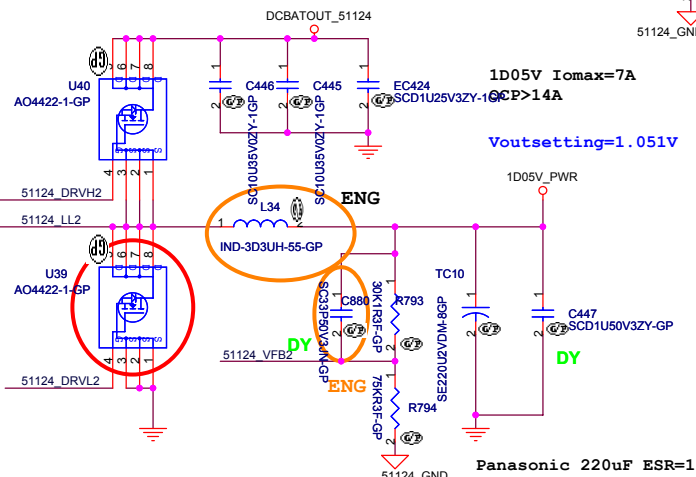
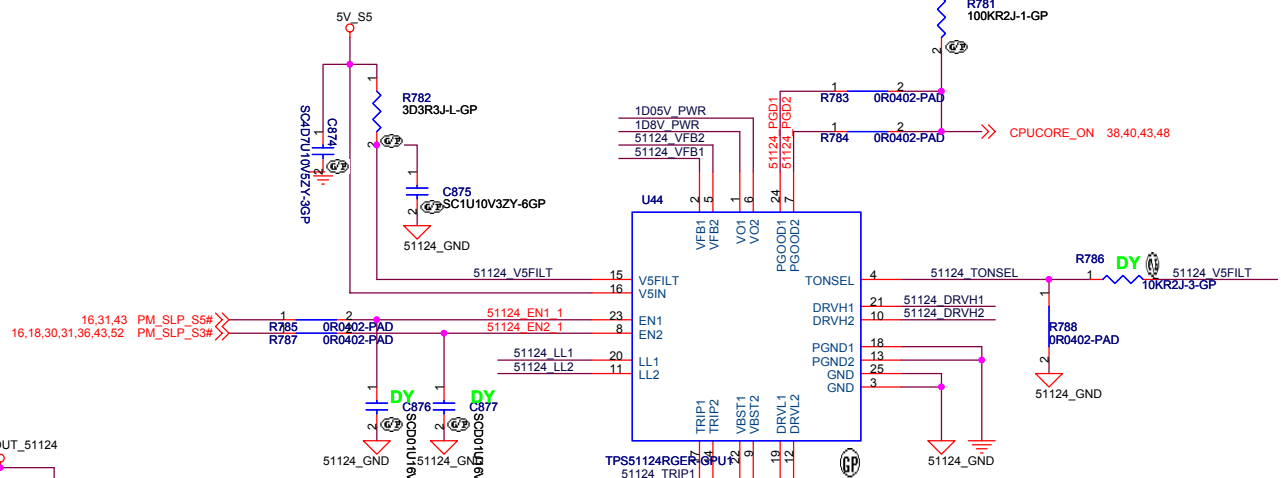
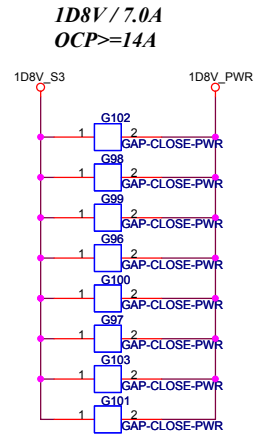
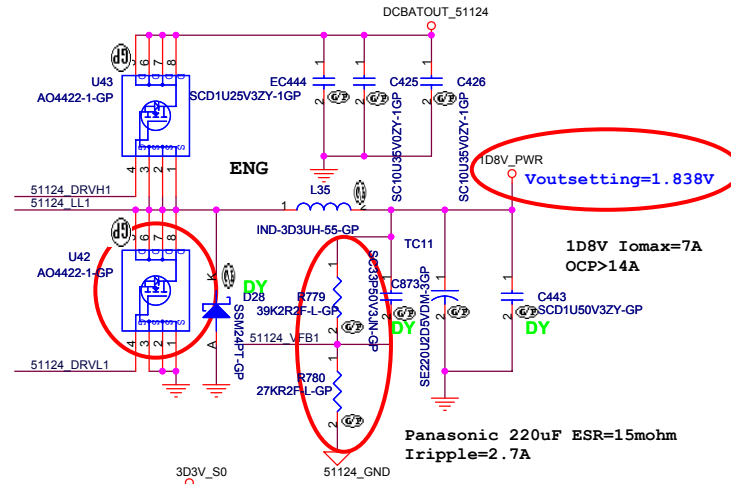
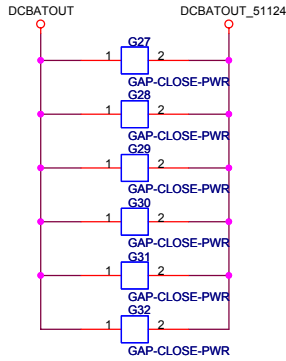
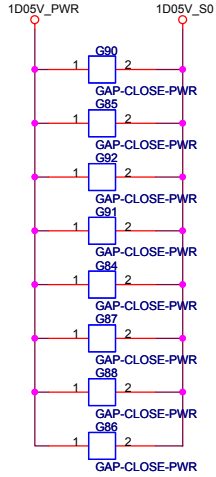
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **5V_UP_S5/3D3V_S5/5V_S5**

Size: A3 Document Number: **AG1** Rev: -1

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1D05V_S0/7A
OCP>=14A



$V_{out} = 0.75V * (R1 + R2) / R2$

$V_{trip} (mV) = R_{trip} (Kohm) * 10 (uA)$
 $I_{ocp} = (V_{trip} / R_{dson}) + ((1 / (2 * L * f)) * ((V_{in} - V_{out}) * V_{out}) / V_{in})$

	GND	OPEN	V5FILT
TONSEL	230k/CH1 283k/CH2	283k/CH1 346k/CH2	346k/CH1 423k/CH2

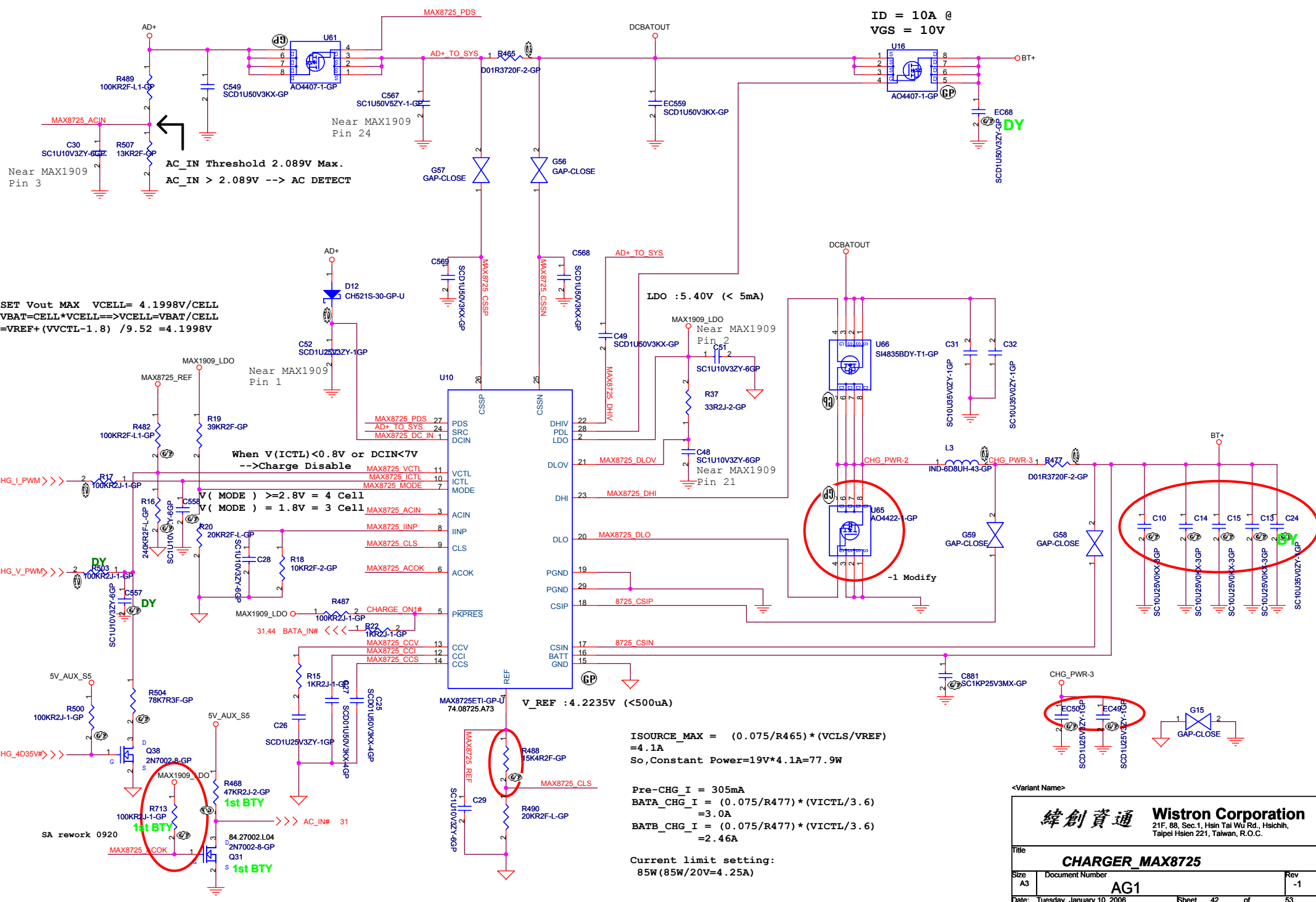
<Variant Name>

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **TPS51124 1D8V_S3/1D05V_S0**

Size A3 Document Number **AG1** Rev -1

Date: Tuesday, January 10, 2006 Sheet 41 of 53



ID = 10A @
VGS = 10V

AC_IN Threshold 2.089V Max.
AC_IN > 2.089V --> AC DETECT

SET Vout MAX VCELL= 4.1998V/CELL
VBAT=CELL*VCELL==>VCELL=VBAT/CELL
=VREF+(VICTL-1.8) /9.52 =4.1998V

When V(ICTL)<0.8V or DCIN<7V
-->Charge Disable

V(MODE) >=2.8V = 4 Cell
V(MODE) = 1.8V = 3 Cell

V_REF : 4.2235V (<500uA)

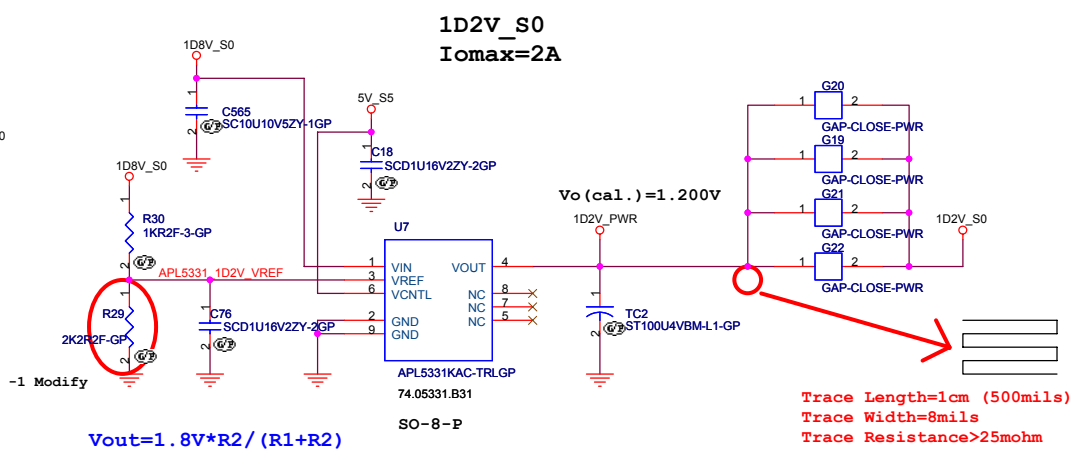
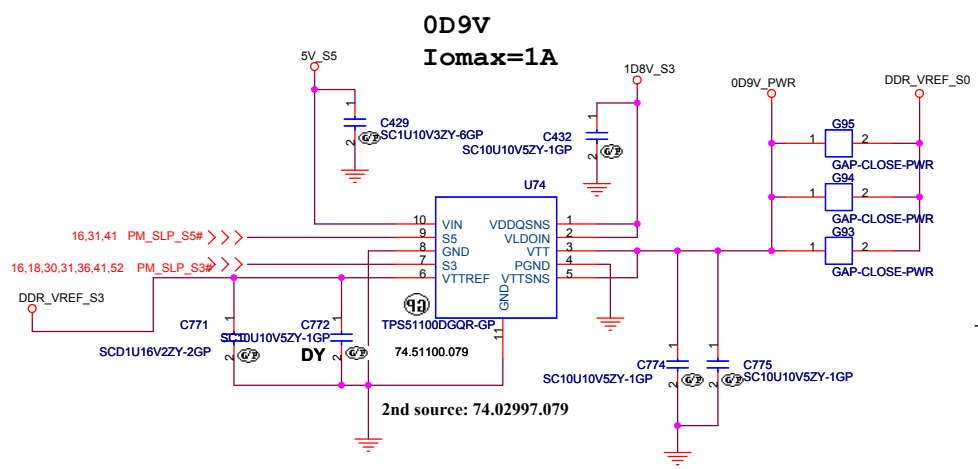
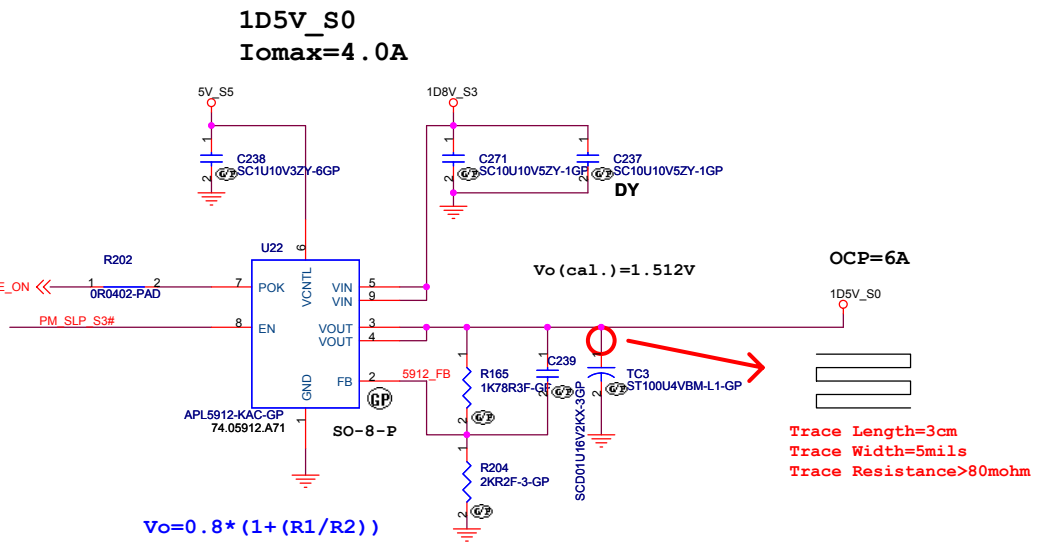
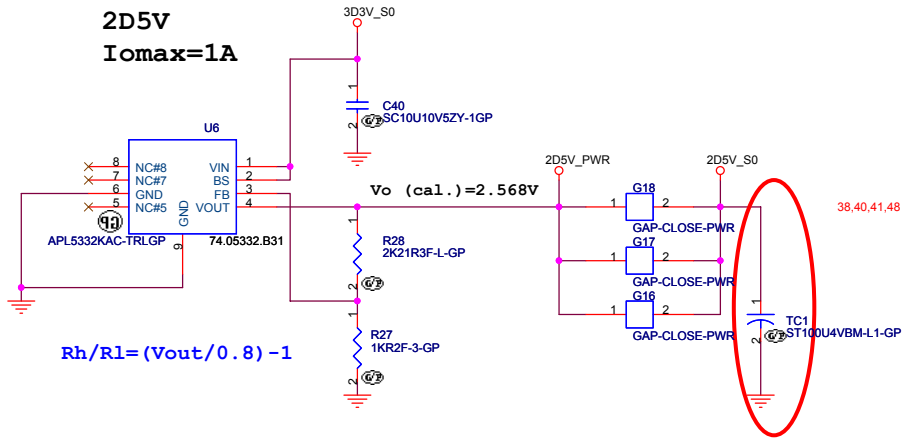
ISOURCE_MAX = (0.075/R465) * (VCLS/VREF)
= 4.1A
So, Constant Power=19V*4.1A=77.9W

Pre-CHG I = 305mA
BATA_CHG_I = (0.075/R477) * (VICTL/3.6)
= 3.0A
BATB_CHG_I = (0.075/R477) * (VICTL/3.6)
= 2.46A

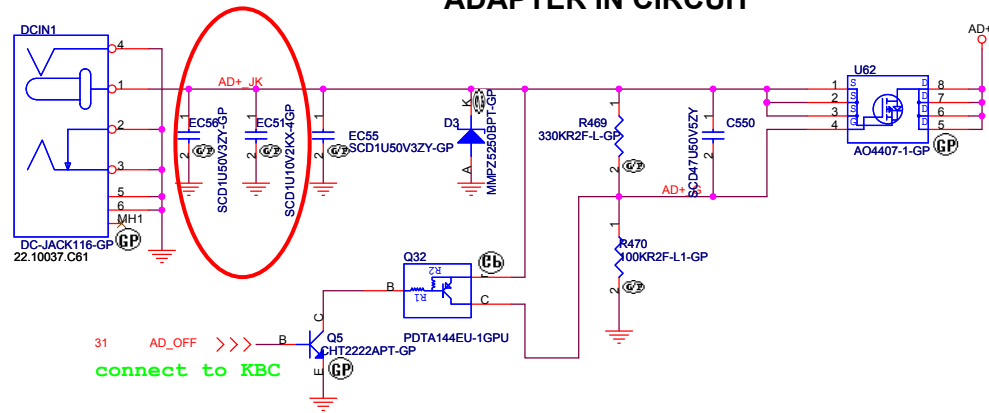
Current limit setting:
85W (85W/20V=4.25A)

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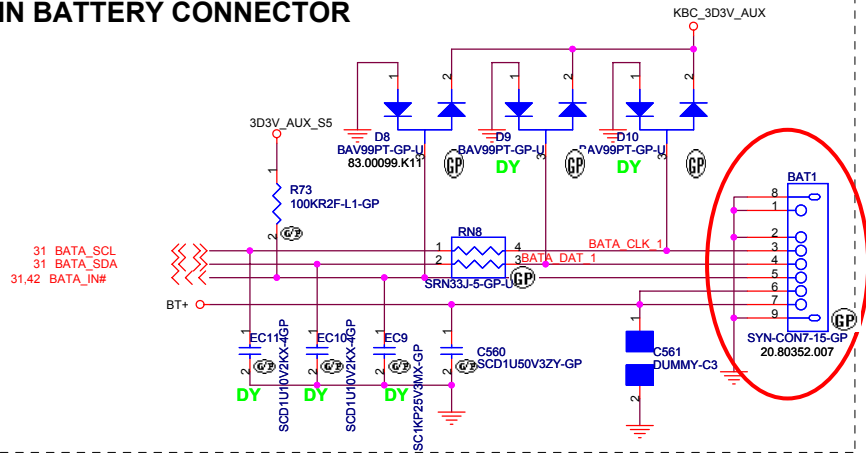
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Title CHARGER_MAX8725	
Size A3	Document Number AG1
Date: Tuesday, January 10, 2006	Sheet 42 of 53
Rev -1	



ADAPTER IN CIRCUIT



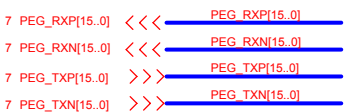
MAIN BATTERY CONNECTOR



Title		
AD/BATT CONN		
Size	Document Number	Rev
A3	AG1	-1
Date: Tuesday, January 10, 2006		
Sheet	44	of 53

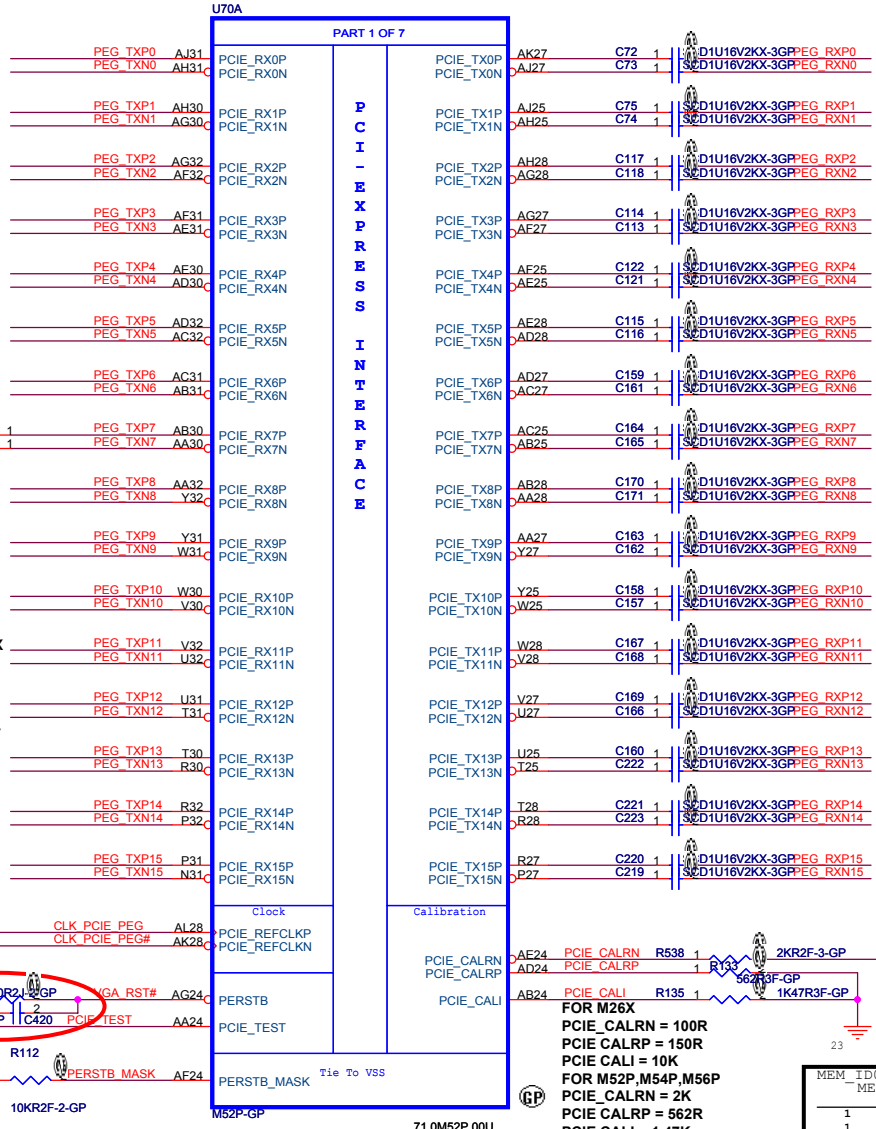
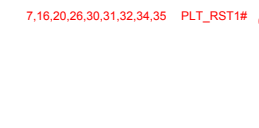
緯創資通 Wistron Corporation
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PCIE TEST PADS
PCIE TEST POINTS MUST BE WITHIN 250 MILS OF THE ASIC BALL WITH POSITIVE AND NEGATIVE SIGNALS THE SAME DISTANCE



PCIE SIGNALS CONNECT TO ROOT COMPLEX

REFER TO PCI EXPRESS DESIGN GUIDE FOR RECOMMENDED AC COUPLING CAPS PLACEMENT ALONG THE TX INTERCONNECT



M54P: 71.0M54P.A0U
M56P: 71.0M56P.B0U

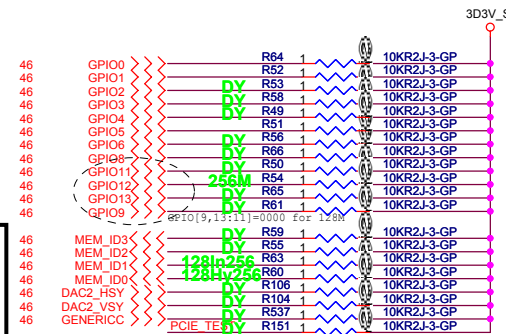
VGA THERMAL SENSOR



Place near GPU

IT IS REQUIRED TO DESIGN IN A THERMAL SENSOR TO FACILITATE THERMAL EVALUATION AND TO PROTECT THE ASIC

STRAPS	PIN	DESCRIPTION OF RECOMMENDED SETTING	RECOMMENDED
STRAP_B_PTX_PWRS_ENB	GPIO0	TRANSMITTER POWER SAVINGS ENABLE - FULL TX OUTPUT SWING	INSTALL 10K RESISTOR
STRAP_B_PTX_DEEMPH_EN	GPIO1	TRANSMITTER DE-EMPHASIS ENABLE DEPENDS ON PCIE CHIPSET BEING USED FOR M26X.M5X INSTALL WITH ATI RS480,RS400,RX480, RC410,RS482 CHIPSETS FOR M26X ONLY DO NOT INSTALL WITH INTEL 915PM CHIPSET	TBD
RSVD	GPIO(3,2)	NO ATI FEATURE ENABLED	DO NOT INSTALL 10K RESISTORS
REVERSE LANES DEBUG ACCESS	GPIO4	NO REVERSED LANE (M26X) NO DEBUG ACCESS (M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTOR
STRAP_FORCE_COMPLIANCE sets the desired PCIE PLL bandwidth for M5x parts.	GPIO5	DO NOT FORCE COMPLIANCE STATE QUICKLY (M26X) NO ATI FEATURE ENABLED (M52P,M54P,M56P)	INSTALL 10K RESISTORS
COMMON MODE RANGE RSVD	GPIO6	NORMAL RANGE (M26X) NO ATI FEATURE ENABLED (M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTORS
DEBUG ACCESS FORCE_COMPLIANCE	GPIO8	NO DEBUG ACCESS (M26X) DON'T FORCE COMPLIANCE STATE(M52P,M54P,M56P)	DO NOT INSTALL 10K RESISTORS
ROMIDCFG(3:0)	GPIO[9,13:11]	SERIAL FLASH ROM TYPE (M26X,M52P,M54P,M56P) - SERIAL M25P10 ROM	1011
MEMORY APERTURE SIZE	GPIO[13:11]	IF NO ROM GPIO11(M26X) AND GPIO12,13(M52,M54,M56) SET MEMORY APERTURE SIZE SEE M26X,M54X,M56X DATA BOOK FOR MEMORY FRAME BUFFER APERTURE SETTINGS	TBD
MEM_TYPE	MEMID (3:0)	MEMORY TYPE AND SPEED SELECT	TBD
RSVD NO STRAP FUNCTION	H2SYNC V2SYNC GENERICC	ATI FEATURE NOT ENABLED (M52P,M54P,M56P) NO STRAP (M26X)	DO NOT INSTALL 10K RESISTORS
RSVD NO STRAP FUNCTION	PCIE_TEST	ATI FEATURE NOT ENABLED (M52P,M54P,M56P) NO STRAP (M26X)	



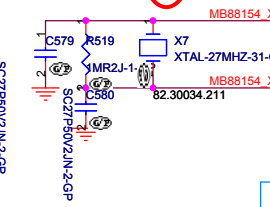
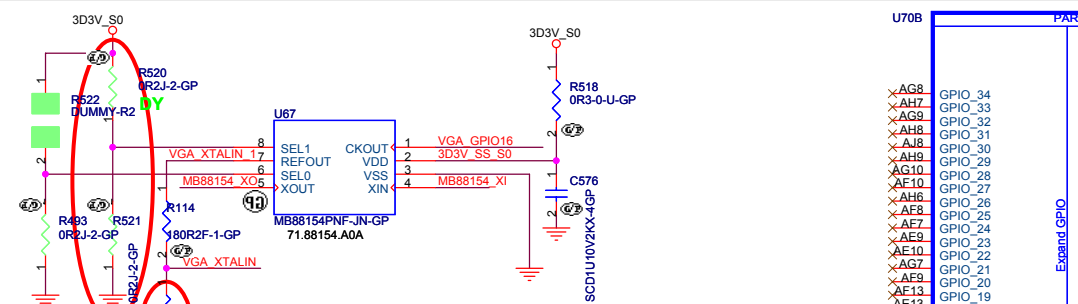
MEM_ID0	MEM_ID2	MEM_ID1	MEM_ID3	MEM	SIZE	VENDOR	CHIPS
1	0	1	0	64M	16M*16	Infineon	x2
1	1	1	0	64M	16M*16	Hynix	x2
0	1	1	0	128M	16M*16	Samsung	x4
0	0	1	0	256M	32M*16	Samsung	x4
0	1	0	0	128M	16M*16	Infineon	x4
0	1	0	0	256M	32M*16	Infineon	x4
1	1	0	0	128M	16M*16	Hynix	x4
1	0	0	0	128M	16M*16	Hynix	x4
0	0	0	0	256M	32M*16	Hynix	x4

When no ROM is attached, GPIO[9] is set to 0.
 GPIO[13:12] is used to select the frame buffer aperture size.
 GPIO[13:12] = 00: 128M frame buffer, same as ROM strap 00
 GPIO[13:12] = 01: 256M frame buffer, same as ROM strap 01
 GPIO[13:12] = 10: 64M frame buffer, same as ROM strap 10
 GPIO[13:12] = 11: reserved, same as ROM strap 11

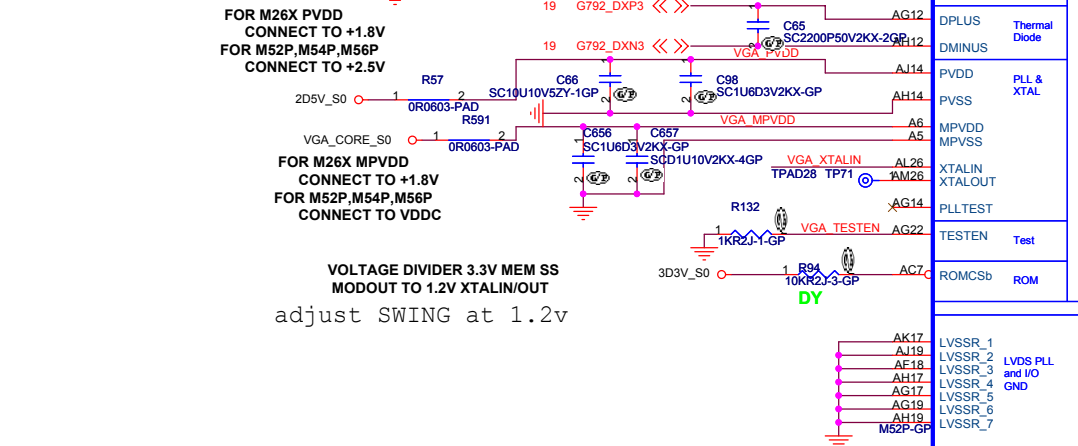
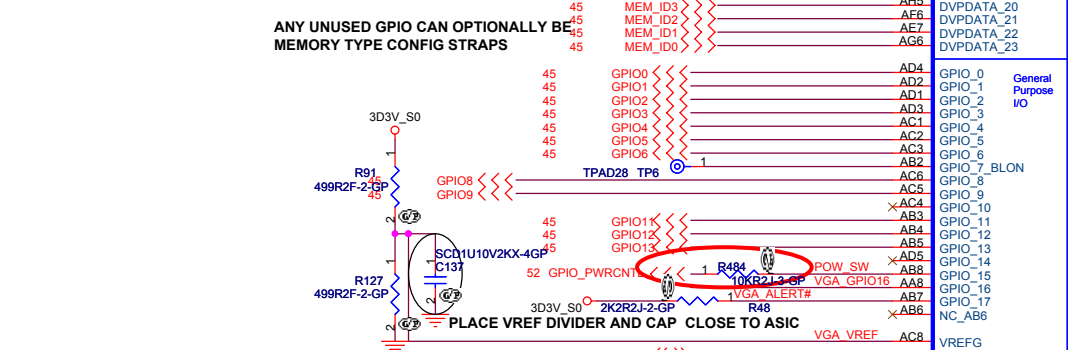
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ATI M5X-P PCIE 1/4

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 Date: Tuesday, January 10, 2006 Sheet 45 of 53



Modulation Rate		
SEL1	SEL0	Center Spread
L	L	+/- 0.5%
L	H	+/- 1.0%
H	L	+/- 1.5%
H	H	No Spread



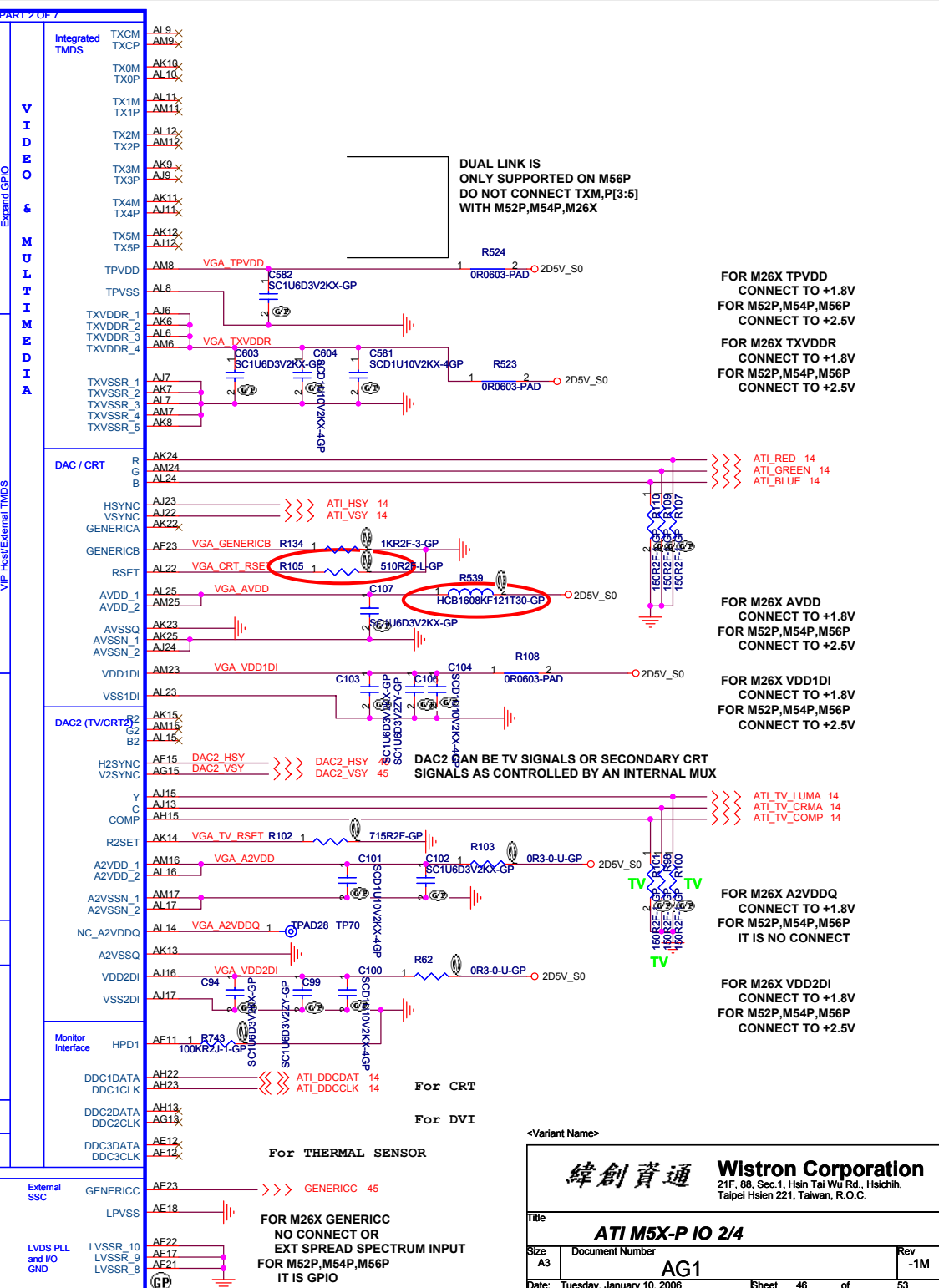
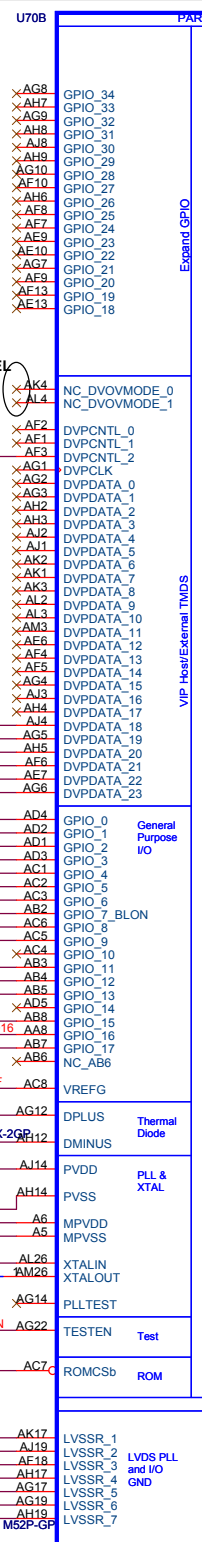
VOLTAGE DIVIDER 3.3V MEM SS
MODOUT TO 1.2V XTALIN/OUT
adjust SWING at 1.2v

DVPCNTL,DVpdata[23..0] ARE CONFIGURED FOR +3.3V SIGNALING MODE ON THIS DESIGN
FOR M26X CONNECT TO +1.8V OR VSS TO DEFINE DVO SIGNAL LEVEL
FOR M52P,M54P,M56P NOT CONNECTED

ANY UNUSED GPIO CAN OPTIONALLY BE PANEL TYPE CONFIG STRAPS

ANY UNUSED GPIO CAN OPTIONALLY BE MEMORY TYPE CONFIG STRAPS

PLACE VREF DIVIDER AND CAP CLOSE TO ASIC



DUAL LINK IS ONLY SUPPORTED ON M56P DO NOT CONNECT TXM,P[3:5] WITH M52P,M54P,M26X

FOR M26X TPVDD CONNECT TO +1.8V
FOR M52P,M54P,M56P CONNECT TO +2.5V
FOR M26X TXVDDR CONNECT TO +1.8V
FOR M52P,M54P,M56P CONNECT TO +2.5V

FOR M26X AVDD CONNECT TO +1.8V
FOR M52P,M54P,M56P CONNECT TO +2.5V

FOR M26X VDD1DI CONNECT TO +1.8V
FOR M52P,M54P,M56P CONNECT TO +2.5V

FOR M26X A2VDDQ CONNECT TO +1.8V
FOR M52P,M54P,M56P IT IS NO CONNECT

FOR M26X VDD2DI CONNECT TO +1.8V
FOR M52P,M54P,M56P CONNECT TO +2.5V

FOR THERMAL SENSOR

FOR M26X GENERIC NO CONNECT OR EXT SPREAD SPECTRUM INPUT FOR M52P,M54P,M56P IT IS GPIO

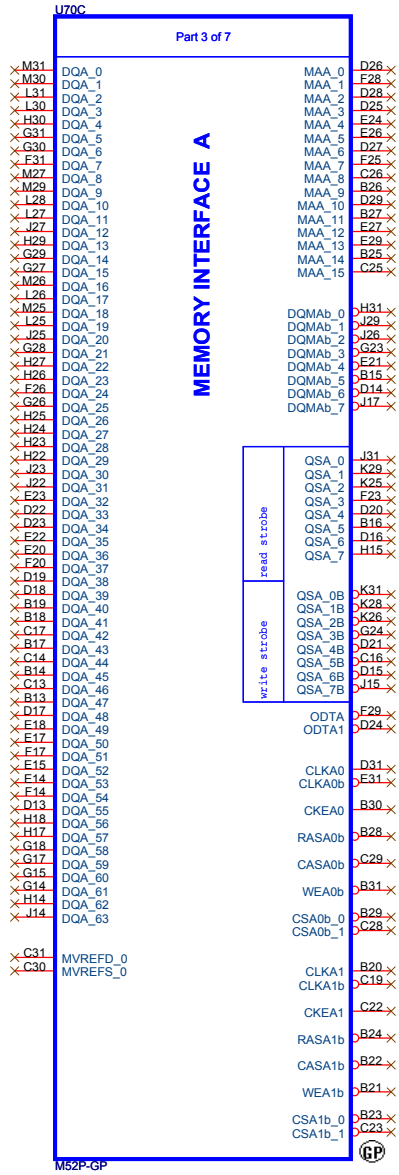
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ATI M5X-P IO 2/4

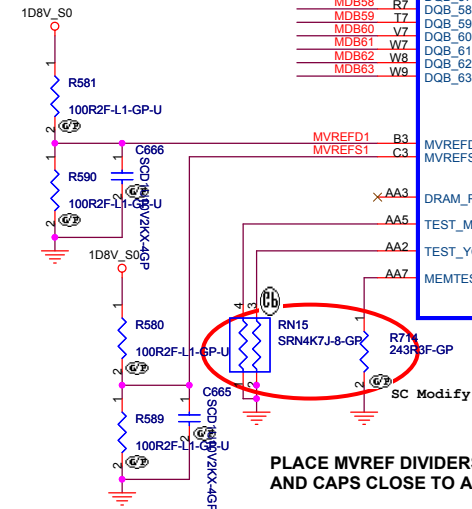
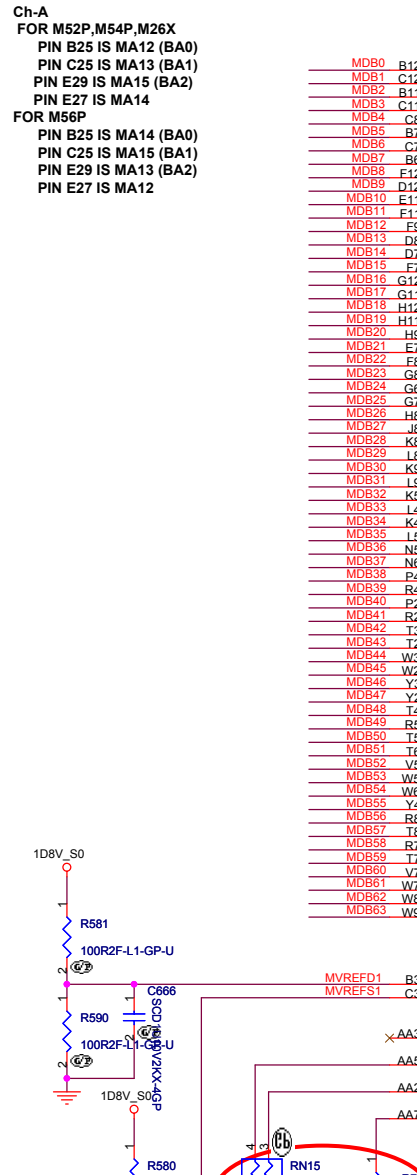
AG1

Rev -1M

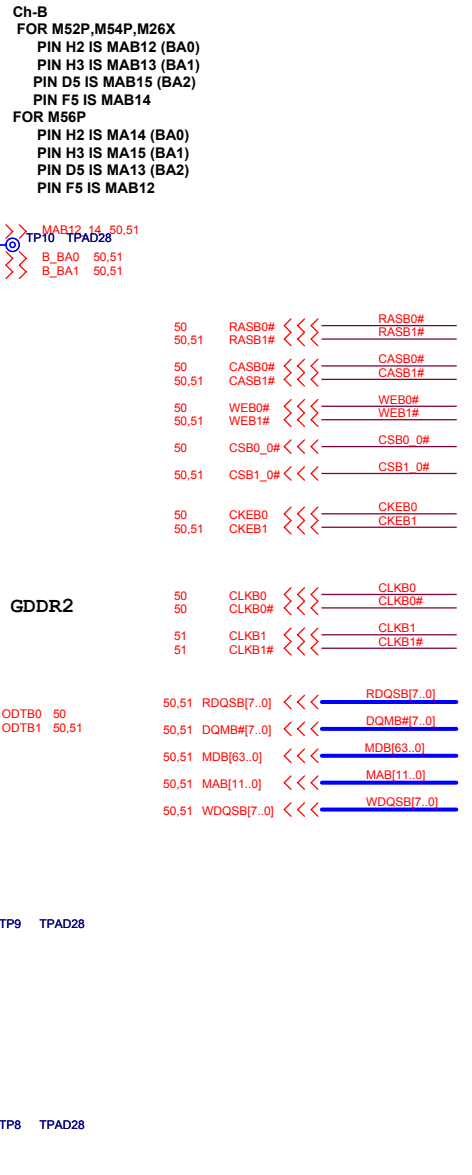
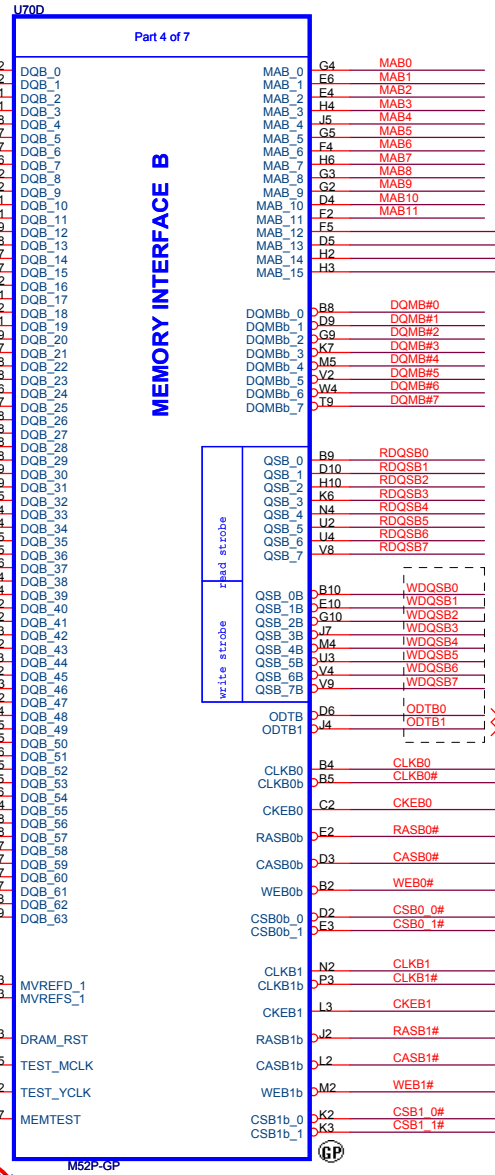
Sheet 46 of 53



PLACE MVREF DIVIDERS AND CAPS CLOSE TO ASIC



PLACE MVREF DIVIDERS AND CAPS CLOSE TO ASIC



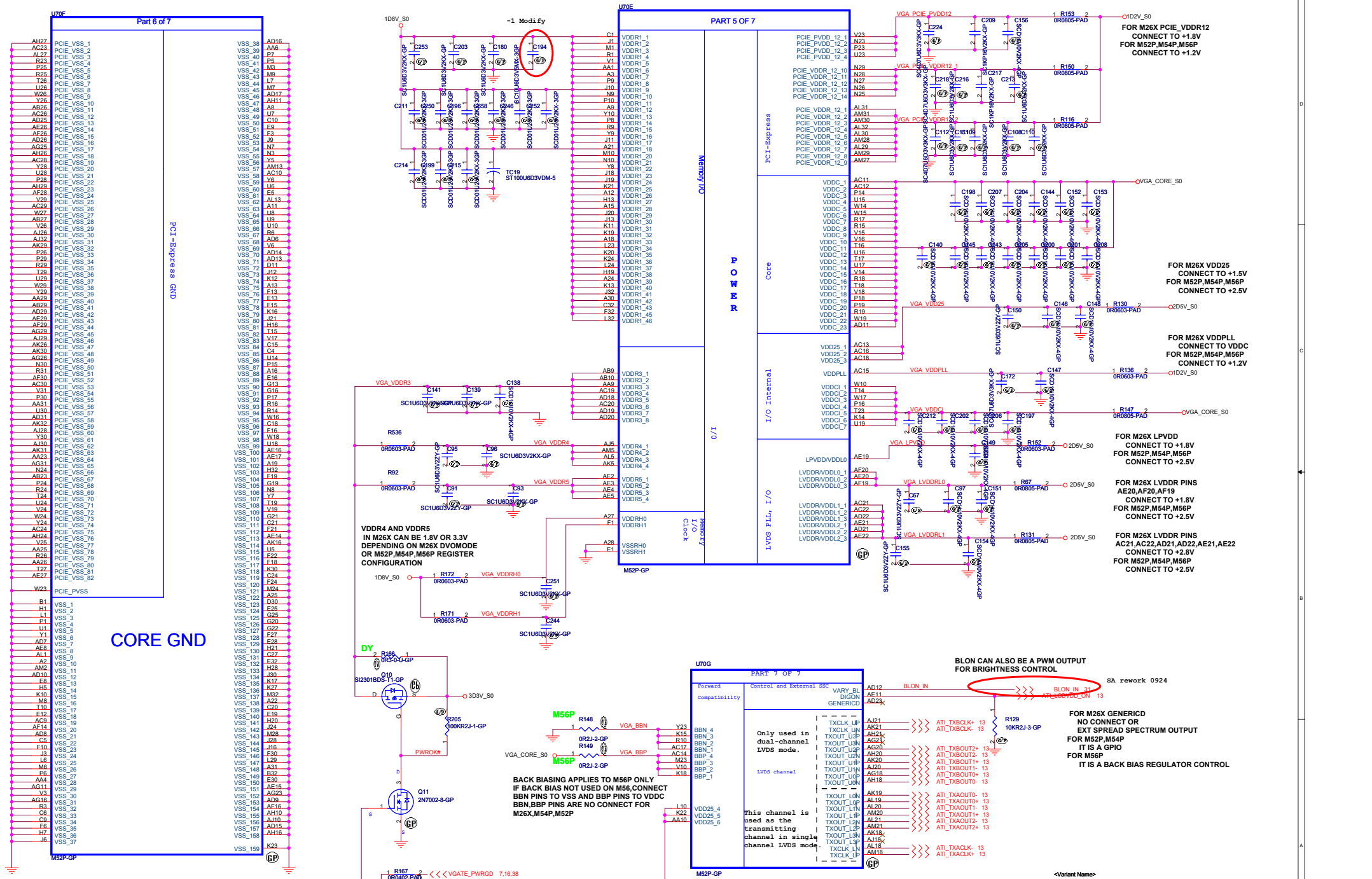
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Title: **ATI M5X-P MEM 3/4**

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Part 6 of 7

PART 5 OF 7

U70G PART 7 OF 7

CORE GND

VDDR4 AND VDDR5
 IN M26X CAN BE 1.8V OR 3.3V
 DEPENDING ON M26X DVOMODE
 OR M52P, M54P, M56P REGISTER
 CONFIGURATION

BACK BIASING APPLIES TO M56P ONLY
 IF BACK BIAS NOT USED ON M56P, CONNECT
 BBN PINS TO VSS AND BBP PINS TO VDDC
 BBN, BBP PINS ARE NO CONNECT FOR
 M26X, M54P, M52P

BLON CAN ALSO BE A PWM OUTPUT
 FOR BRIGHTNESS CONTROL

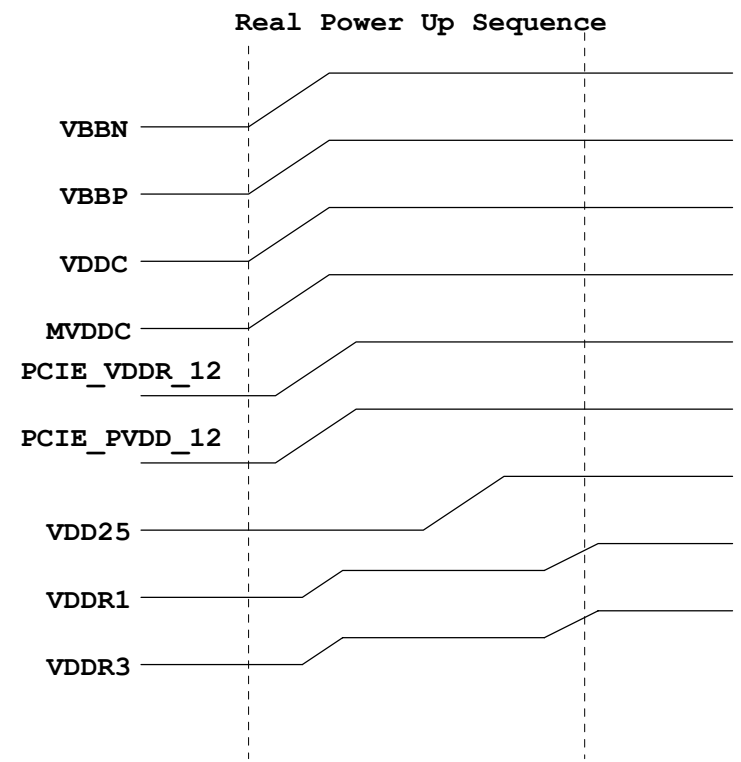
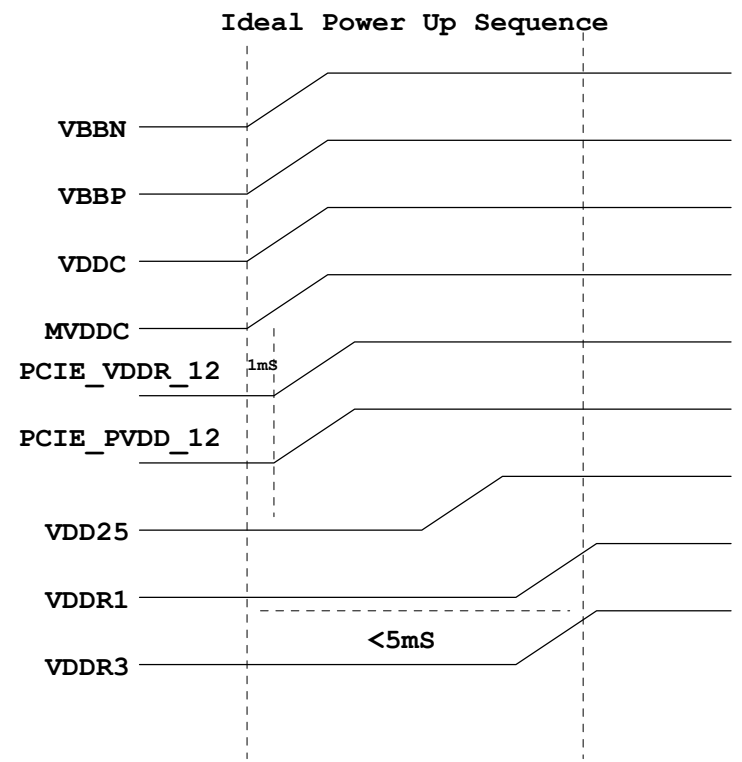
FOR M26X GENERIC
 NO CONNECT OR
 EXT SPREAD SPECTRUM OUTPUT
FOR M52P, M54P
 IT IS A GPIO
FOR M56P
 IT IS A BACK BIAS REGULATOR CONTROL

CONNECT THESE VDD25 PINS TO 2.5V FOR M52P, M54P, M56P
 THESE VDD25 PINS ARE NO CONNECT FOR M26X

SA rework 0924

Forward Compatibility	Control and External SSC	VARY_BL	AD12	BLON_IN	SA rework 0924
		DIGON	AE11	BLON_IN_01	
		GENERIC	AD23x	BLON_IN_02	
BBN_4	TXCLK_LP	AK21	ATI_TBCLK+ 13		
BBN_3	TXCLK_LUN	AK22	ATI_TBCLK- 13		
BBN_2	TXOUT_U0B	AH23			
BBN_1	TXOUT_U0N	AG23			
BBP_4	TXOUT_U0P	AH20	ATI_TBOUT2+ 13		
BBP_3	TXOUT_U0N	AH20	ATI_TBOUT2- 13		
BBP_2	TXOUT_U1P	AK20	ATI_TBOUT1+ 13		
BBP_1	TXOUT_U1N	AK20	ATI_TBOUT1- 13		
	TXOUT_U0P	AG18	ATI_TBOUT0+ 13		
	TXOUT_U0N	AG18	ATI_TBOUT0- 13		
	TXOUT_L0N	AK19	ATI_TXAOUT0- 13		
	TXOUT_L0P	AL15	ATI_TXAOUT0+ 13		
	TXOUT_L1B	AK20	ATI_TXAOUT1- 13		
	TXOUT_L1P	AM20	ATI_TXAOUT1+ 13		
	TXOUT_L2N	AL21	ATI_TXAOUT2- 13		
	TXOUT_L2P	AM21	ATI_TXAOUT2+ 13		
	TXOUT_L3N	AK18	ATI_TXAOUT3- 13		
	TXOUT_L3P	AL18	ATI_TXAOUT3+ 13		
	TXCLK_LP	AK18	ATI_TXACLK- 13		
	TXCLK_LP	AM18	ATI_TXACLK+ 13		

<Variant Name>



RESISTOR

Symbol name	Value	Tolerance (J: 5%, F: 1%, D: 0.5%, B: 0.1%)	Rating 0402=> 1/16W, 25V 0603 => 1/16W, 75V 0805 => 1/10W, 100V	Size 2=>0402, 3=>0603, 5=>0805, 6=>1206, 0=>1210
10KR3	10K Ohm	If no letter, it means J: 5%	1/16W, 75V	0603
33D3R5	33.3 Ohm	If no letter, it means J: 5%	1/10W, 100V	0805
1KR3F	1K Ohm	F: 1%	1/16W, 75V	0603

The naming rule is value + R + size + tolerance
 For the value, it can be read by the number before R. (R means resistor)
 For the tolerance, it can be read from the last letter.
 For the rating, we don't show on the symbol name.
 For the size, R2=>0402, R3=>0603, R5=>0805,.....

General Guidelines:

- BBN and BBP must ramp up before or at the same time as VDDC but not after.
- VDDC and MVDDC must be ramped up first, followed by PCIE_VDDR_12, PCIE_FVDD12, VDD25, VDDR1 and VDDR3 (and other I/O powers).
- All powers must be ramped up within 5ms of each other (from the ramp of VDDC to 90% of VDDR3).
- VDD25 can be ramped with VDDC or VDDR1 but it cannot be ramped later than VDDR1.
- The power down is the opposite of the power on sequence: VDDR3/VDDR1 -> VDD25 ->VDDC/MVDDC/BBN/BBP.

Due to the level shifter design in the memory I/Os, in order to avoid over-stressing the thin oxide transistors when VDDR1 is powered on but VDDC is not, VDDC must ramp up before VDDR1. Similarly, VDDC must ramp up before VDDR3. The level shifter design is a function of the transistor types used in 90nm technology and of the voltage level support. The drawback of ramping up VDDC before the I/O voltages (such as VDDR1 and VDDR3) is that parasitic P/N junctions are forward biased, thus creating a conduction path. These conduction paths will pump up VDDR1 (from the memory I/Os) and VDDR3 (from the GPIOs).

The real power up sequence will appear as follows:
 Figure 2-2. Real Power Up Sequence
 As long as MVDDC ramps up with VDDC, the pump voltage on VDDR1 should be all right since the DRAM spec will not be violated.

CAPACITOR

Symbol name	Value	Tolerance (J: +/-5, K: +/-10, M: +/-20, Z: +80/-20)	Rating (X5R / X7R < 80%, Y5V/Y5U/Z5U < 1/3)	Size 2=>0402, 3=>0603, 5=>0805, 6=>1206, 0=>1210
SCD1U10V2MX-1	0.1uF	M/X5R	10V	0402
SC10U6D3V5MX	10uF	M/X5R	6.3V	0805
SC2D2U16V5ZY	2.2uF	Z/Y5V	16V	0805

The naming rule is
 Capacitor type + value + rating + size + tolerance + material
 SCD1U10V2MX-1
 SC=> SMT Ceramic, TC=> POS cap or SP cap
 D1U => 0.1uF
 10V => the voltage rating is 10V
 2=> 0402, 3=>0603, 5=>0805
 M=>tolerance J, K, M, Z
 X=> X7R/X5R, Y=> Y5V
 -1 => symbol version, nonsense to EE characteristic

<Variant Name>

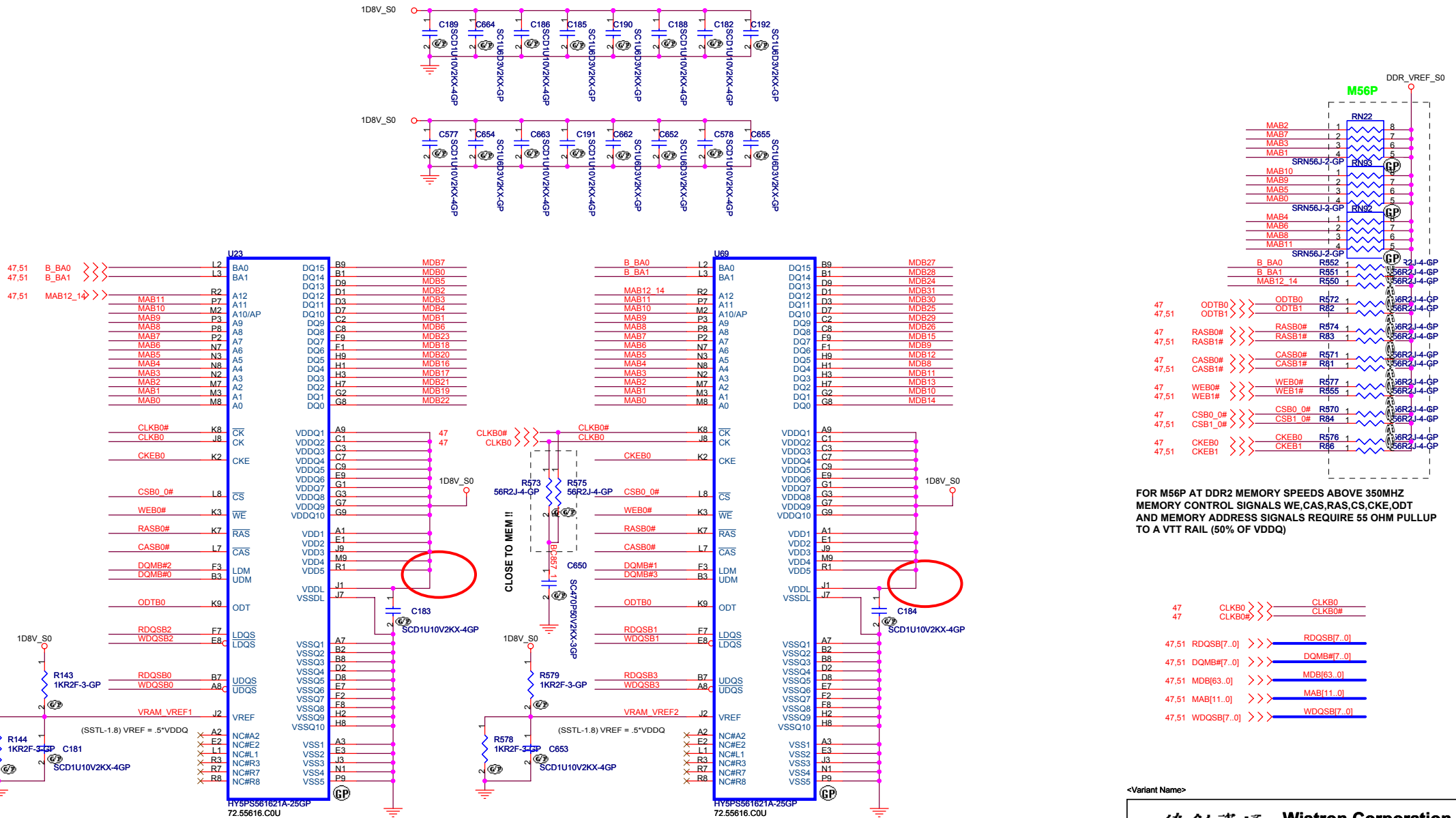
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ATI M5X-P POWER SEQUENCE

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CHAN B DDR2 84BGA 32MX16 MEMORY



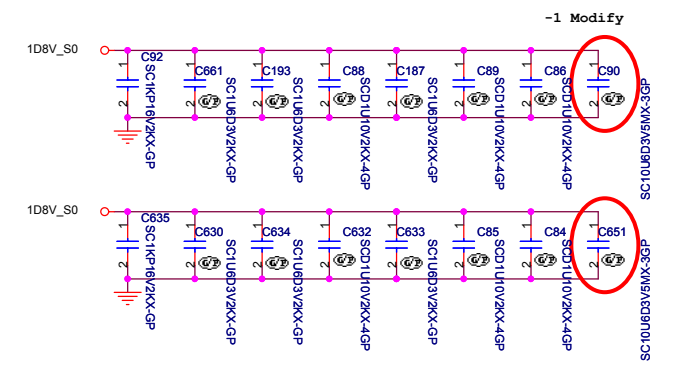
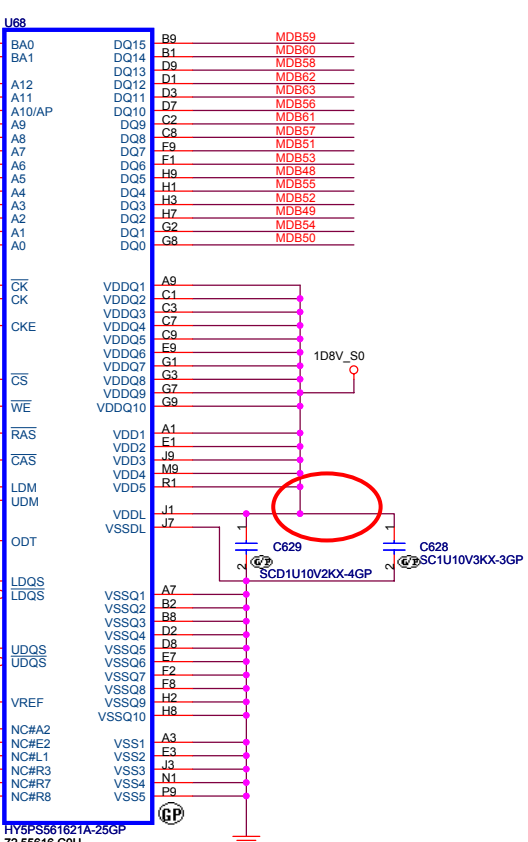
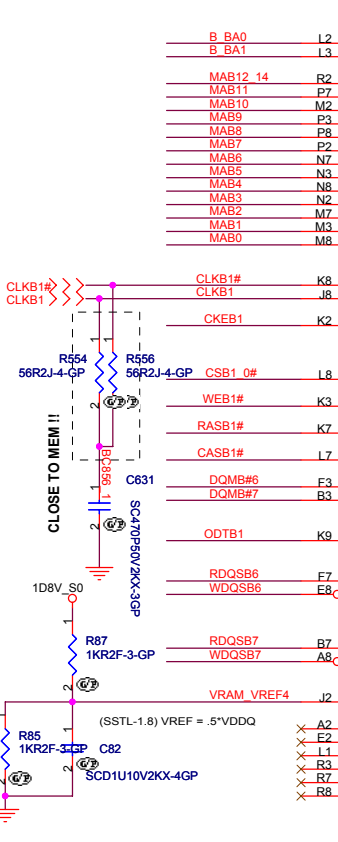
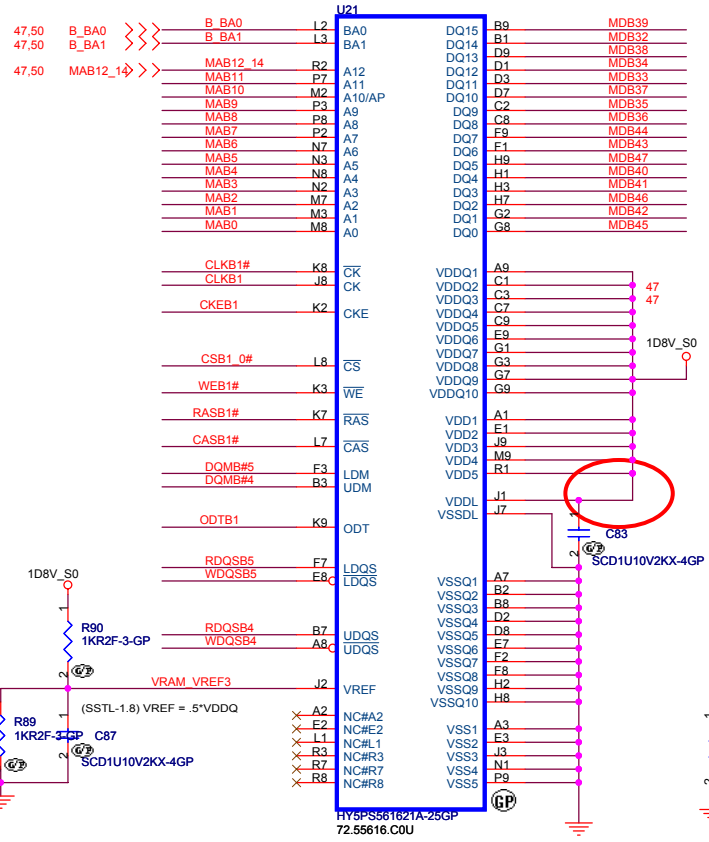
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 72.18256.B0U IC VRAM HYB18T256161AFL25 BGA (16M*16, 350Mhz) Infineon-128M
 72.18512.A0U IC VRAM HYB18T512161BF-25 BGA (32M*16, 400Mhz) Infineon-256M

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File: **VRAM 1/2**

Size: A3 Document Number: **AG1** Rev: SC

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- 47.50 RASB1# >>> RASB1#
- 47.50 CASB1# >>> CASB1#
- 47.50 WEB1# >>> WEB1#
- 47.50 CSB1_0# >>> CSB1_0#
- 47.50 CKEB1 >>> CKEB1
- 47.50 ODTB1 >>> ODTB1
- 47.50 RDQS#(7..0) >>> RDQS#(7..0)
- 47.50 DQMB#(7..0) >>> DQMB#(7..0)
- 47.50 MDB(63..0) >>> MDB(63..0)
- 47.50 MAB(11..0) >>> MAB(11..0)
- 47.50 WDQS#(7..0) >>> WDQS#(7..0)

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緯創資通

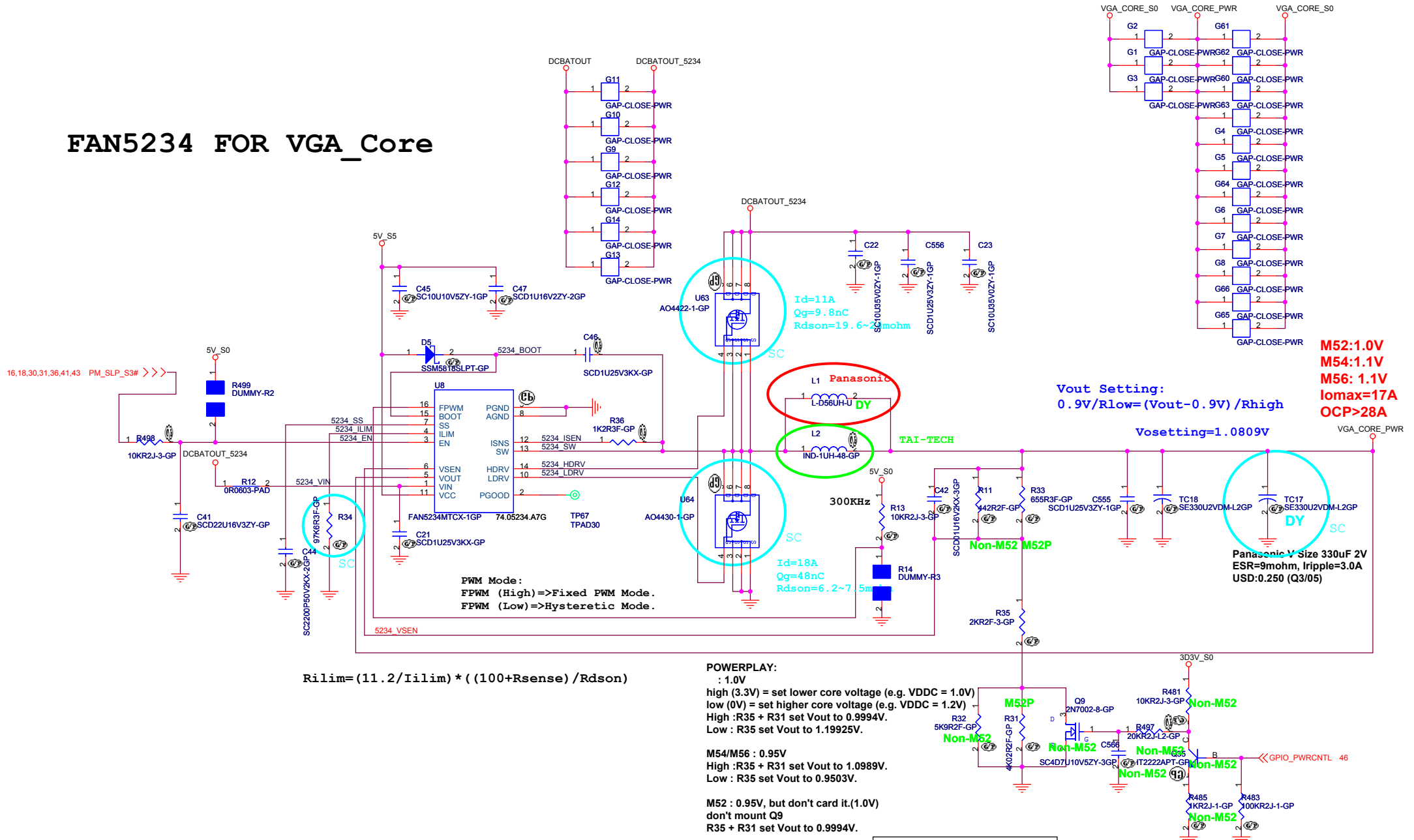
Variant Name: **VRAM 2/2**

Title: **VRAM 2/2**

Size: A3, Document Number: **AG1**, Rev: -1

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FAN5234 FOR VGA_Core



16,18,30,31,36,41,43 PM_SLP_S3# >>>

Id=11A
Qg=9.8nC
Rdson=19.6~21mohm

Id=18A
Qg=48nC
Rdson=6.2~7.5mohm

Vout Setting:
0.9V/Rlow=(Vout-0.9V)/Rhigh

Vosetting=1.0809V

M52:1.0V
M54:1.1V
M56:1.1V
Iomax=17A
OCP>28A

$$R_{lim} = (11.2 / I_{lim}) * ((100 + R_{sense}) / R_{dson})$$

POWERPLAY:

: 1.0V
high (3.3V) = set lower core voltage (e.g. VDDC = 1.0V)
low (0V) = set higher core voltage (e.g. VDDC = 1.2V)
High : R35 + R31 set Vout to 0.9994V.
Low : R35 set Vout to 1.19925V.

M54/M56 : 0.95V
High : R35 + R31 set Vout to 1.0899V.
Low : R35 set Vout to 0.9503V.

M52 : 0.95V, but don't card it.(1.0V)
don't mount Q9
R35 + R31 set Vout to 0.9994V.

ATI M5x VGA Core			
VGA	Ver.	Normal	PowerPlay
M52	A12	1.0	0.95/1.0
M54	A12	1.1	0.95/0.95
M56	B24	1.1	0.95/0.95

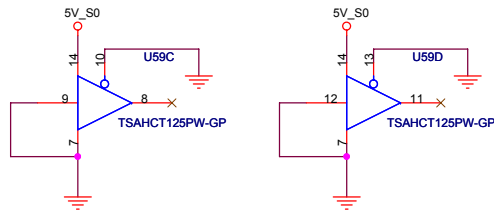
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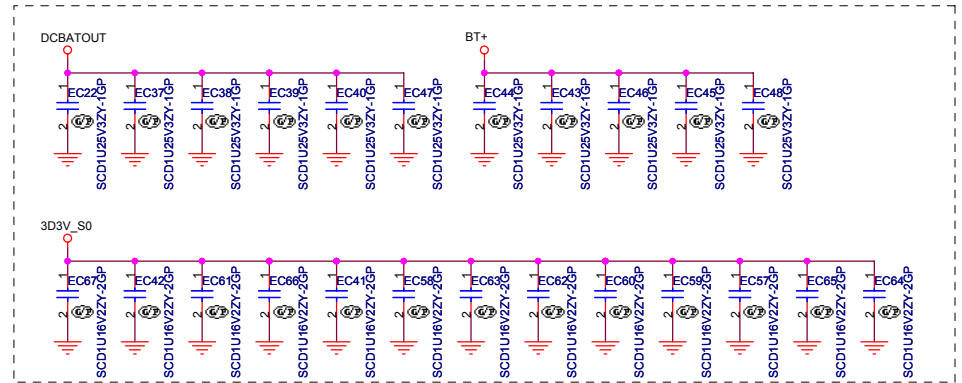
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Size A3 Document Number **AG1** Rev **-1**

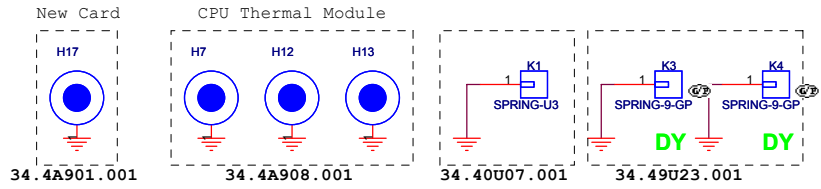
Date: Tuesday, January 10, 2006 Sheet 52 of 53



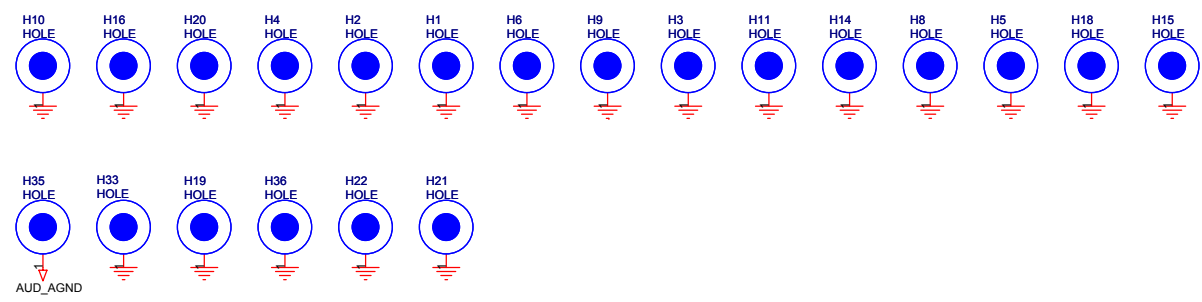
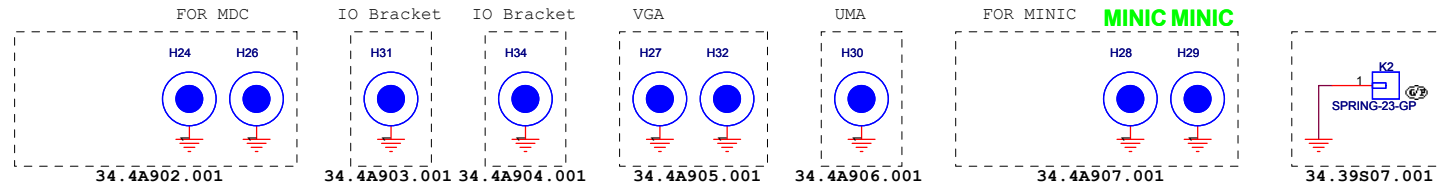
EMI CAP



TOP SIDE:



BOTTOM SIDE:



<Variant Name>

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